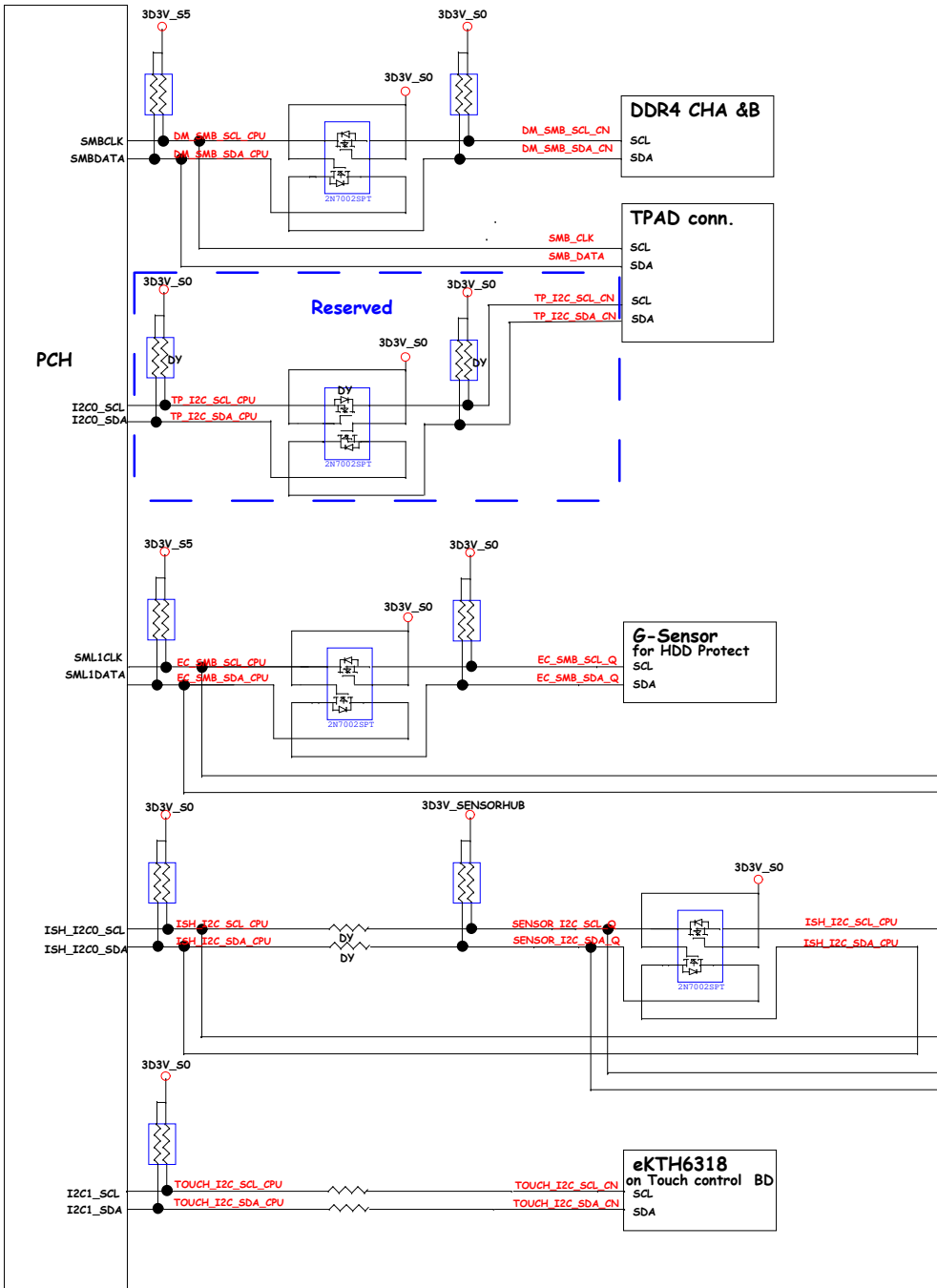
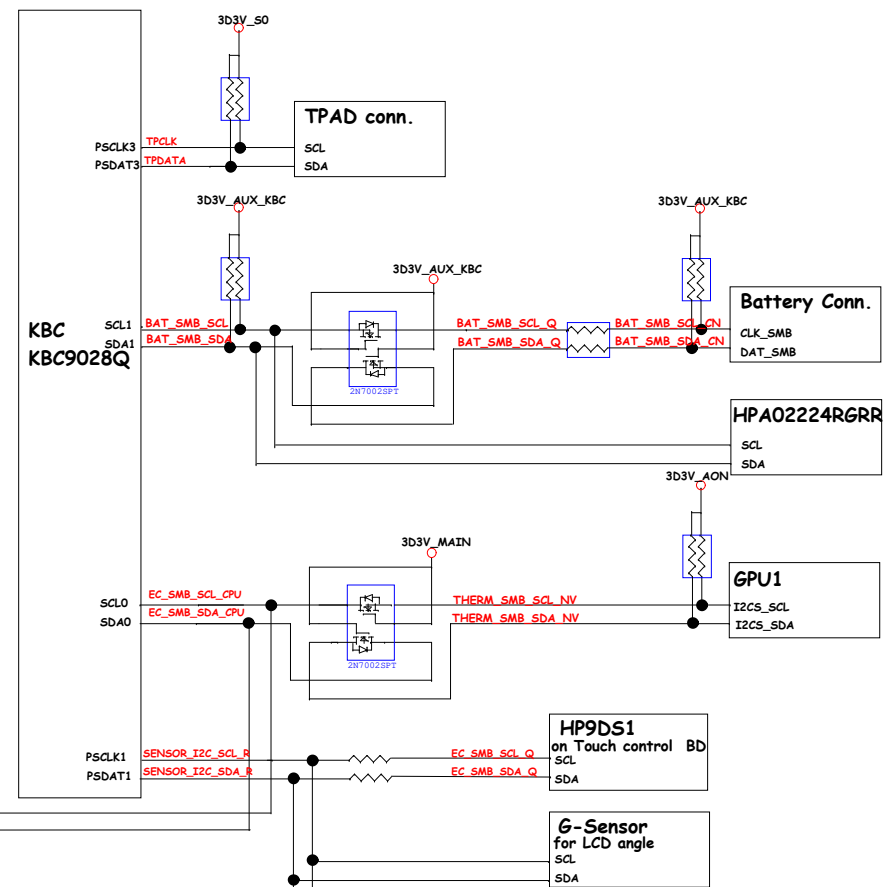


PCH SMBus/ I2C Block Diagram

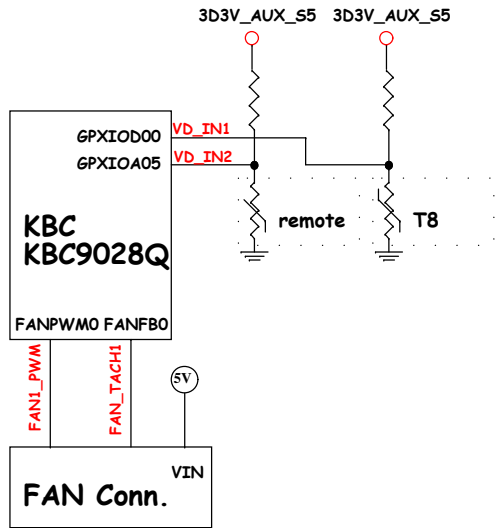


KBC SMBus/ I2C Block Diagram

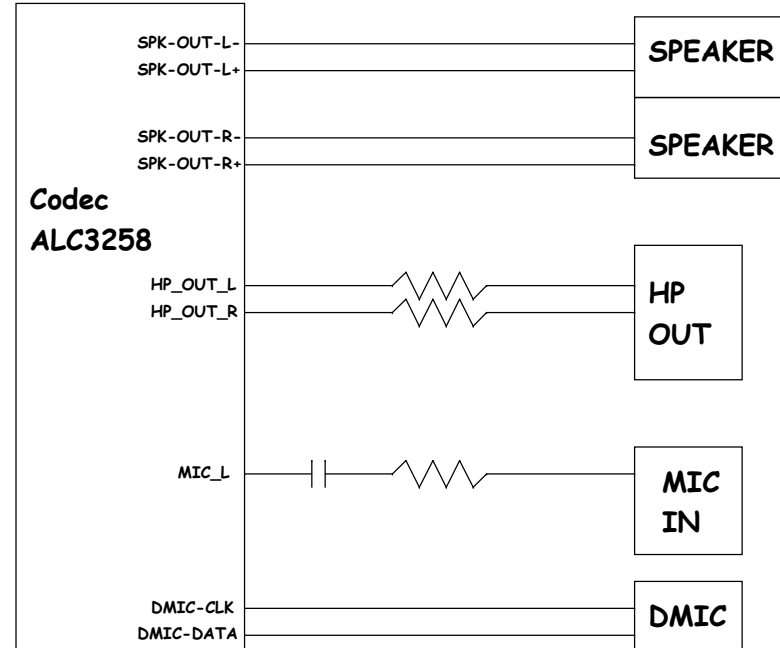


Wistron Confidential document. Anyone can not duplicate, modify, forward or any other purpose application without get Wistron permission.

Thermal Block Diagram



Audio Block Diagram



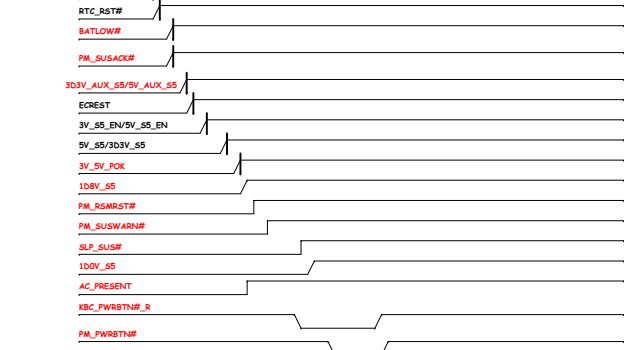
Wistron Confidential document, Anyone can not Duplicate, Modify, Forward or any other purpose application without get Wistron permission

UMA

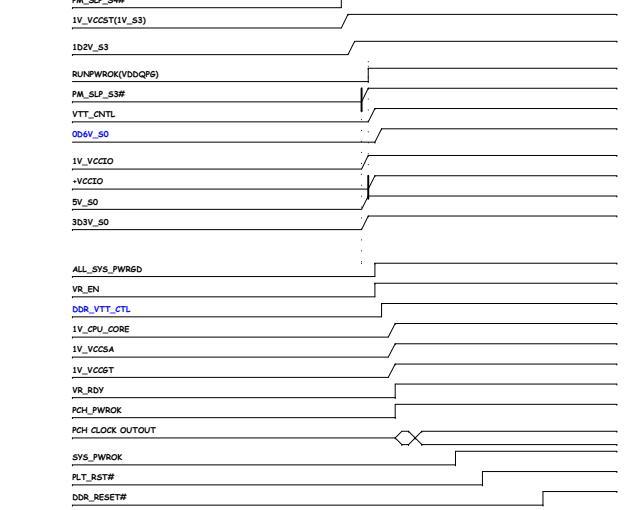
 Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title THERMAL/AUDIO BLOCK DIAGRAM	
Size A3	Document Number FAROE 14" Pavilion
Date: Monday, August 06, 2018	Sheet 105 of 106
Rev SA	

Intel-Power Up Sequence

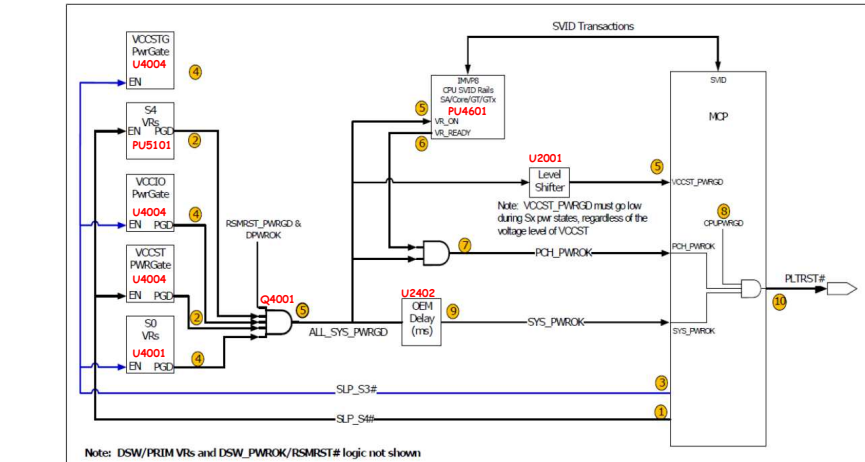
(AC mode)



(DC mode)

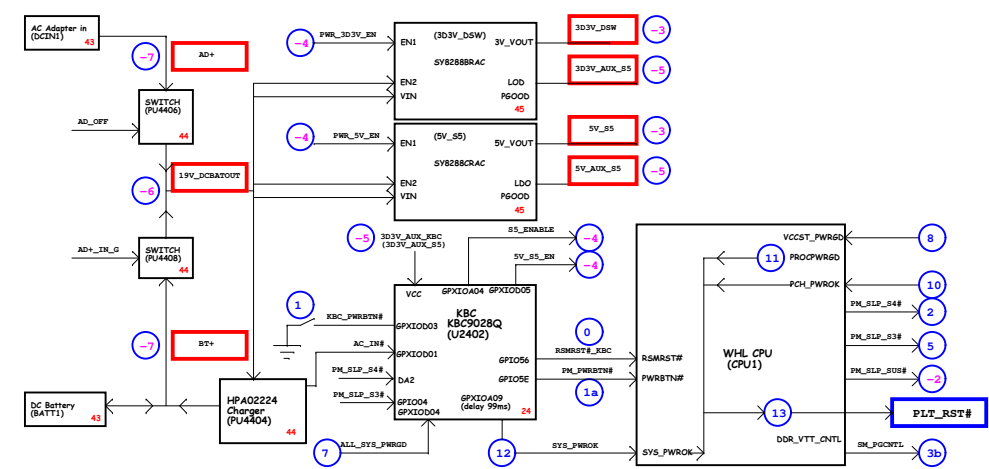


#575412 Rev0.8 P.557
Figure 12-17.WHL U (Volume) PWROK Generation Flow Diagram

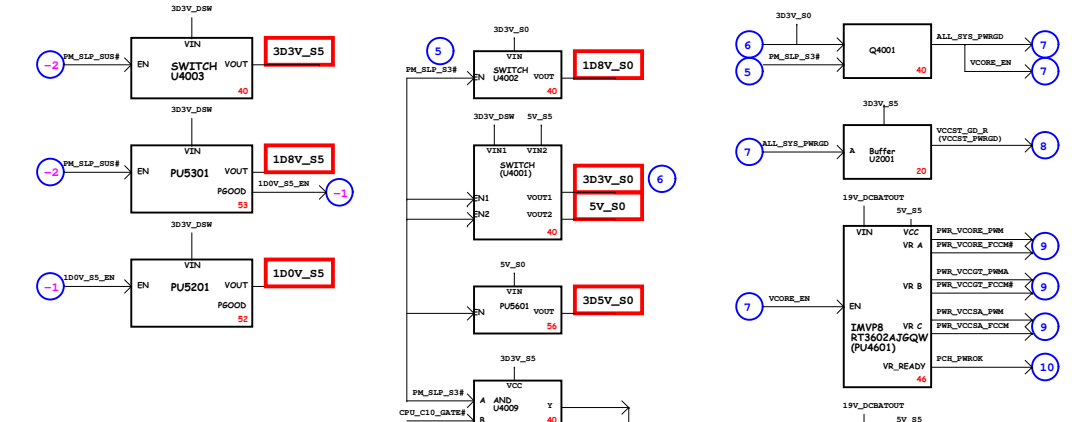


Note: DSW/PRIM VRS and DSW_PWR0K/RSMRST# logic not shown

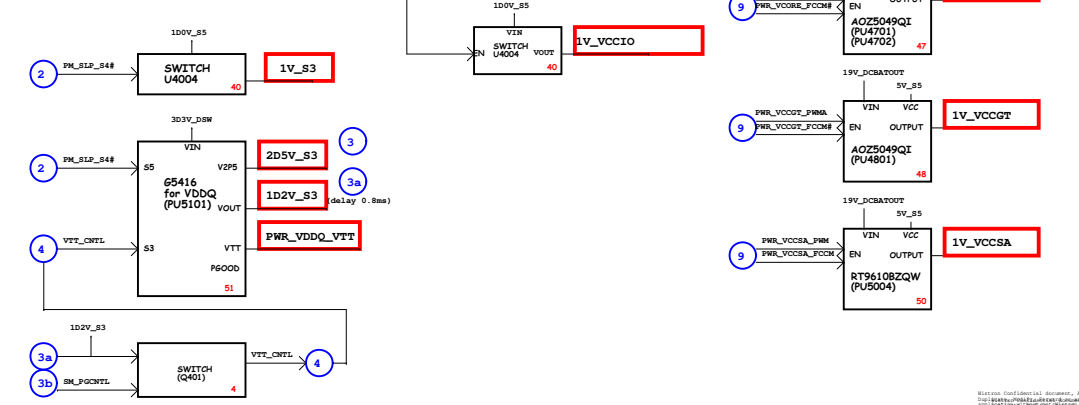
WHL U POWER UP SEQUENCE DIAGRAM



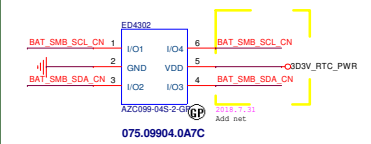
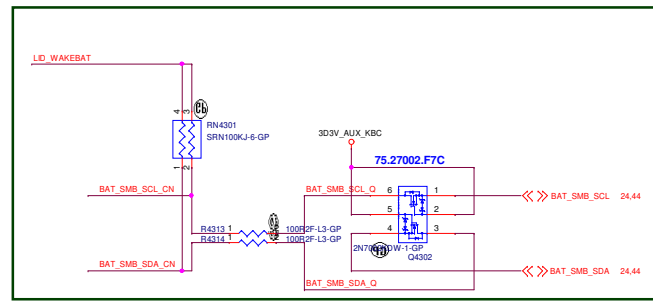
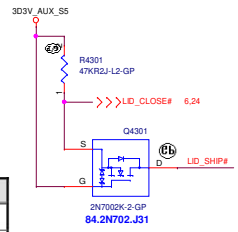
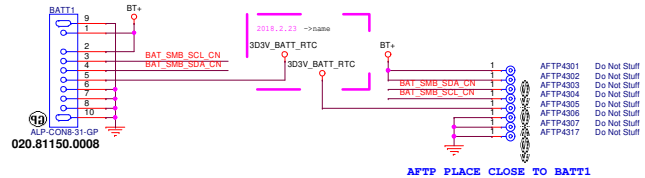
SLP_SUS# ON POWER	SLP_S3# ON POWER	ALL_SYS_PWRGD ON POWER
-------------------	------------------	------------------------



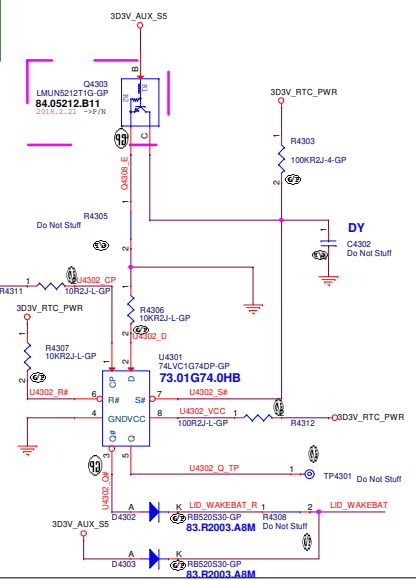
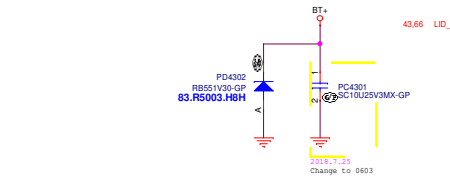
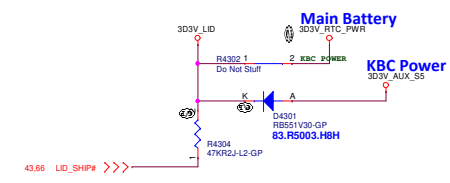
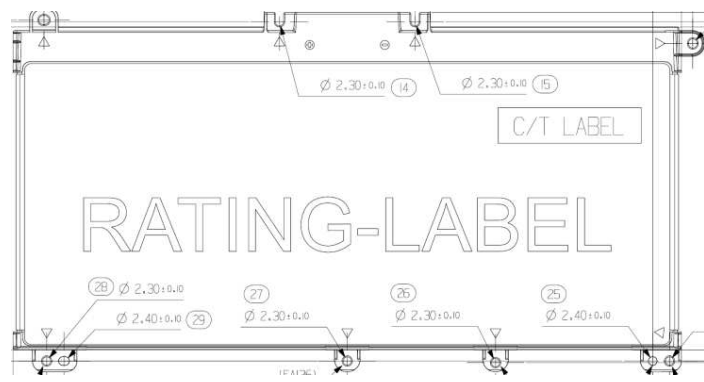
SLP_S4# ON POWER



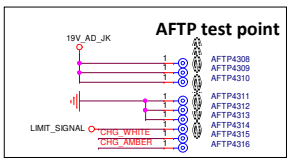
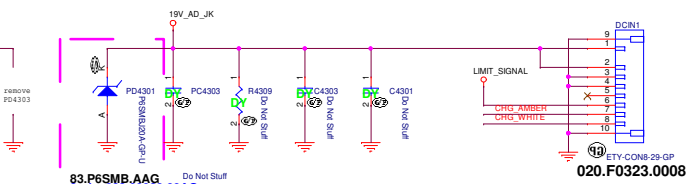
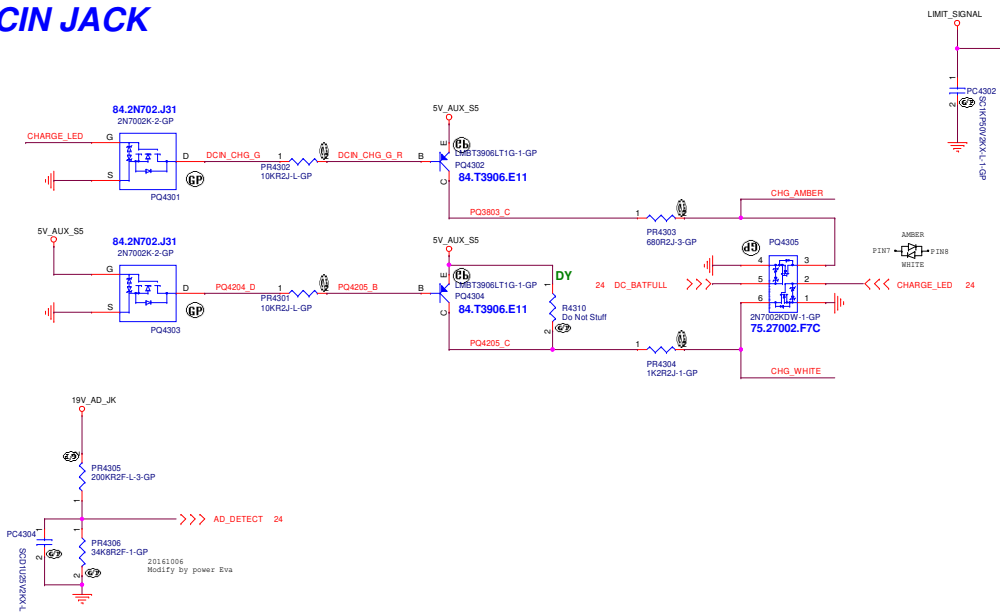
Battery Connector



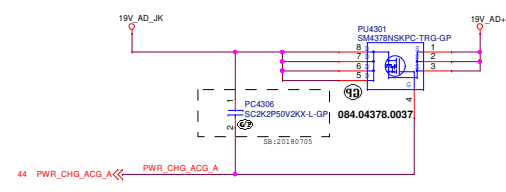
Pin No.	Symbol	Description
1~2	BATT+	Batt+, Battery Positive Terminal
3	SMC	SMBus clock interface I/O pin
4	SMD	SMBus data interface I/O pin
5	RTC	LDO - 3.3V
6	B/I	Connected to GND
7~8	GND	Batt-, Battery Negative Terminal

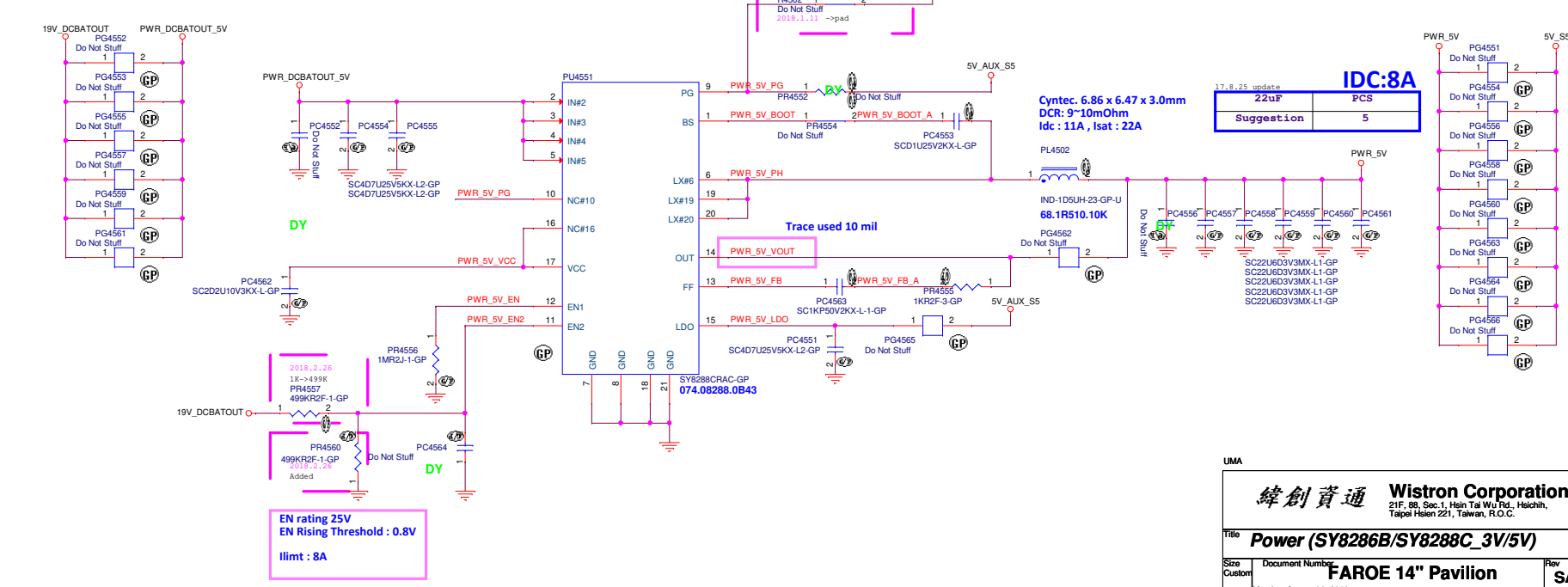
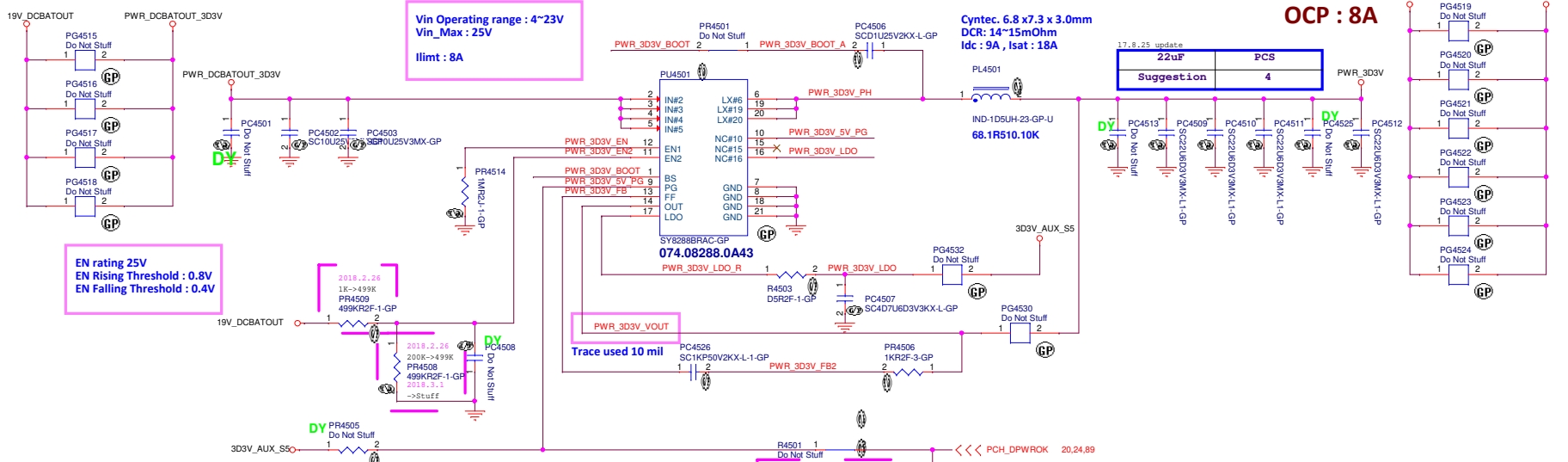
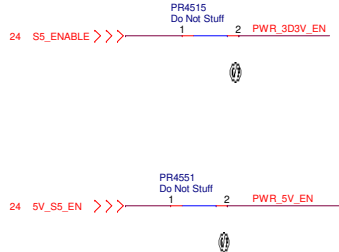


DCIN JACK



AC Present = White
 Standby = White pulsing
 Charging = Amber
 *LED's are off if no AC jack plugged in





UMA

緯創資通 Wistron Corporation
 21F, 9th, Sec.1, Hsien Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

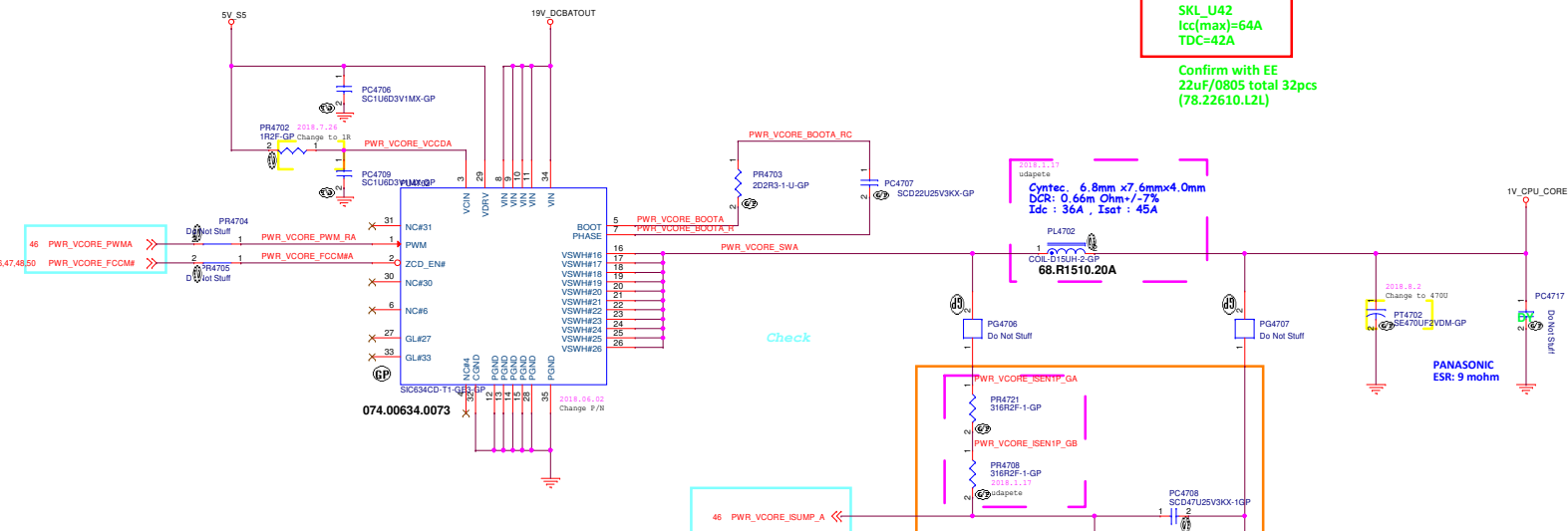
Title: **Power (SY8286B/SY8288C_3V/5V)**

Size: Document Number: **FAROE 14" Pavilion** Rev: **SA**

Date: **Monday, August 06, 2018** Sheet: **45** of **106**

Main Func = CPU_CORE

2018.06.04
Delete PG4701~PG4705



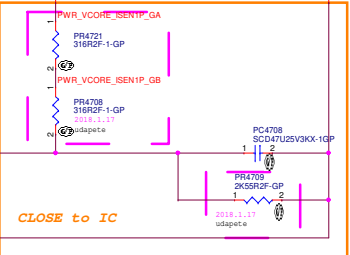
SKL_U42
Icc(max)=64A
TDC=42A

Confirm with EE
22uF/0805 total 32pcs
(78.22610.L2L)

Cytech 6.8mm x7.6mmx4.0mm
DCR: 0.66m Ohm/-7%
Idc : 36A , Isat : 45A

46.47,48,50
PWR_VCORE_PWM_A
PWR_VCORE_FCCMA

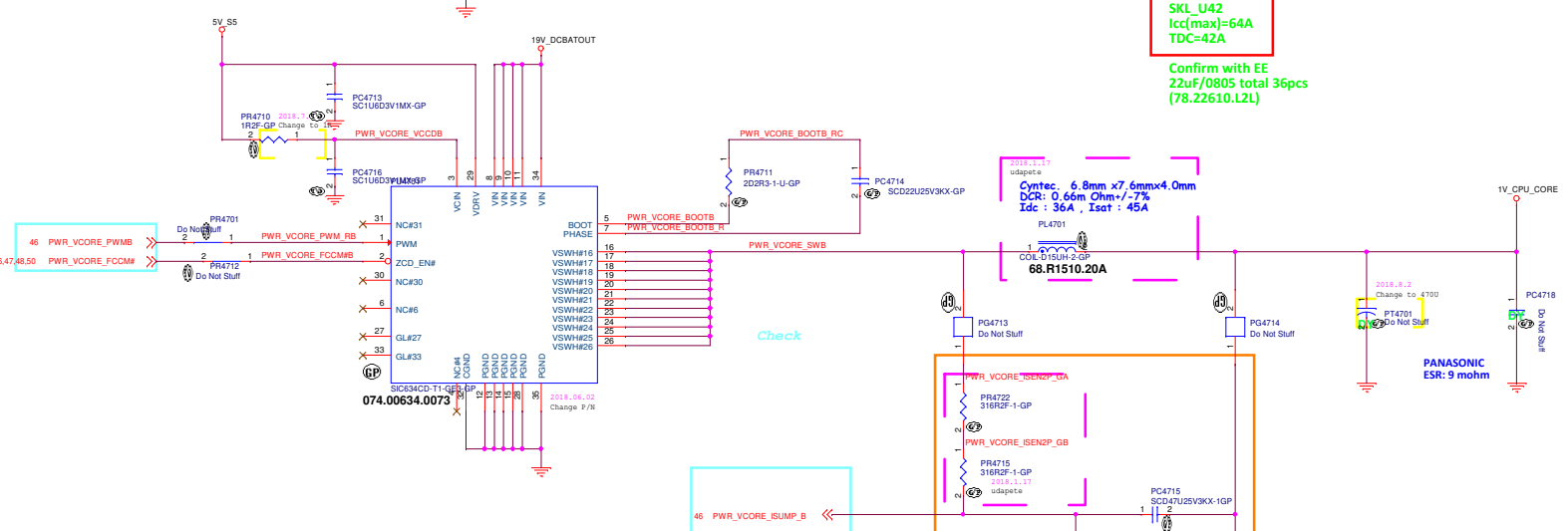
Check



2018.6.2
Change to 4700
PT4702
22uF/0805 VDM-GP

PANASONIC
ESR: 9 mohm

2018.06.04
Delete PG4708~PG4712



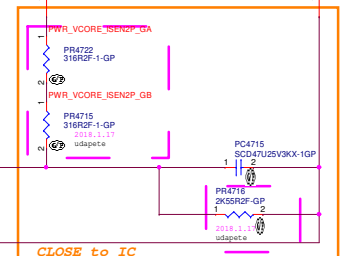
SKL_U42
Icc(max)=64A
TDC=42A

Confirm with EE
22uF/0805 total 36pcs
(78.22610.L2L)

Cytech 6.8mm x7.6mmx4.0mm
DCR: 0.66m Ohm/-7%
Idc : 36A , Isat : 45A

46.47,48,50
PWR_VCORE_PWM_B
PWR_VCORE_FCCMB

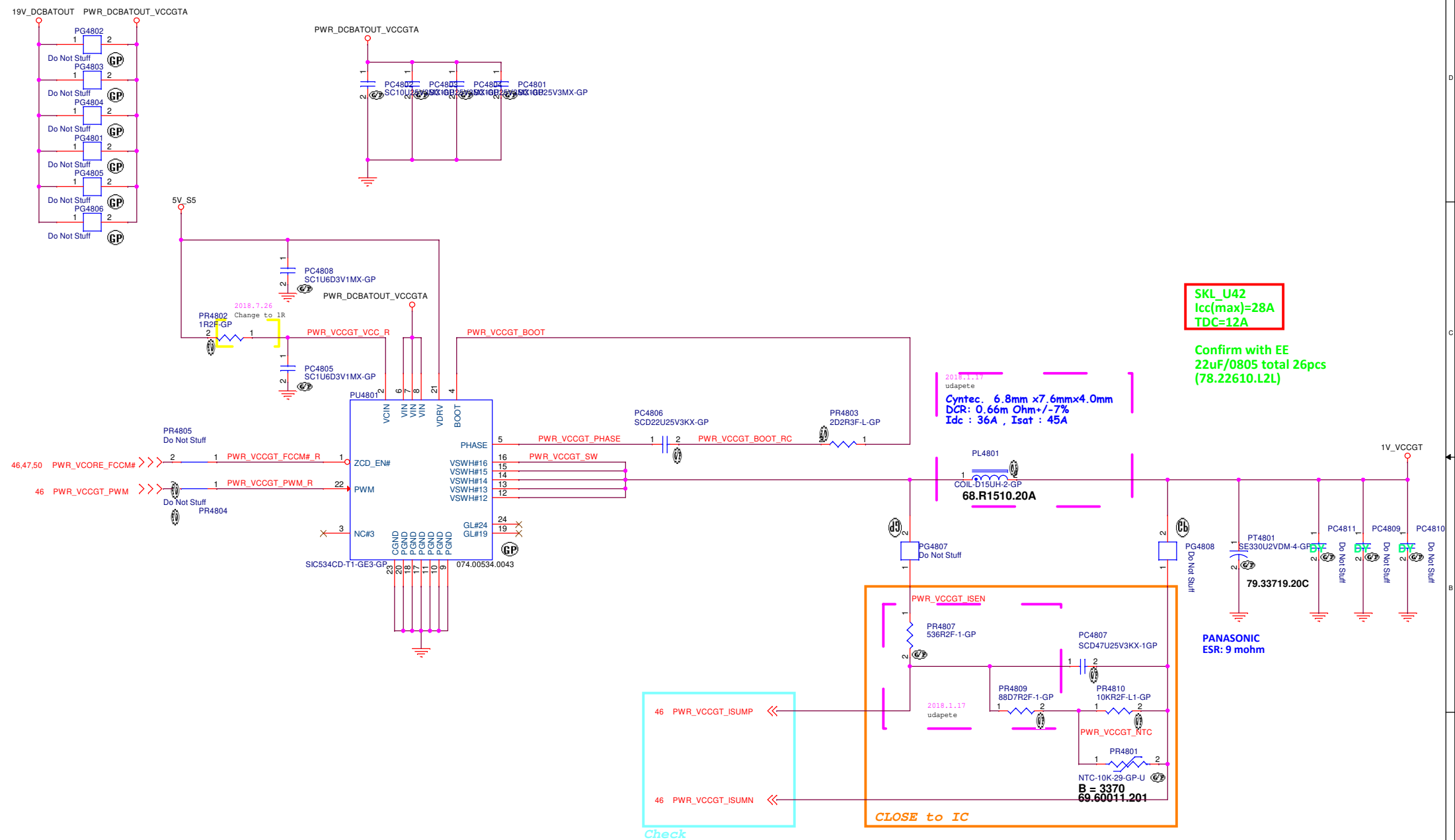
Check



2018.6.2
Change to 4700
PT4710
22uF/0805 VDM-GP

PANASONIC
ESR: 9 mohm

Main Func = CPU_CORE



SKL_U42
Icc(max)=28A
TDC=12A

Confirm with EE
22uF/0805 total 26pcs
(78.22610.L2L)

2015.11.17
udapete
Cyntec 6.8mm x7.6mmx4.0mm
DCR: 0.66m Ohm+/-7%
Idc : 36A , Isat : 45A

PANASONIC
ESR: 9 mohm

46 PWR_VCCGT_ISUMP <<
46 PWR_VCCGT_ISUMN <<
Check

PWR_VCCGT_ISEN
PR4807 536R2F-1-GP
PC4807 SCD47U25V3KX-1GP
PR4809 88D7R2F-1-GP
PR4810 10KR2F-L1-GP
PWR_VCCGT_NTC
PR4801
NTC-10K-29-GP-U
B = 3370
69.60011.201
CLOSE to IC

UMA

緯創資通 Wistron Corporation
21F, 88, Sec. 1, Hsin Tai Wu Rd., Hstchih, Taipei Hsien 221, Taiwan, R.O.C.

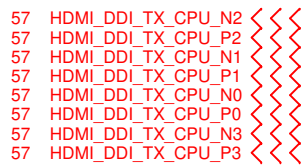
Title **Power (ISL95859_CPUCORE(3/3))**

Size A3	Document Number	Rev
Date: Monday, August 06, 2018	FAROE 14" Pavilion	SA

Sheet 48 of 106

Main Func = CPU

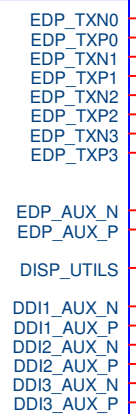
HDMI



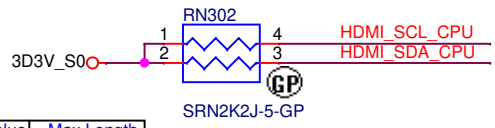
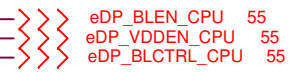
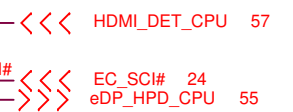
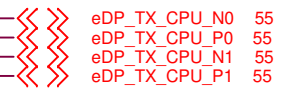
CPU1A



1 OF 20



eDP



2018.1.11 updated

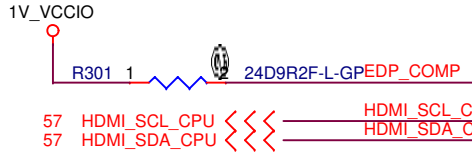
#575412 eDP RCOMP Guideline

Signal	Trace Width	Isolation Spacing	Resistor Value	Max Length
eDP_RCOMP	5 mils	25 mils	24.9 Ω ±1%	600 mils

2018.1.11 updated

PCH strap pin:

Display Port B Detected	
GPP_E19 / DDPB_CTRLDATA / CNV_BT_IF_SELECT	Low = Not detected (Default) High = Detected* This signal has a weak internal PD



PCH strap pin:

Display Port C Detected	
GPP_E21 / DDPC_CTRLDATA	Low = Not detected (Default)* High = Detected This signal has a weak internal PD

PCH strap pin:

Display Port D Detected	
GPP_E23 / DDPD_CTRLDATA	Low = Not detected (Default)* High = Detected This signal has a weak internal PD

PCH strap pin:

(EDS Reserved)	
GPP_H17	Low = TBD High = TBD This signal has a weak internal PD*

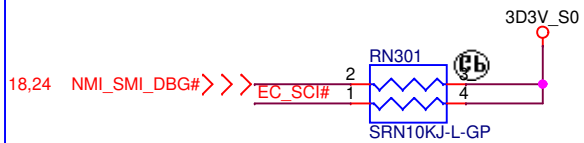
This strap should sample LOW.

2018.1.11 updated

#575412 DDI Disabling and Termination Guidelines

Port	Strap	Enable Port	Disable Port
Port 1	DDPB_CTRLDATA	Pull up to 3.3 V with 2.2-k ohm ±5% resistor	NC
Port 2	DDPC_CTRLDATA	Pull up to 3.3 V with 2.2-k ohm ±5% resistor	NC
Port 3	DDPD_CTRLDATA	Pull up to 3.3 V with 2.2-k ohm ±5% resistor	NC
Port 4	DDPF_CTRLDATA	Pull up to 3.3 V with 2.2-k ohm ±5% resistor	NC

WHISKEY-LAKE-GP
ZZ.00CPU.271



UMA

緯創資通 Wistron Corporation
 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

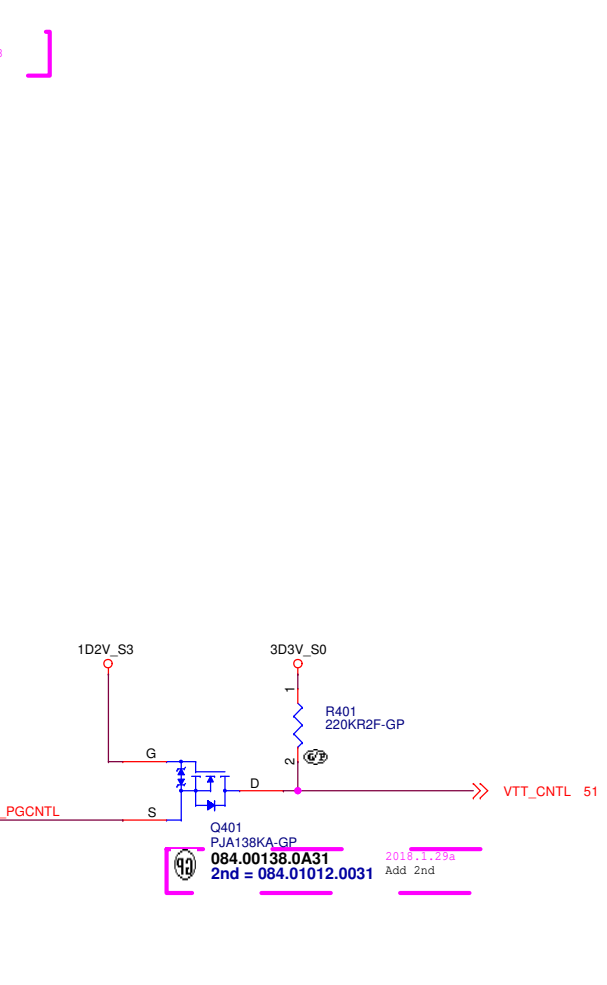
Title **CPU (DDI/EDP)**

Size A4 Document Number **FAROE 14" Pavilion** Rev **SA**

Date: Monday, August 06, 2018 Sheet 3 of 106

DDR4 Channel A ball type:Non Interleaved Type

CPU1B		2 OF 20	
12 M_A DQ0	M A DQ0 A26	DDR0_DQ0/DDR0_DQ0	DDR0_CKN0/DDR0_CKN0
12 M_A DQ1	M A DQ1 D26	DDR0_DQ1/DDR0_DQ1	DDR0_CK0P/DDR0_CK0P
12 M_A DQ2	M A DQ2 D28	DDR0_DQ2/DDR0_DQ2	DDR0_CKN1/DDR0_CKN1
12 M_A DQ3	M A DQ3 C28	DDR0_DQ3/DDR0_DQ3	DDR0_CK1P/DDR0_CK1P
12 M_A DQ4	M A DQ4 B26	DDR0_DQ4/DDR0_DQ4	
12 M_A DQ5	M A DQ5 C26	DDR0_DQ5/DDR0_DQ5	DDR0_CKE0/DDR0_CKE0
12 M_A DQ6	M A DQ6 B28	DDR0_DQ6/DDR0_DQ6	DDR0_CKE1/DDR0_CKE1
12 M_A DQ7	M A DQ7 A28	DDR0_DQ7/DDR0_DQ7	DDR0_CKE2/NC
12 M_A DQ8	M A DQ8 B30	DDR0_DQ8/DDR0_DQ8	DDR0_CKE3/NC
12 M_A DQ9	M A DQ9 D30	DDR0_DQ9/DDR0_DQ9	
12 M_A DQ10	M A DQ10 B33	DDR0_DQ10/DDR0_DQ10	DDR0_CS#0/DDR0_CS#0
12 M_A DQ11	M A DQ11 D32	DDR0_DQ11/DDR0_DQ11	DDR0_CS#1/DDR0_CS#1
12 M_A DQ12	M A DQ12 A30	DDR0_DQ12/DDR0_DQ12	DDR0_ODT0/DDR0_ODT0
12 M_A DQ13	M A DQ13 C30	DDR0_DQ13/DDR0_DQ13	NC/DDR0_ODT1
12 M_A DQ14	M A DQ14 B32	DDR0_DQ14/DDR0_DQ14	
12 M_A DQ15	M A DQ15 C32	DDR0_DQ15/DDR0_DQ15	DDR0_CAB9/DDR0_MA0
12 M_A DQ32	M A DQ32 H37	DDR0_DQ16/DDR0_DQ32	DDR0_CAB8/DDR0_MA1
12 M_A DQ33	M A DQ33 H34	DDR0_DQ17/DDR0_DQ33	DDR0_CAB5/DDR0_MA2
12 M_A DQ34	M A DQ34 K34	NC/DDR0_MA3	NC/DDR0_MA4
12 M_A DQ35	M A DQ35 K35	DDR0_DQ18/DDR0_DQ34	DDR0_CAA0/DDR0_MA5
12 M_A DQ36	M A DQ36 H36	DDR0_DQ19/DDR0_DQ35	DDR0_CAA2/DDR0_MA6
12 M_A DQ37	M A DQ37 H35	DDR0_DQ20/DDR0_DQ36	DDR0_CAA4/DDR0_MA7
12 M_A DQ38	M A DQ38 K36	DDR0_DQ21/DDR0_DQ37	DDR0_CAA3/DDR0_MA8
12 M_A DQ39	M A DQ39 K37	DDR0_DQ22/DDR0_DQ38	DDR0_CAA1/DDR0_MA9
12 M_A DQ40	M A DQ40 N36	DDR0_DQ23/DDR0_DQ39	DDR0_CAB7/DDR0_MA10
12 M_A DQ41	M A DQ41 N34	DDR0_DQ24/DDR0_DQ40	DDR0_CAA7/DDR0_MA11
12 M_A DQ42	M A DQ42 R37	DDR0_DQ25/DDR0_DQ41	DDR0_CAA6/DDR0_MA12
12 M_A DQ43	M A DQ43 R34	DDR0_DQ26/DDR0_DQ42	DDR0_CAB0/DDR0_MA13
12 M_A DQ44	M A DQ44 N37	DDR0_DQ27/DDR0_DQ43	DDR0_DQ28/DDR0_DQ44
12 M_A DQ45	M A DQ45 N35	DDR0_DQ29/DDR0_DQ45	DDR0_DQ30/DDR0_DQ46
12 M_A DQ46	M A DQ46 R36	DDR0_DQ31/DDR0_DQ47	DDR0_CAB1/DDR0_MA15
12 M_A DQ47	M A DQ47 R35	DDR0_DQ32/DDR1_DQ0	DDR0_CAB3/DDR0_MA16
13 M_B DQ0	M B DQ0 AN35	DDR0_DQ33/DDR1_DQ1	DDR0_CAB4/DDR0_BA0
13 M_B DQ1	M B DQ1 AN34	DDR0_DQ34/DDR1_DQ2	DDR0_CAB6/DDR0_BA1
13 M_B DQ2	M B DQ2 AR35	DDR0_DQ35/DDR1_DQ3	DDR0_CAA5/DDR0_BG0
13 M_B DQ3	M B DQ3 AR34	DDR0_DQ36/DDR1_DQ4	
13 M_B DQ4	M B DQ4 AN37	DDR0_DQ37/DDR1_DQ5	DDR0_CAA8/DDR0_ACT#
13 M_B DQ5	M B DQ5 AN36	DDR0_DQ38/DDR1_DQ6	DDR0_CAA9/DDR0_BG1
13 M_B DQ6	M B DQ6 AR36	DDR0_DQ39/DDR1_DQ7	
13 M_B DQ7	M B DQ7 AR37	DDR0_DQ40/DDR1_DQ8	DDR0_DQSN0/DDR0_DQSN0
13 M_B DQ8	M B DQ8 AU35	DDR0_DQ41/DDR1_DQ9	DDR0_DQSP0/DDR0_DQSP0
13 M_B DQ9	M B DQ9 AU34	DDR0_DQ42/DDR1_DQ10	DDR0_DQSN1/DDR0_DQSN1
13 M_B DQ10	M B DQ10 AW35	DDR0_DQ43/DDR1_DQ11	DDR0_DQSP1/DDR0_DQSP1
13 M_B DQ11	M B DQ11 AW34	DDR0_DQ44/DDR1_DQ12	DDR0_DQSN2/DDR0_DQSN4
13 M_B DQ12	M B DQ12 AU37	DDR0_DQ45/DDR1_DQ13	DDR0_DQSP2/DDR0_DQSP4
13 M_B DQ13	M B DQ13 AU36	DDR0_DQ46/DDR1_DQ14	DDR0_DQSN3/DDR0_DQSN5
13 M_B DQ14	M B DQ14 AW36	DDR0_DQ47/DDR1_DQ15	DDR0_DQSP3/DDR0_DQSP5
13 M_B DQ15	M B DQ15 AW37	DDR0_DQ48/DDR1_DQ32	DDR0_DQSN4/DDR1_DQSN0
13 M_B DQ32	M B DQ32 BA35	DDR0_DQ49/DDR1_DQ33	DDR0_DQSP4/DDR1_DQSP0
13 M_B DQ33	M B DQ33 BA34	DDR0_DQ50/DDR1_DQ34	DDR0_DQSN5/DDR1_DQSN1
13 M_B DQ34	M B DQ34 BC35	DDR0_DQ51/DDR1_DQ35	DDR0_DQSP5/DDR1_DQSP1
13 M_B DQ35	M B DQ35 BC34	DDR0_DQ52/DDR1_DQ36	DDR0_DQSN6/DDR1_DQSN4
13 M_B DQ36	M B DQ36 BA37	DDR0_DQ53/DDR1_DQ37	DDR0_DQSP6/DDR1_DQSP4
13 M_B DQ37	M B DQ37 BA36	DDR0_DQ54/DDR1_DQ38	DDR0_DQSN7/DDR1_DQSN5
13 M_B DQ38	M B DQ38 BC36	DDR0_DQ55/DDR1_DQ39	DDR0_DQSP7/DDR1_DQSP5
13 M_B DQ39	M B DQ39 BC37	DDR0_DQ56/DDR1_DQ40	
13 M_B DQ40	M B DQ40 BE35	DDR0_DQ57/DDR1_DQ41	NC/DDR0_ALERT#
13 M_B DQ41	M B DQ41 BE34	DDR0_DQ58/DDR1_DQ42	NC/DDR0_PAR
13 M_B DQ42	M B DQ42 BG35	DDR0_DQ59/DDR1_DQ43	DDR_VREF_CA
13 M_B DQ43	M B DQ43 BG34	DDR0_DQ60/DDR1_DQ44	DDR_VREF_DQ0
13 M_B DQ44	M B DQ44 BE37	DDR0_DQ61/DDR1_DQ45	DDR_VREF_DQ1
13 M_B DQ45	M B DQ45 BE36	DDR0_DQ62/DDR1_DQ46	DDR_VREF_DQ
13 M_B DQ46	M B DQ46 BG36	DDR0_DQ63/DDR1_DQ47	DDR_VTT_GTL
13 M_B DQ47	M B DQ47 BG37		



Notes:

1. DQ Bit Swapping is allowed within the same byte, and Byte Swapping is allowed within the same channel
2. Clock (CLK and CLK#) and Strobe (DQS and DQS#) differential signal swapping within a pair is not allowed. Also differential clock pair to clock pair swapping within a channel is not allowed.

UMA

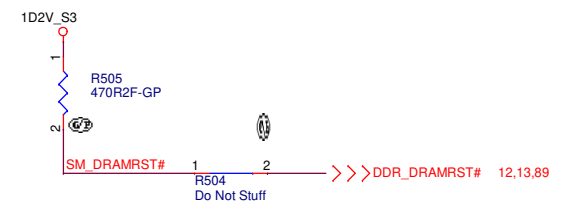
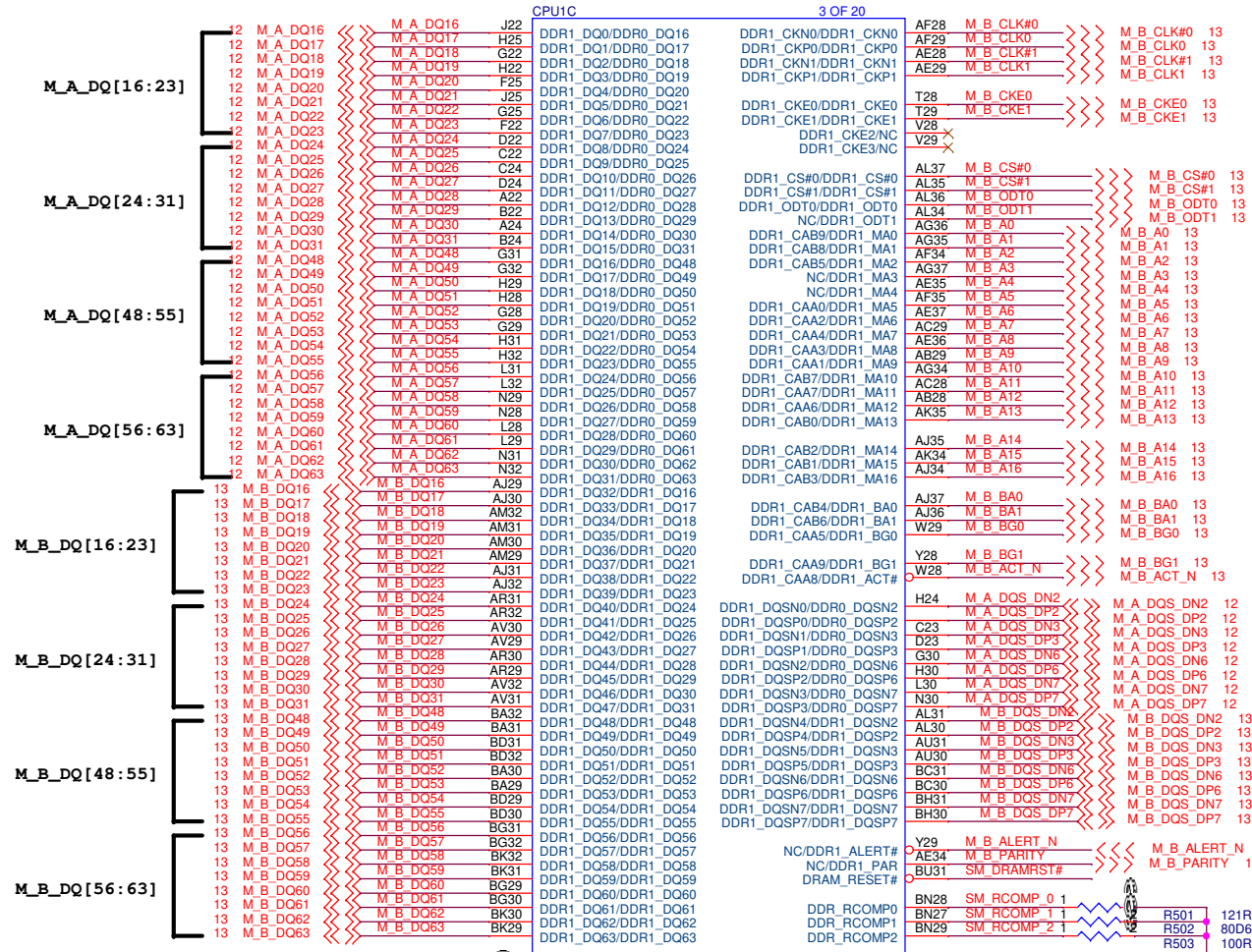
緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **CPU (DDR_CHA)**

Size B Document Number: **FAROE 14" Pavilion** Rev SA

Date: Monday, August 06, 2018 Sheet 4 of 106

DDR4 Channel B ball type:Non Interleaved Type



2018.1.12 updated

#575412_DDR_COMP_Guideline

Signal	Trace Width	Trace Spacing	Resistor Value(Ω ±1%)	Max Length
DDR_RCOMP[2:0]	15 mils	20-25 mils	121/80.6/100	500 mils

Notes:

1. DQ Bit Swapping is allowed within the same byte, and Byte Swapping is allowed within the same channel
2. Clock (CLK and CLK#) and Strobe (DQS and DQS#) differential signal swapping within a pair is not allowed. Also differential clock pair to clock pair swapping within a channel is not allowed.

UMA

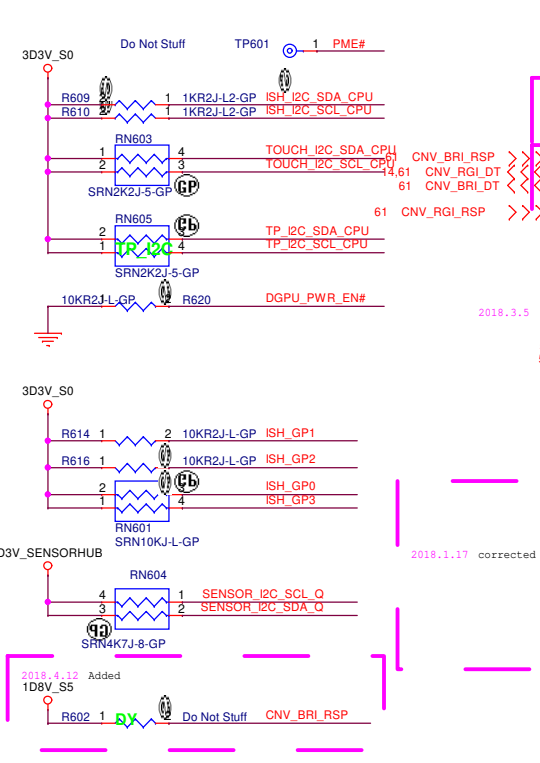
緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsieh, Taipei Hsien 221, Taiwan, R.O.C.

Title: **CPU (DDR_CHB)**

Size B: Document Number: **FAROE 14" Pavilion** Rev: **SA**

Date: Monday, August 06, 2018 Sheet 5 of 106

Main Func = PCH



PCH strap pin:
**BOOT BIOS STRAP (BBS)
 LPC/SPI FOR SYSTEM FLASH**

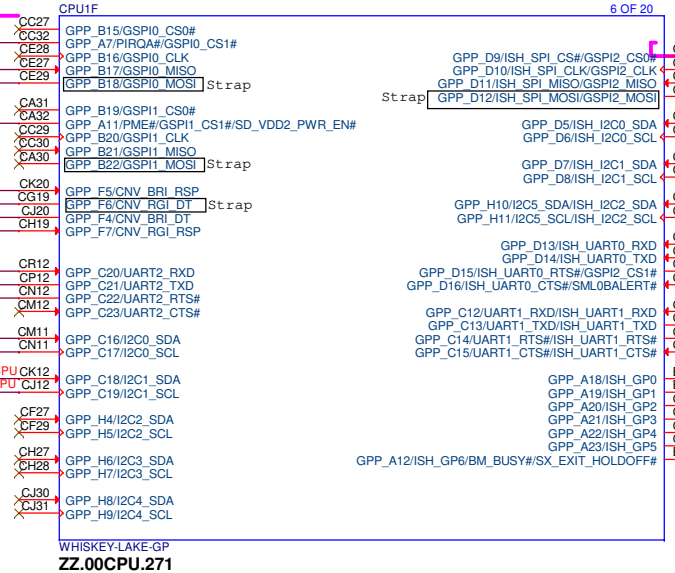
GPP_B22/ GSPi0_MOSI	Low = SPI (Default)* High= LPC WEAK INTERNAL PD
------------------------	---

PCH strap pin:
NO REBOOT

GPP_B18/ GSPi0_MOSI	Low = REBOOT (Default)* High= NO REBOOT WEAK INTERNAL PD
------------------------	--

PCH strap pin:
**M.2 CNVI MODES
 INTEGRATED CNVI ENABLE/DISABLE**

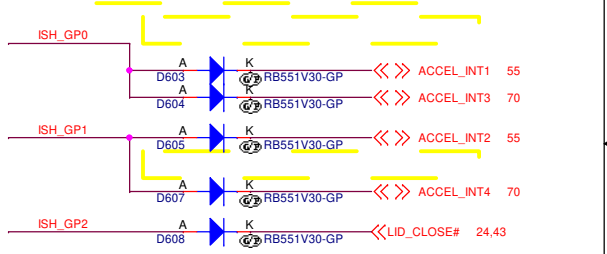
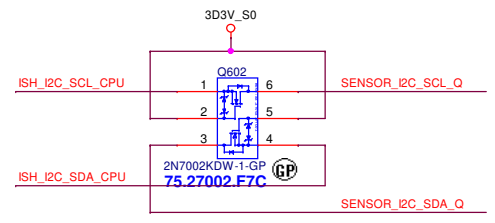
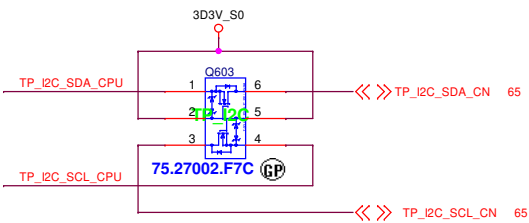
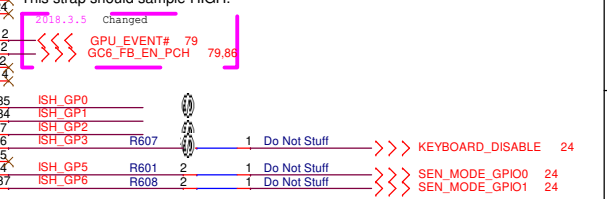
GPP_F6/ CNV_RGI_DT	Low = ENABLE High= DISABLE(Default)* WEAK INTERNAL PU
-----------------------	---



PCH strap pin:
JTAG ODT DISABLE(EDS Reserved)

GPP_D12/ ISH_SPI_MOSI GSPi2_MOSI	Low = JTAG ODT DISABLED High= JTAG ODT ENABLED (Default) *
--	---

This strap should sample HIGH.



Main Func = CPU

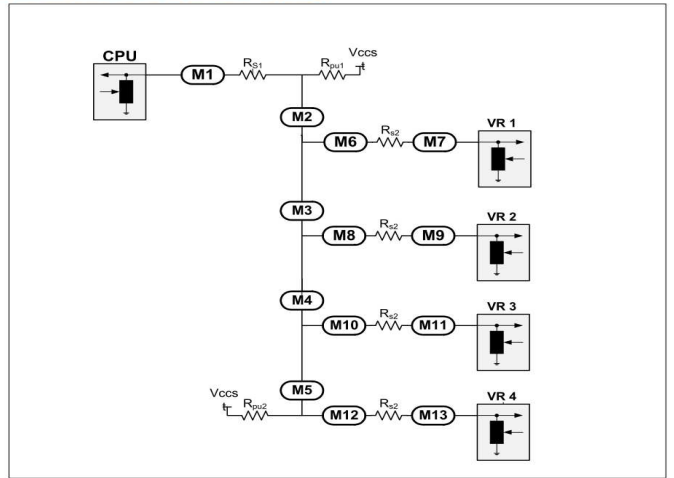
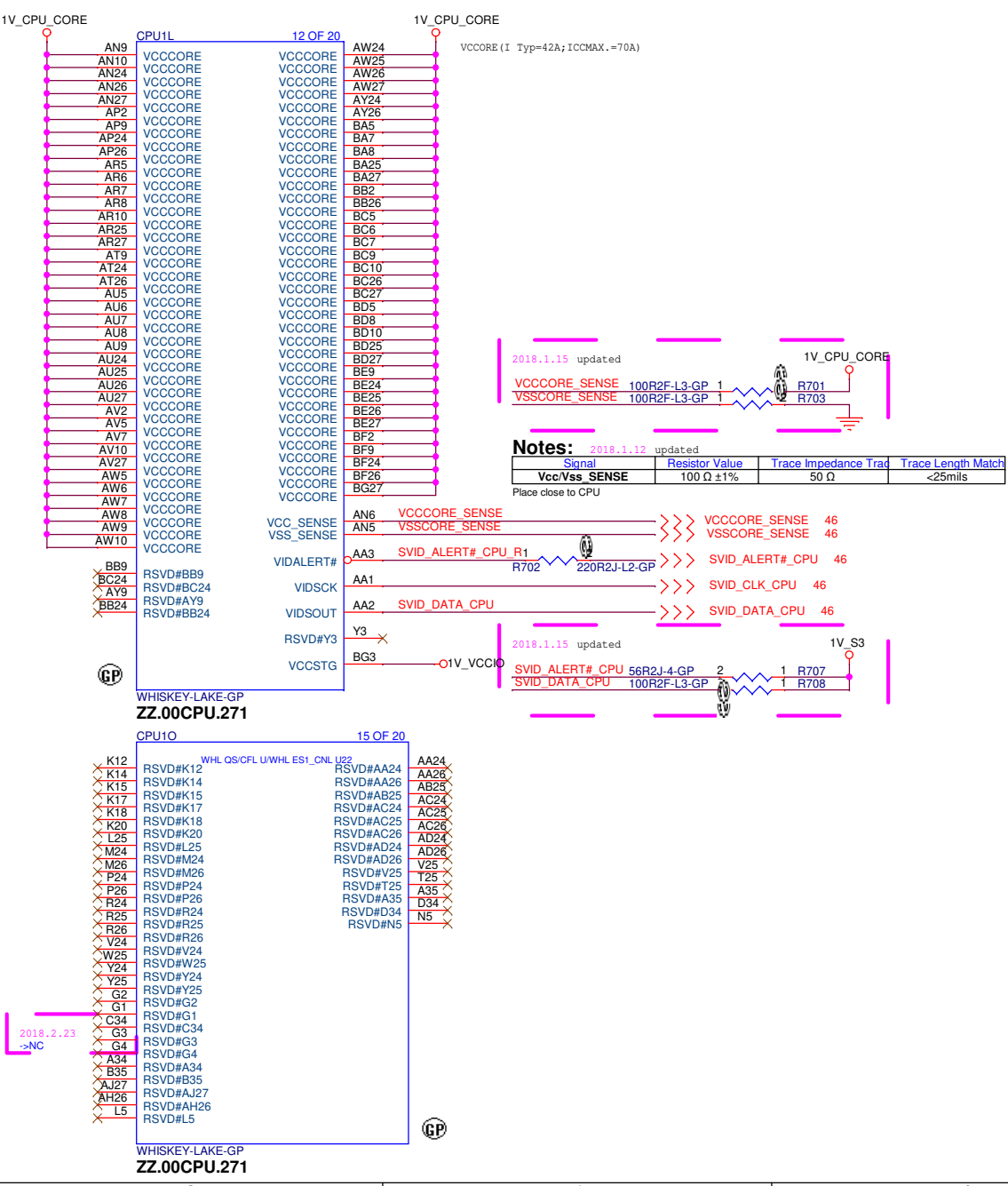


Figure above demonstrates Routing Illustration for SVID Topology, each trace from CPU to VR represents 3 signals: VIDSOUT, VIDSCK, VIDSALERT#.

Table 7-18. SVID Routing Guidelines (Sheet 1 of 2)

Segment	Tline Type	Reference	Via Count	Max Length, mm		Max Length, Mils	
				Segment	Total	Segment	Total
M1	MS/SL/DSL	VSS		76	76	2992.13	2992.13
M2	MS/SL/DSL	VSS		381		15000	
M3	MS/SL/DSL	VSS		102	432	4015.75	17007.9
M4	MS/SL/DSL	VSS		102		4015.75	
M5	MS/SL/DSL	VSS		102		4015.75	
M6	MS/SL/DSL	VSS		3	3	118.11	118.11
M7	MS/SL/DSL	VSS		3	3	118.11	118.11
M8	MS/SL/DSL	VSS		3	3	118.11	118.11
M9	MS/SL/DSL	VSS		3	3	118.11	118.11
M10	MS/SL/DSL	VSS		3	3	118.11	118.11
M11	MS/SL/DSL	VSS		3	3	118.11	118.11
M12	MS/SL/DSL	VSS		3	3	118.11	118.11
M13	MS/SL/DSL	VSS		3	3	118.11	118.11

Topology Guidelines

SVID Signals	VIDSOUT, VIDSCK, VIDSALERT#
VIDSOUT platform resistors	Rpu1=100Ω, Rpu2=100Ω, Rs1=0Ω, Rs2=10Ω
VIDSCK platform resistors	Rpu1=Empty, Rpu2=45Ω, Rs1=0Ω, Rs2=49.9Ω
VIDSALERT# platform resistors	Rpu1=56Ω, Rpu2=Empty, Rs1=220Ω, Rs2=0Ω
Platform resistors tolerances	± 5%
Route ordering	When routing at minimum spacing route Alert between Data and Clock
Length Matching Rules	
Length Matching between VIDSOUT and VIDSCK	± 100mils

JIMA

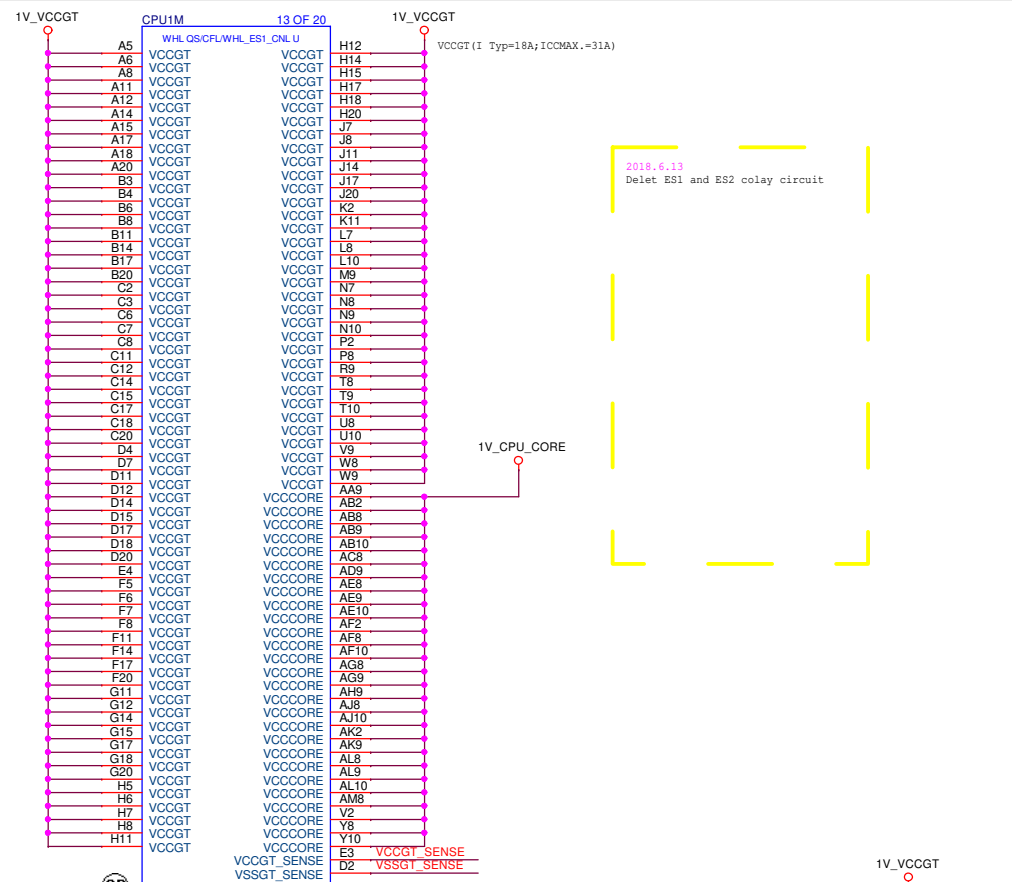
緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **CPU (POWER1)**

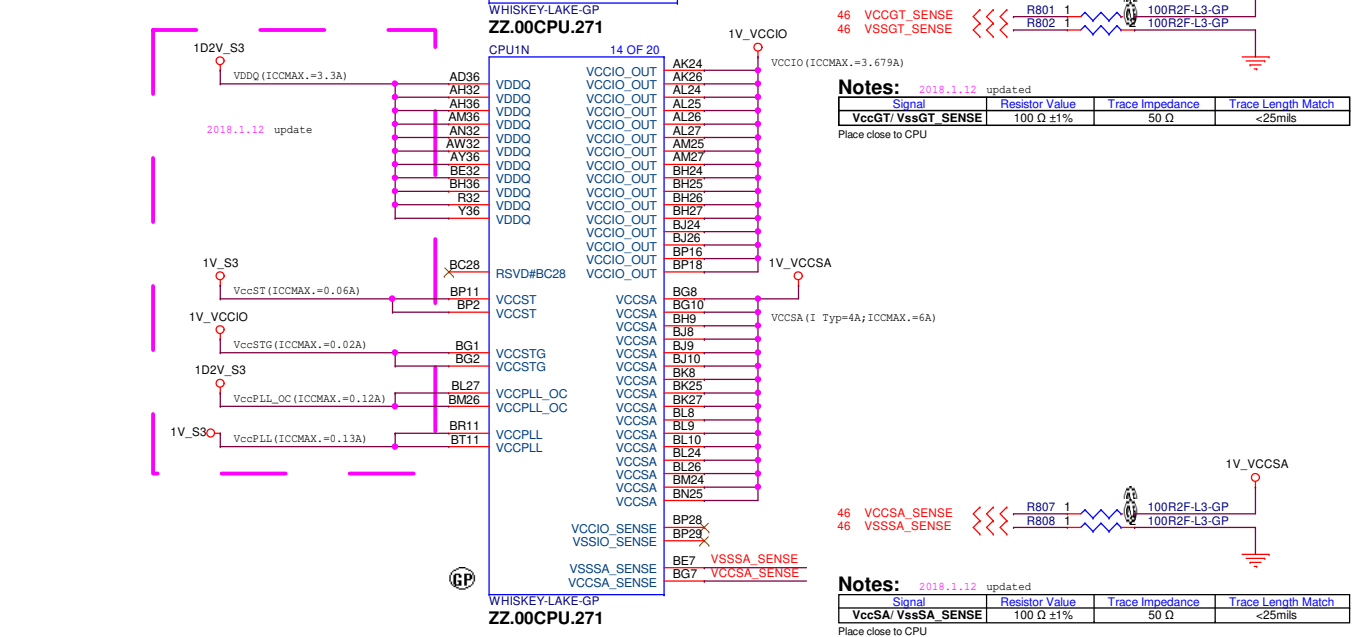
Size B Document Number: **FAROE 14" Pavilion** Rev SA

Date: Monday, August 06, 2018 Sheet 7 of 106

Main Func = CPU



Pin Number	CFL-U43E	WHL ES1 Netname	WHL ES2 Netname
AA9	VCCGT	VCCGT	VCCCORE
AB10	VCCGT	VCCGT	VCCCORE
AB2	VCCGT	VCCGT	VCCCORE
AB8	VCCGT	VCCGT	VCCCORE
AB9	VCCGT	VCCGT	VCCCORE
AC8	VCCGT	VCCGT	VCCCORE
AD9	VCCGT	VCCGT	VCCCORE
AE10	VCCGT	VCCGT	VCCCORE
AE8	VCCGT	VCCGT	VCCCORE
AE9	VCCGT	VCCGT	VCCCORE
AF10	VCCGT	VCCGT	VCCCORE
AF2	VCCGT	VCCGT	VCCCORE
AF8	VCCGT	VCCGT	VCCCORE
AG8	VCCGT	VCCGT	VCCCORE
AG9	VCCGT	VCCGT	VCCCORE
AH9	VCCGT	VCCGT	VCCCORE
AJ10	VCCGT	VCCGT	VCCCORE
AJ8	VCCGT	VCCGT	VCCCORE
AK2	VCCGT	VCCGT	VCCCORE
AK9	VCCGT	VCCGT	VCCCORE
AL10	VCCGT	VCCGT	VCCCORE
AL8	VCCGT	VCCGT	VCCCORE
AL9	VCCGT	VCCGT	VCCCORE
AM8	VCCGT	VCCGT	VCCCORE
Y10	VCCGT	VCCGT	VCCCORE
Y8	VCCGT	VCCGT	VCCCORE



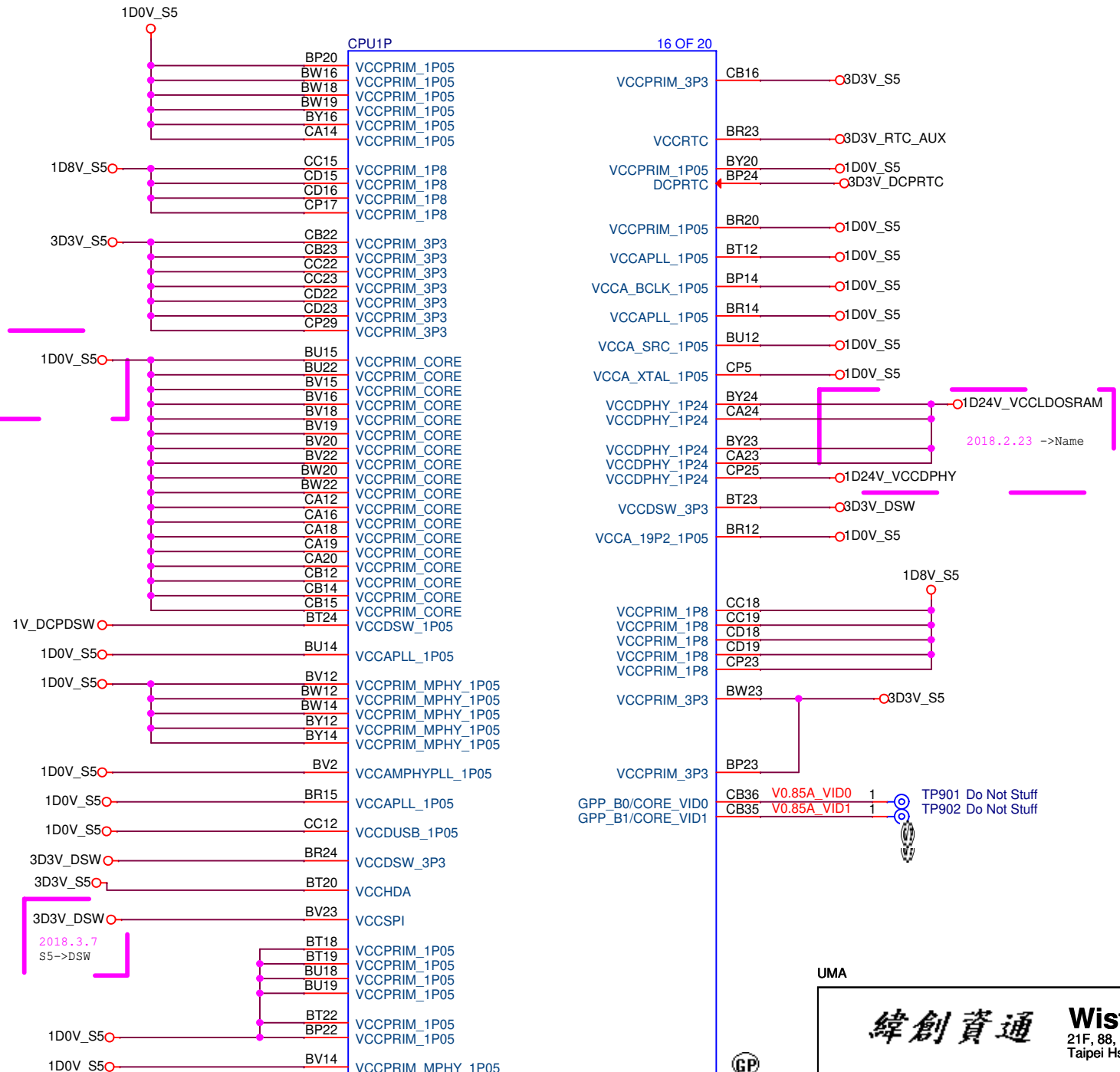
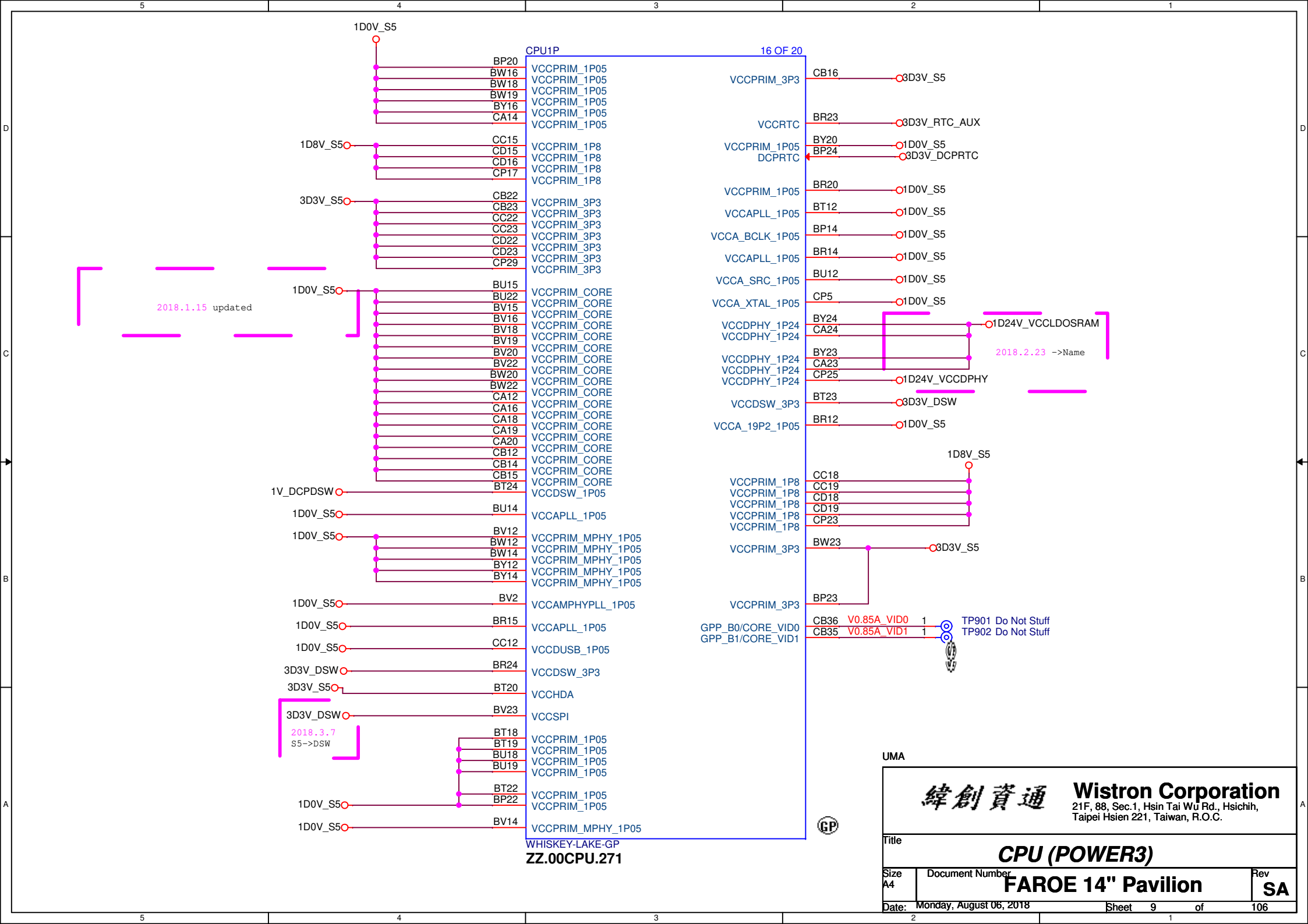
UMA

緯創資通 Wistron Corporation
21F, 88, Sec. 1, Hsin Tai Wu Rd., Hstchih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **CPU (POWER2)**

Size A3 Document Number: **FAROE 14" Pavilion** Rev: **SA**

Date: Monday, August 06, 2018 Sheet 8 of 106



WHISKEY-LAKE-GP
ZZ.00CPU.271

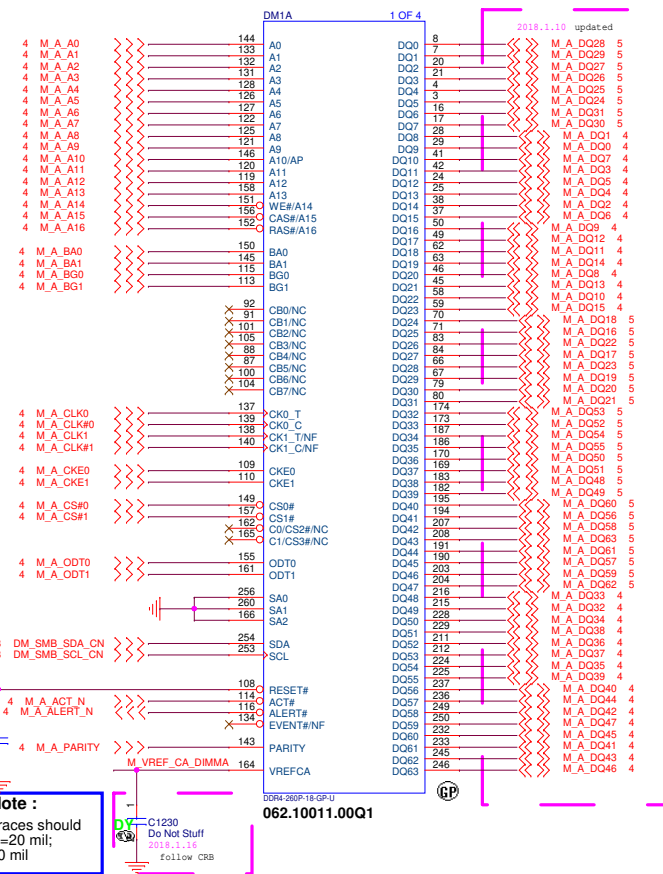
UMA

緯創資通 **Wistron Corporation**
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

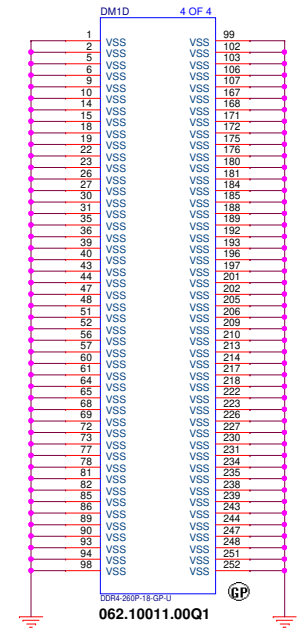
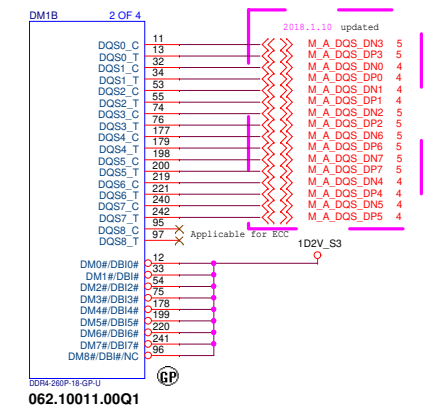
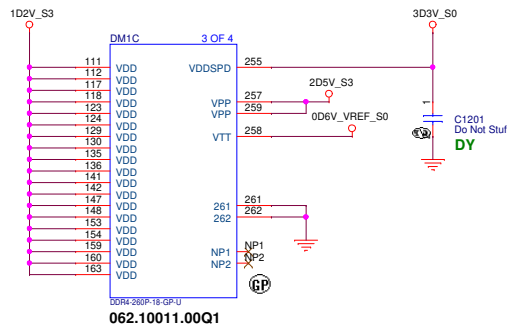
Title: **CPU (POWER3)**

Size A4	Document Number	Rev SA
Date: Monday, August 06, 2018	Sheet 9 of 106	

DDR4 Reverse Type



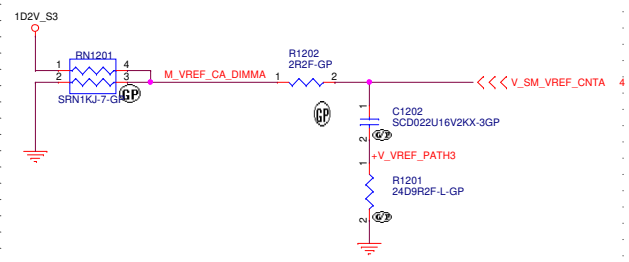
Layout Note :
VREFCA traces should have width=20 mil; spacing=20 mil



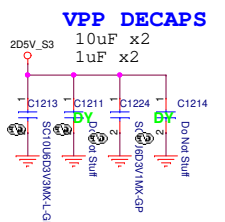
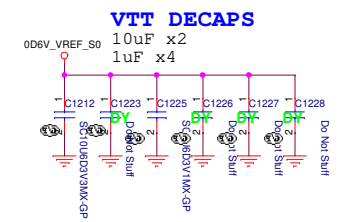
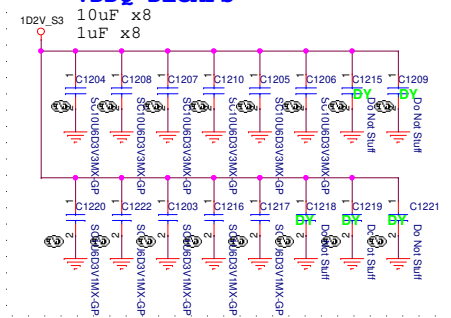
SPD Address of DIMMA

SPD SA2	0
SPD SA1	0
SPD SA0	0

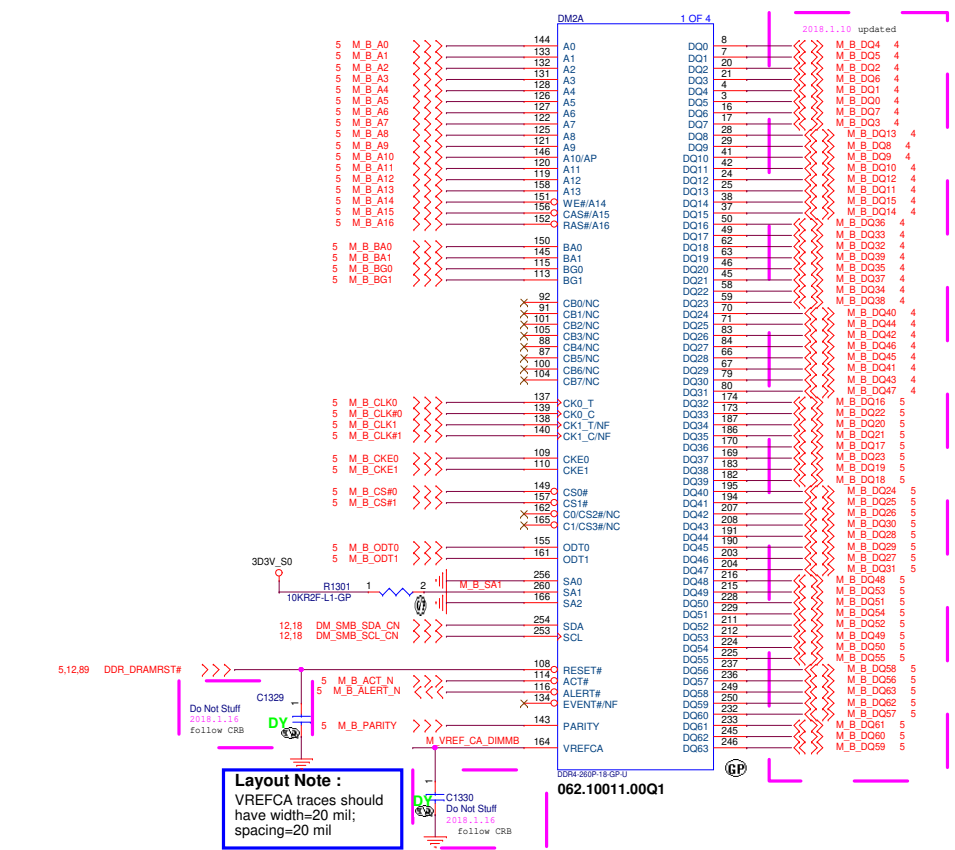
SA_DIMM_VREFDQ



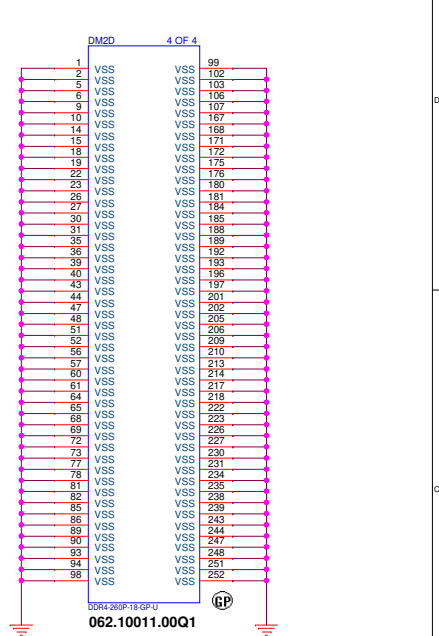
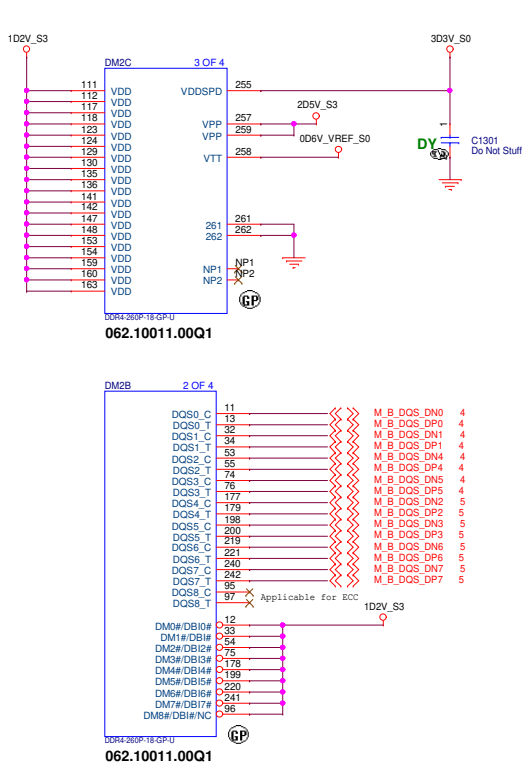
Layout Note : Place these Caps near DIM1



DDR4 Reverse Type

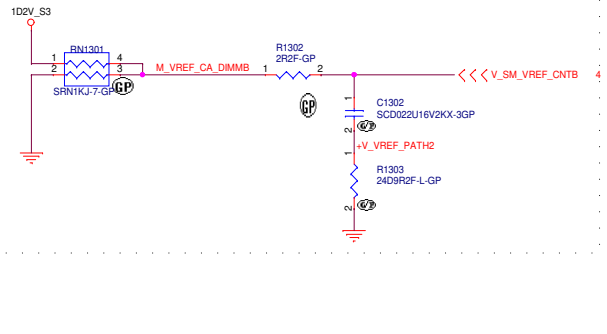


Layout Note :
VREFCA traces should have width=20 mil; spacing=20 mil

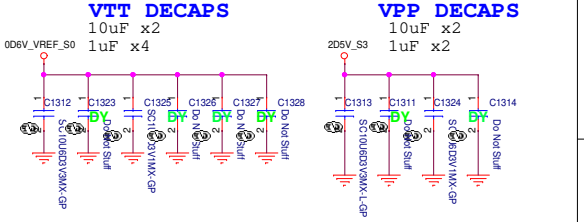
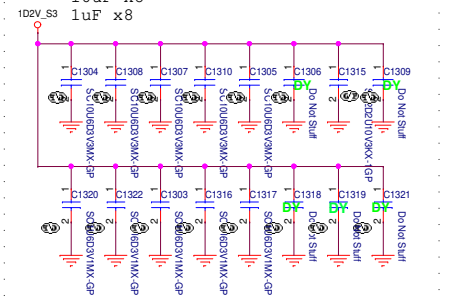


SPD Address of DIMMB SA_DIMM_VREFDQ

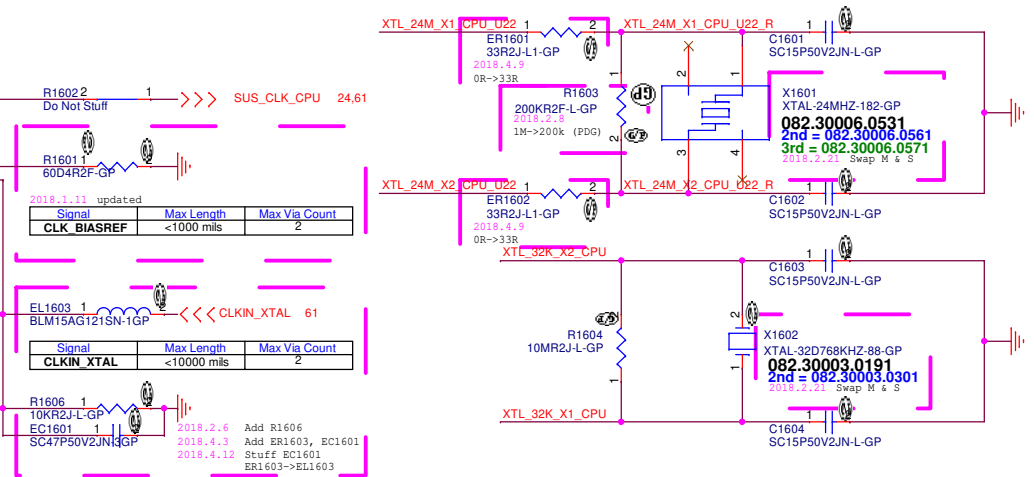
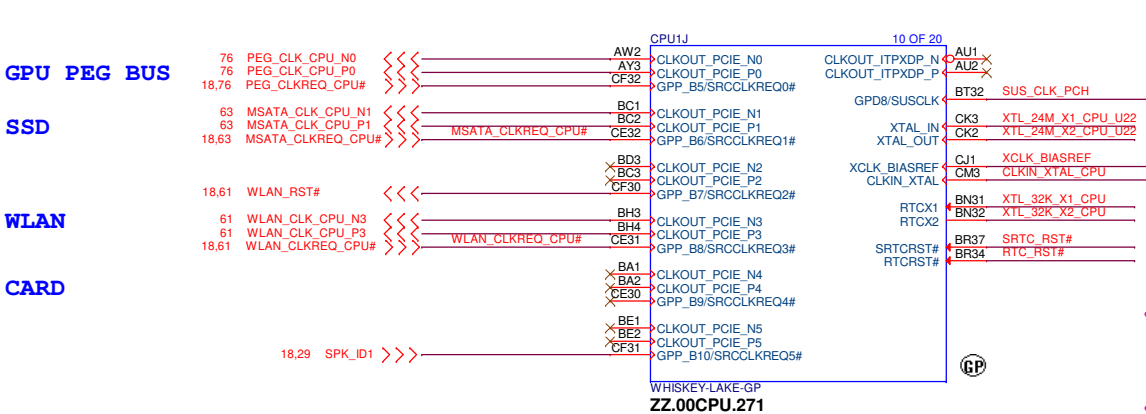
SPD SA2	0
SPD SA1	1
SPD SA0	0



Layout Note : Place these Caps near DIM1



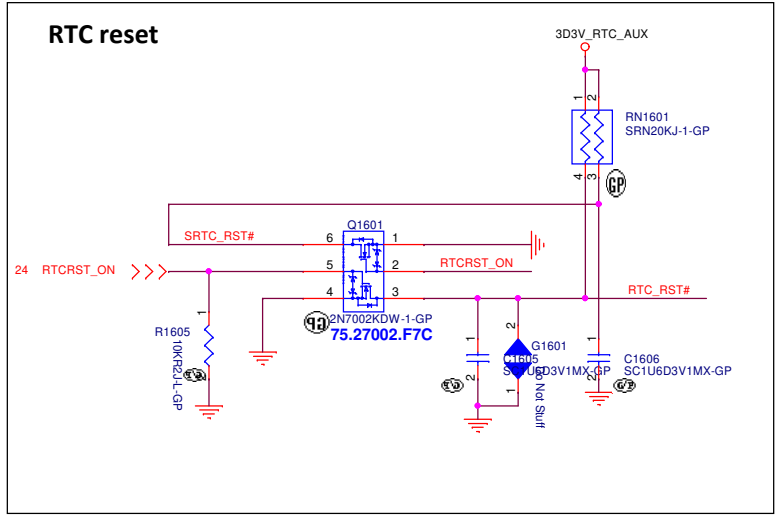
Main Func = PCH



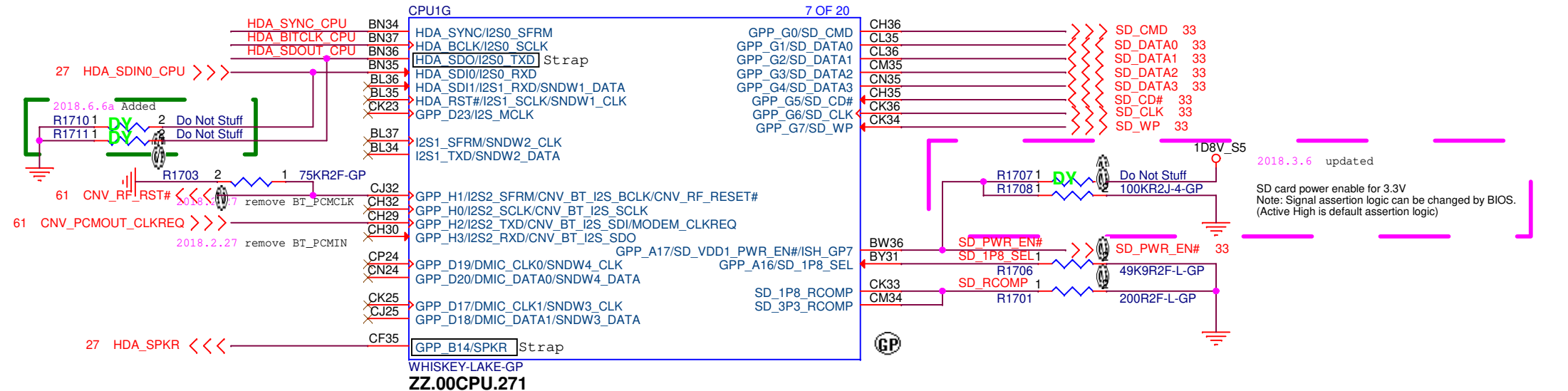
2018.1.10 updated
Table 7-1. Platform Clocks and Associated Signal Details and Descriptions

Signal Name	Type	SSC Capable	Description
CLKOUT_ITPXDP_P CLKOUT_ITPXDP_N	O	Yes	Differential ITP Debug Clock: 100 MHz differential output to processor XDP/ITP connector on the platform
CNL U PCH-LP: • CLKOUT_PCIE_P[5:0] • CLKOUT_PCIE_N[5:0]	O	Yes	PCI Express* Clock Output: Serial Reference 100 MHz PCIe* 3.0 specification compliant differential output clocks to PCIe* devices
CLKOUT_LPC[1:0]	O	No	Low Pin Count (LPC) Clock Outputs: Single-Ended 24-MHz output to various single load connectors/devices
SRCCLKREQ#[5:0]	I/O		Clock Request: Serial Reference Clock request signals for PCIe* 100 MHz differential clocks
XTAL_IN	I		Crystal Input: Input connection for 24MHz crystal to PCH
XTAL_OUT	O		Crystal Output: Output connection for 24 MHz crystal to PCH
XCLK_BIASREF	I/O		Differential Clock Bias Reference: Used to set BIAS reference for differential clocks
CLKIN_XTAL	I		XTAL Clock Input: Single ended integrated CNV (Connectivity) XTAL clock input

Note:
 1. SSC = Spread Spectrum Clcking
 2. The SRCCLKREQ# signals can be configured to map to any of the PCH PCI Express* Root Ports while using any of the CLKOUT_PCIE_P/N differential pairs



Main Func = PCH



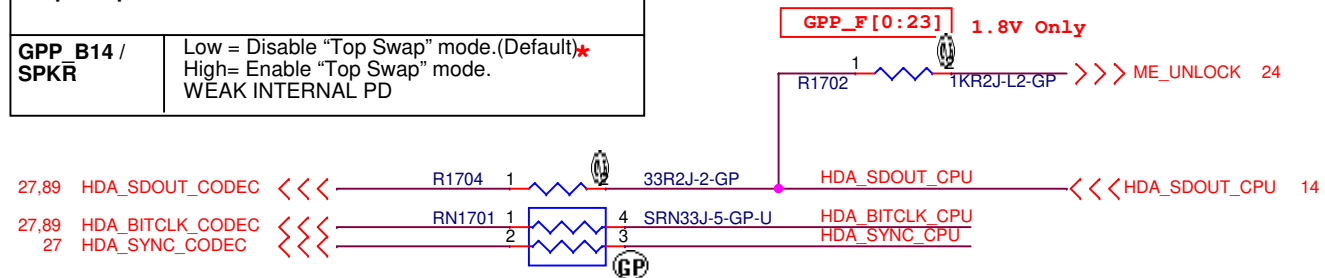
PCH strap pin:

Flash Descriptor Security Override/ Intel ME Debug Mode	
HDA_SDO/ I2S0_TXD	Low = Security measures not override(Default)* High= Overriden WEAK INTERNAL PD

The internal pull-down is disabled after PLTRST# deasserts

PCH strap pin:

Top Swap Override	
GPP_B14 / SPKR	Low = Disable "Top Swap" mode.(Default)* High= Enable "Top Swap" mode. WEAK INTERNAL PD



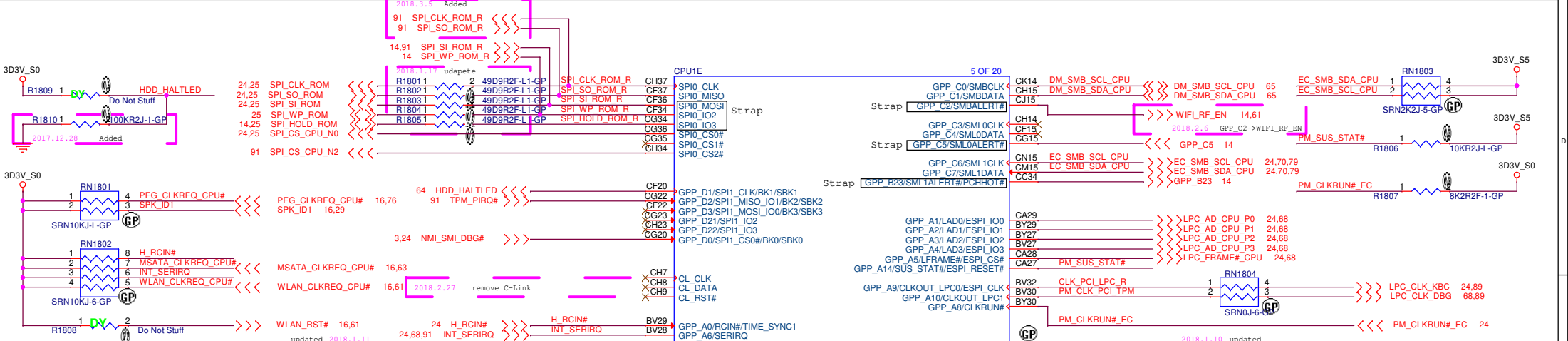
UMA

緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **PCH (AUDIO/SDIO/SDXC)**

Size A4 Document Number: **FAROE 14" Pavilion** Rev: **SA**

Date: Monday, August 06, 2018 Sheet 17 of 106



updated 2018.1.11

PCH strap pin:
BOOT HALT(EDS Reserved)

SPI0_MOSI	Low = Enable High = Disable(Default) ★ WEAK INTERNAL PU
-----------	---

This strap should sample HIGH.

PCH strap pin:
CONSENT STRAP(EDS Reserved)

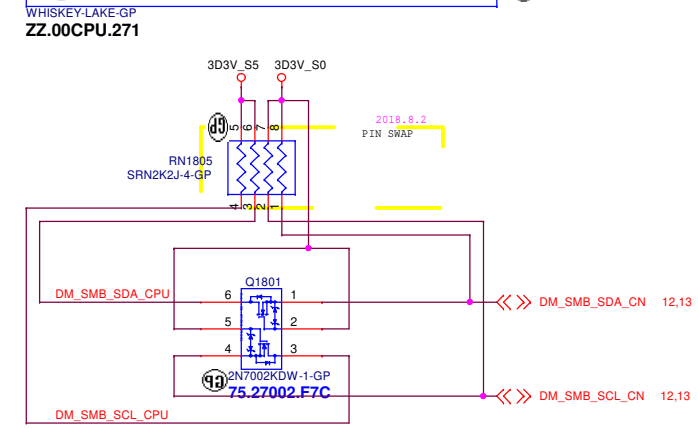
SPI0_IO2	Low = Enable High = Disable(Default) ★ WEAK INTERNAL PU
----------	---

This strap should sample HIGH.

PCH strap pin:
A0 PERSONALITY STRAP(EDS Reserved)

SPI0_IO3	Low = Enable High = Disable(Default) ★ WEAK INTERNAL PU
----------	---

This strap should sample HIGH.



2018.1.10 updated

PCH strap pin:
TLS CONFIDENTIALITY
Intel ME Crypto Transport Layer Security

GPP_C2 / SMBALERT#	Low = Disable(Default) ★ High = Enable WEAK INTERNAL PD
--------------------	---

PCH strap pin:
eSPI or LPC is selected for EC

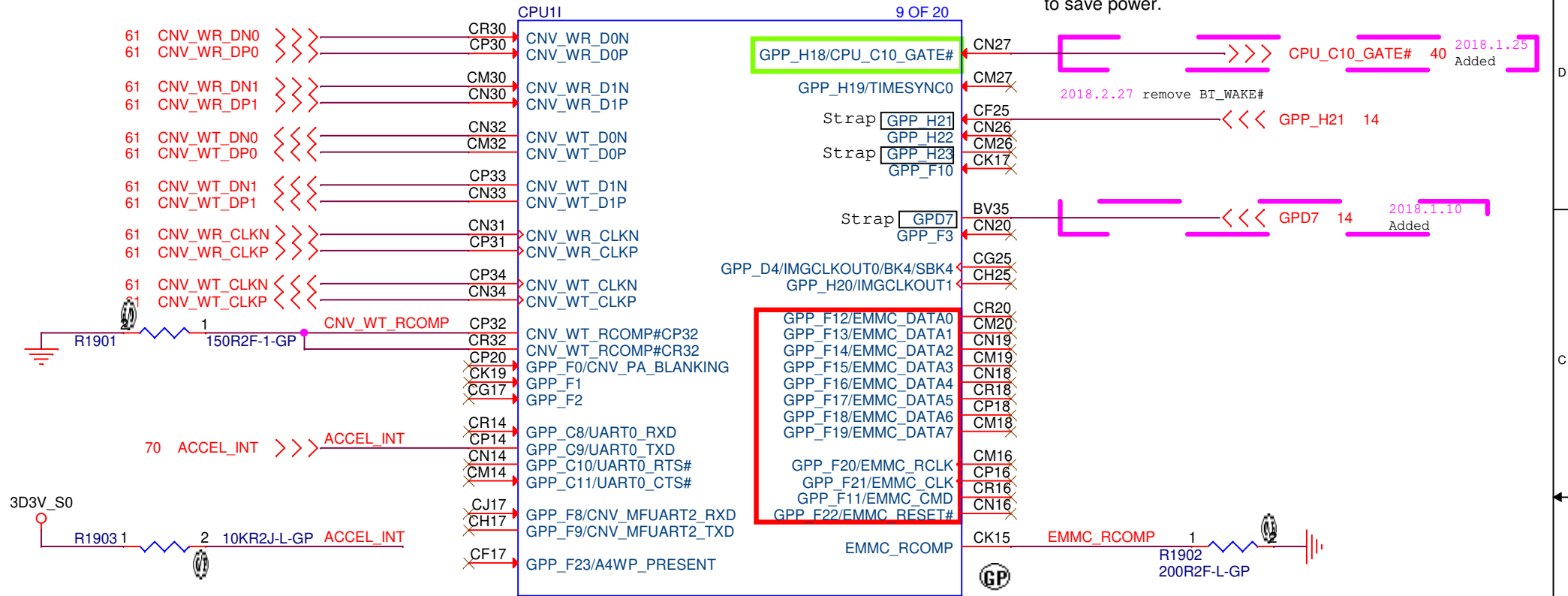
GPP_C5 / SML0ALERT#	Low = LPC(Default) ★ High = eSPI WEAK INTERNAL PD
---------------------	---

PCH strap pin:
EXI BOOT STALL BYPASS

GPP_B23 / SMLTALERT# / PCHHOT#	Low = DISABLED (BSSB 4 WIRE)(Default) ★ High = ENABLED (BSSB 2+2) WEAK INTERNAL PD
--------------------------------	--

Main Func = PCH

2018.1.12 updated
CPU_C10_GATE# is a new signal from the Whiskey Lake SoC that can be used for gating off VccSTG, VccPLL_OC and VccIO (WHL-U) in the S0/C10 system state in order to save power.



2018.1.10 updated

PCH strap pin:

XTAL INPUT MODE HVM ONLY	
GPP_H21	Low = 38.4/19.2MHZ (DEFAULT) High= 24MHZ*

2018.1.10 updated

PCH strap pin:

MAF/SAF STRAP	
GPP_H23	Low = MAF ENABLE(Default) * High= SAF ENABLE WEAK INTERNAL PD

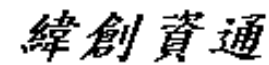
2018.1.11 updated

PCH strap pin:

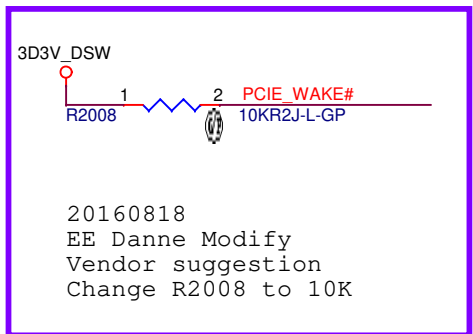
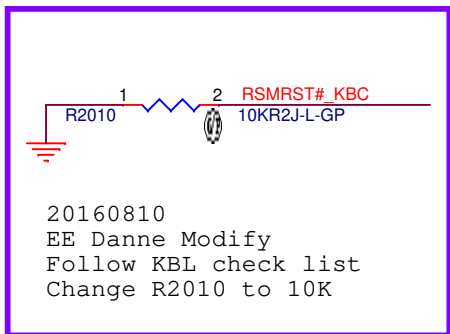
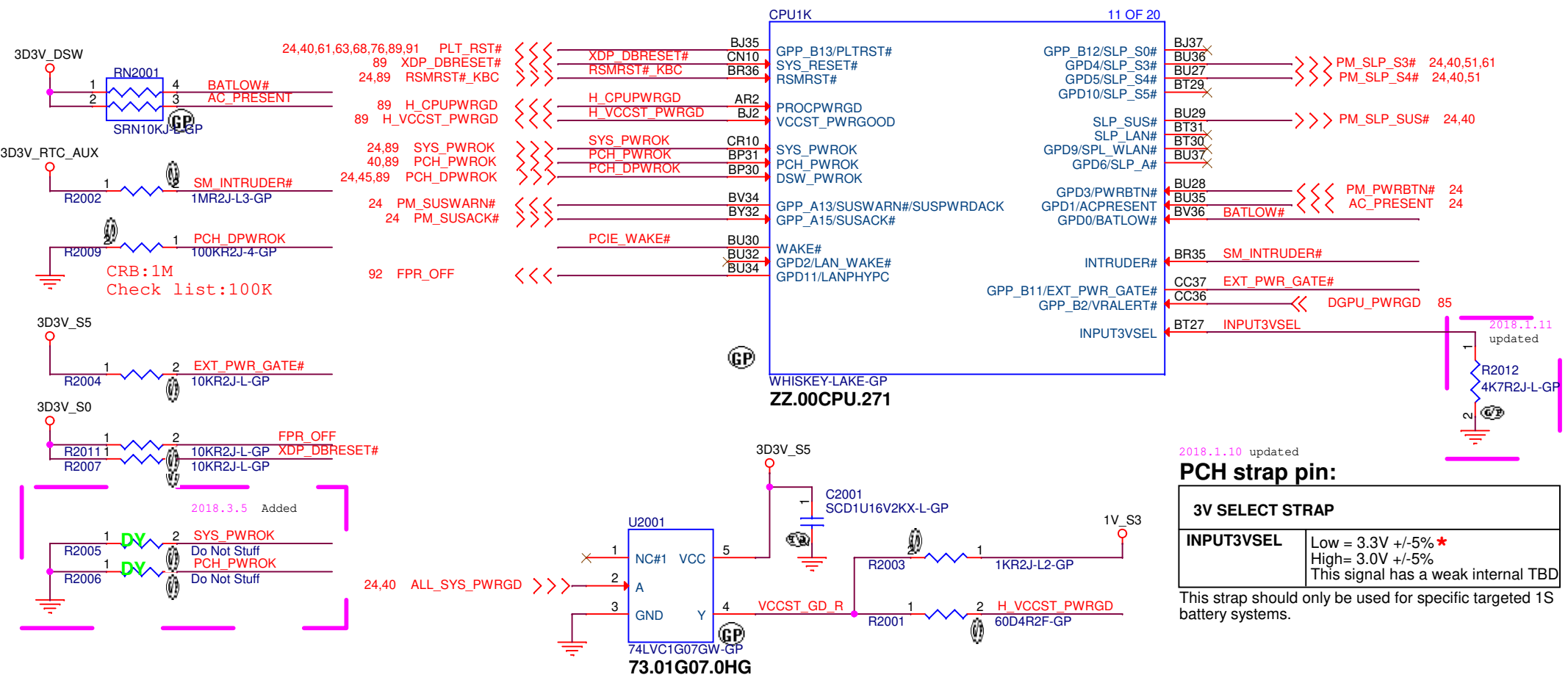
XTAL INPUT MODE(EDS Reserved) HVM ONLY	
GPD7	Low = XTAL INPUT IS SINGLE ENDED * High= XTAL IS ATTACHED WEAK INTERNAL PD?

WHISKEY-LAKE-GP
ZZ.00CPU.271

UMA

 Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.		
Title PCH (CSI2/EMMC)		
Size A	Document Number FAROE 14" Pavilion	Rev SA
Date: Monday, August 06, 2018		Sheet 19 of 106

Main Func = PCH



UMA

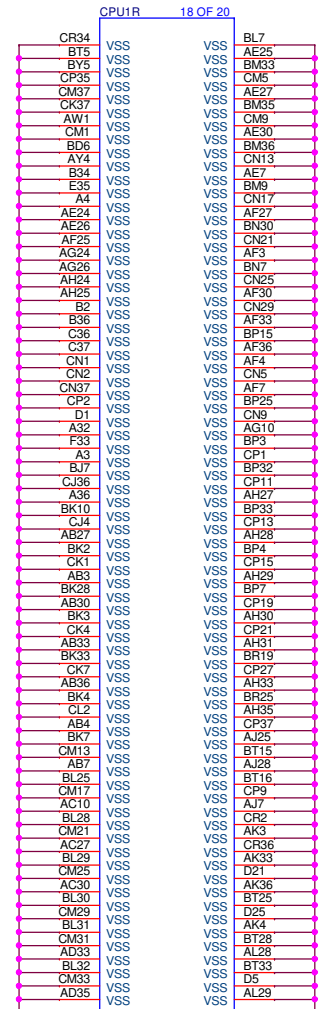
緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title **PCH (SYS POWER MANAGEMENT)**

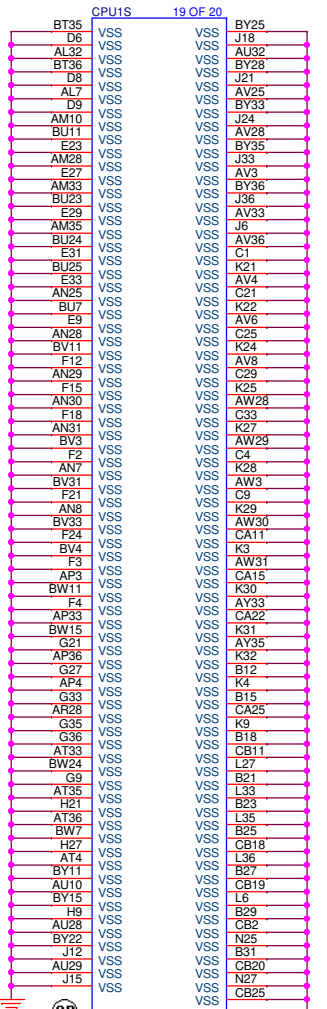
Size A4 Document Number **FAROE 14" Pavilion** Rev **SA**

Date: Monday, August 06, 2018 Sheet 20 of 106

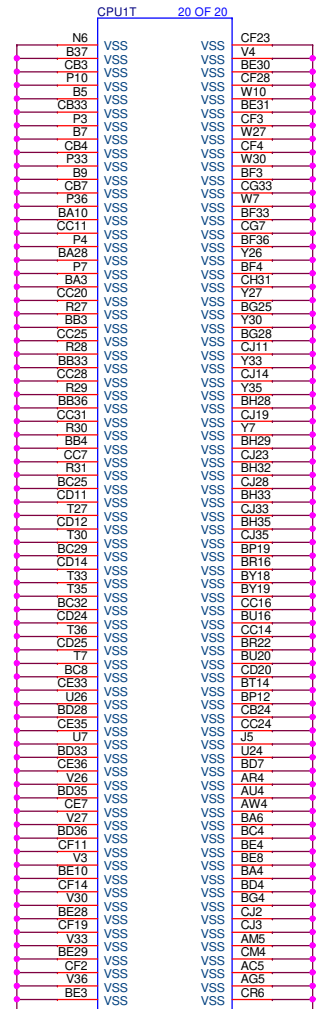
Main Func = PCH



WHISKEY-LAKE-GP
ZZ.00CPU.271



WHISKEY-LAKE-GP
ZZ.00CPU.271



WHISKEY-LAKE-GP
ZZ.00CPU.271

UMA

緯創資通 Wistron Corporation
21F, 88, Sec. 1, Hsin Tai Wu Rd., Hstchih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **PCH (VSS)**

Size: A3 | Document Number: **FAROE 14" Pavilion** | Rev: **SA**

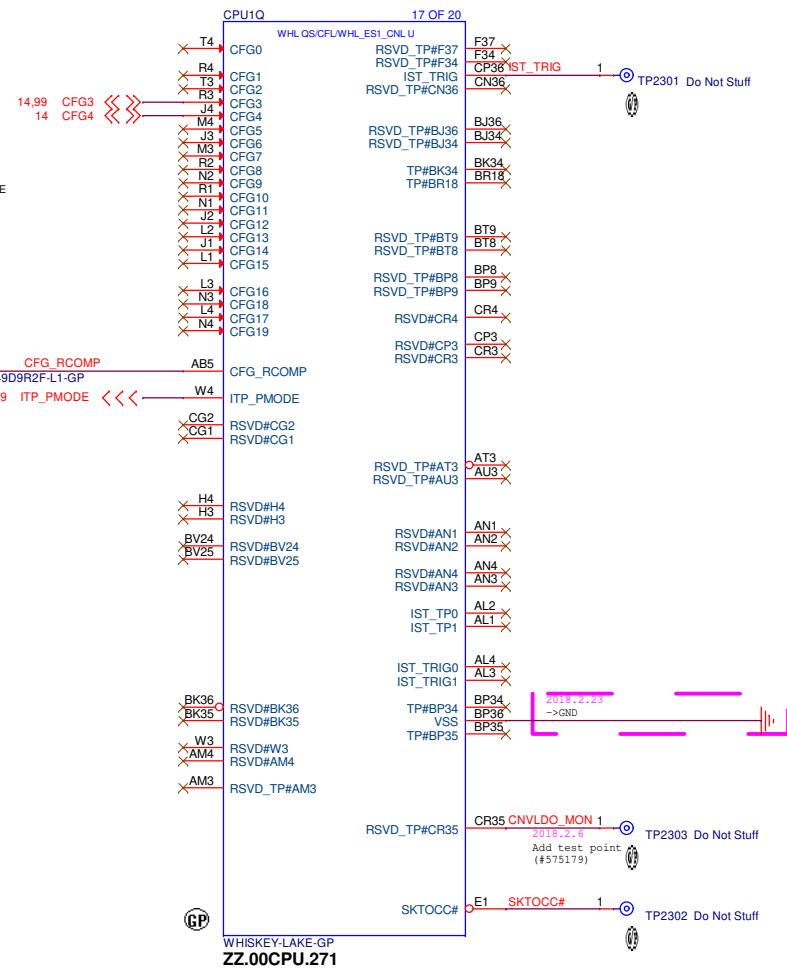
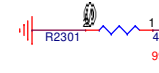
Date: Monday, August 06, 2018 | Sheet: 21 of 106

Main Func = CPU

2018.1.12 updated

CPU strap pin:

PHYSICAL_DEBUG_ENABLED (DFX PRIVACY)	
CFG3	Low = ENABLED SET DFX ENABLED BIT IN DEBUG INTERFACE MSR High = DISABLED*
DISPLAY PORT PRESENCE STRAP	
CFG4	Low = ENABLED* AN EXTERNAL DISPLAY PORT DEVICE IS CONNECTED TO THE EMBEDDED DISPLAY PORT High = DISABLED NO PHYSICAL DISPLAY PORT ATTACHED TO EMBEDDED DISPLAY PORT



WHISKEY-LAKE-GP
ZZ.00CPU.271

2018.1.15 updated

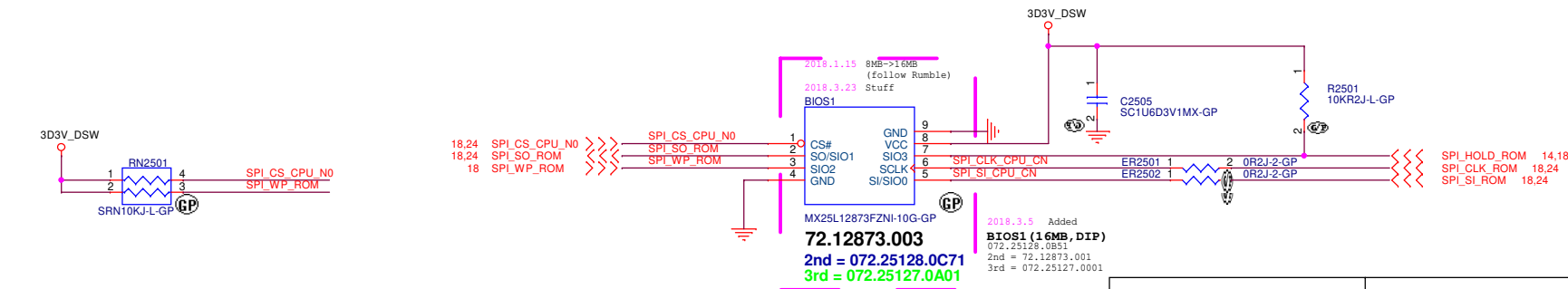
#575962 RVP Rev0.5 P.32~33

Description	CFG
CFG[0]: EAR-STALL/NOT STALL RESET SEQUENCE AFTER PCU PLL IS LOCKED 1 : (DEFAULT) NORMAL OPERATION; NO STALL 0 : STALL	CFG0
CFG[1]: PCH/ PCH LESS MODE SELECTION 1 : (DEFAULT) NORMAL OPERATION 0 : PCH-LESS MODE	CFG1
CFG[2]: PCI EXPRESS STATIC LANE REVERSAL FOR ALL PEG PORTS 1 : (DEFAULT) NORMAL OPERATION; 0 : LANE REVERSAL	CFG2
CFG[3]: PHYSICAL_DEBUG_ENABLED (DFX PRIVACY) 0 : ENABLED SET DFX ENABLED BIT IN DEBUG INTERFACE MSR 1 : DISABLED	CFG3
CFG[4]: DISPLAY PORT PRESENCE STRAP 0 : ENABLED AN EXTERNAL DISPLAY PORT DEVICE IS CONNECTED TO THE EMBEDDED DISPLAY PORT 1 : DISABLED NO PHYSICAL DISPLAY PORT ATTACHED TO EMBEDDED DISPLAY PORT	CFG4
CFG[6:5]: PCIE PORT BIFURCATION STRAPS 11 : DEVICE1 FUNCTION 1, DEVICE 1 FUNCTION2 DISABLED 10 : DEVICE1 FUNCTION1 ENABLED DEVICE1 FUNCTION 2 DISABLED 01 : DEVICE 1 FUNCTION 1 DISABLED, DEVICE 1 FUNCTION 2 ENABLED 00 : DEVICE 1 FUNCTION 1 ENABLED, DEVICE 1 FUNCTION 2 ENABLED	CFG5, CFG6
CFG[7]: PEG DEFER TRAINING 1 : (DEFAULT) PEG TRAIN IMMEDIATELY FOLLOWING XKRESETB DE ASSERTION 0 : PEG WAIT FOR BIOS FOR TRAINING	CFG7
CFG[8]: ALLOW THE USE OF NOA ON LOCKED UNITS 1 : DISABLED (DEFAULT); IN THIS CASE, NOA WILL BE DISABLED IN LOCKED UNITS AND ENABLED IN UN-LOCKED UNITS 0 : ENABLED; NOA WILL BE AVAILABLE REGARDLESS OF THE LOCKING OF THE UNIT	CFG8
CFG[9]: NO SVID PROTOCOL CAPABLE VR CONNECTED 1 : VRS SUPPORTING SVID PROTOCOL ARE PRESENT 0 : NO VR SUPPORTING SVID IS PRESENT. THE CHIP WILL NOT GENERATE (OR RESPOND TO) SVID ACTIVITY	CFG9
CFG[10]: SAFE MODE BOOT 1 : POWER FEATURES ACTIVATED DURING RESET 0 : POWER FEATURES (ESPECIALLY CLOCK GATINE ARE NOT ACTIVATED	CFG10
CFG[11]: DMI AC COUPLING - JUST A PLACE HOLDER. NOT APPLICABLE FOR ULX-ULT 1 : (DEFULT) DMI WILL BE CONFIGURED AS HALF SWING DC COUPLED 0 : DMI WILL BE CONFIGURED AS FULL SWING AC COUPLED	CFG11
CFG[12]: PM SYNC LEGACY THIS STRAP IS NEW IN SKL. IT TELL THE CPU THAT IT IS CONNECTED TO PCH SUPPORTING OLDER VERSION OF PMSYNC PROTOCOL IN LEGACY MORE CPU DOESN'T WAIT FOR EPOC MESSAGE FROM THE PCH 1 : (DEFAULT) PMSYNC 2.0 0 : LEGACY	CFG12
CFG[13]: PMSYNC AYNC MODE- PM SYNC 1 : (DEFAULT) SYNCHRONOUS (1_24_MHZ_CYCLE_PER_BIT) 0 : ASYNC - 4-24MHZ CYCLES PER BIT	CFG13

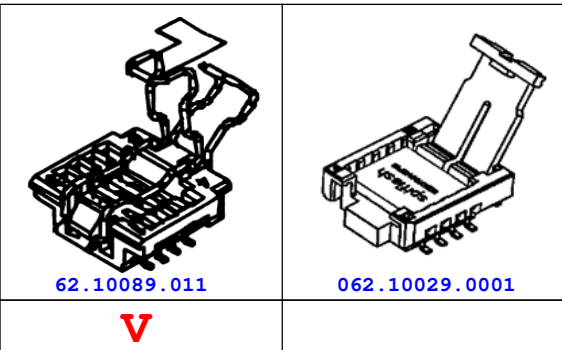
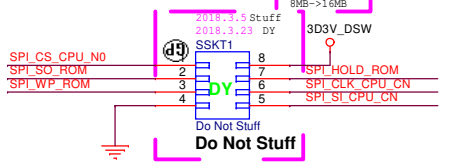
UMA

Wistron Corporation 21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
CPU (RESERVED, CFG)	
Title	
Size A3	Document Number
FAROE 14" Pavilion	
Date: Monday, August 06, 2018	Sheet 23 of 106

SSID = Flash.ROM

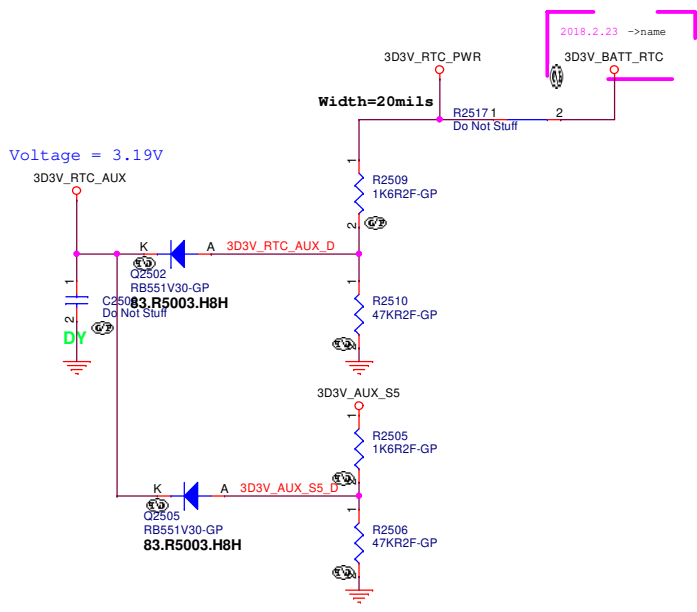


SPI FLASH ROM 16M byte



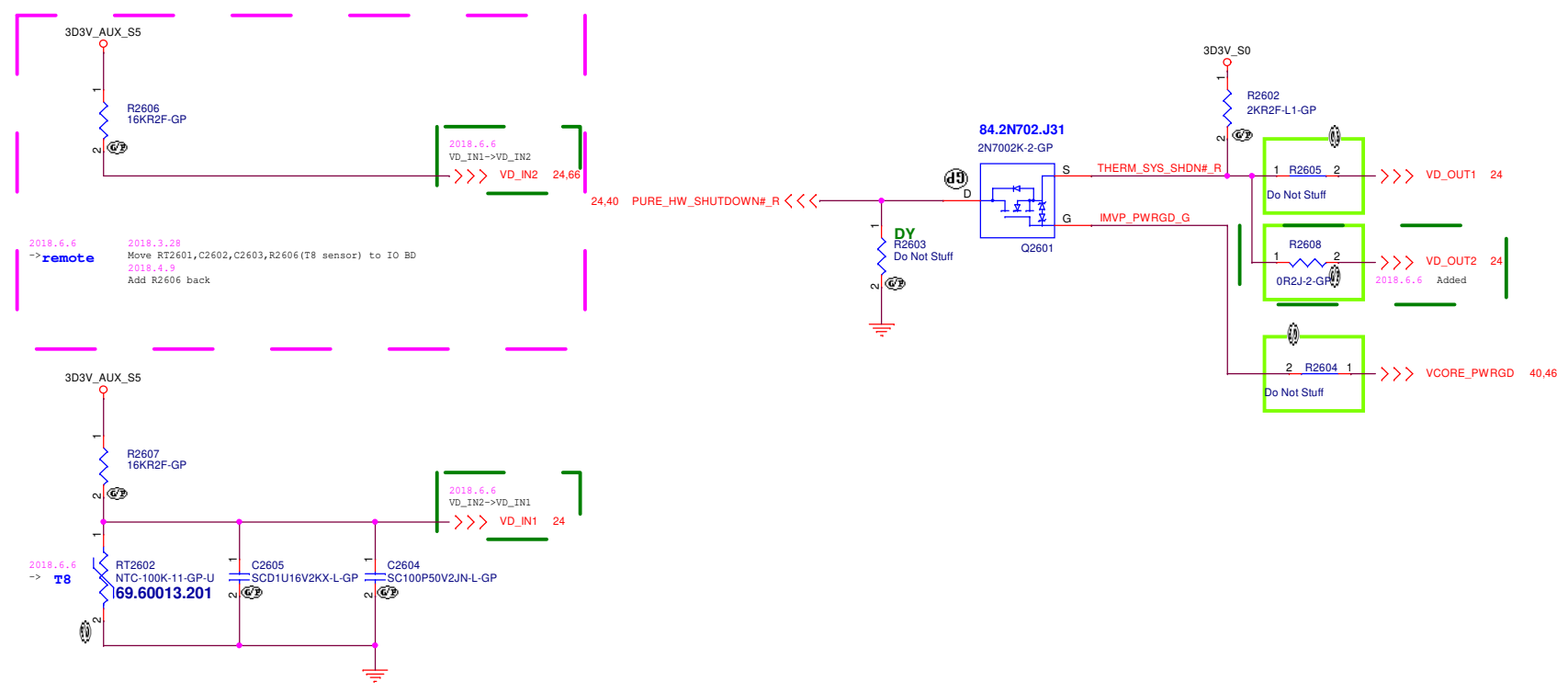
Co-lay with BIOS1

SSID = RBAT



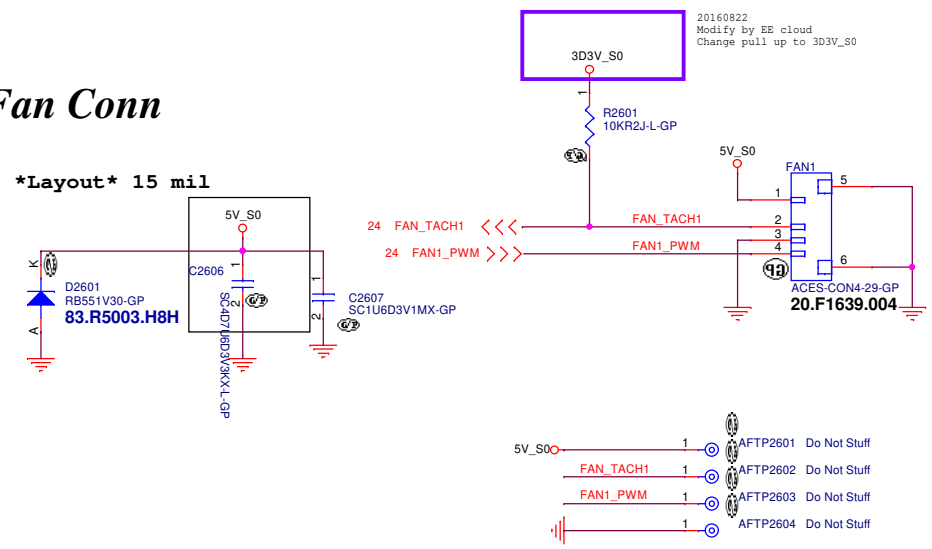
SSID = Thermal

Thermal sensor NCT 7718W

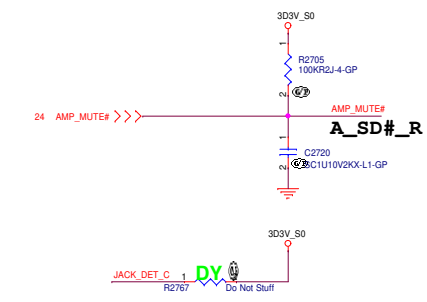
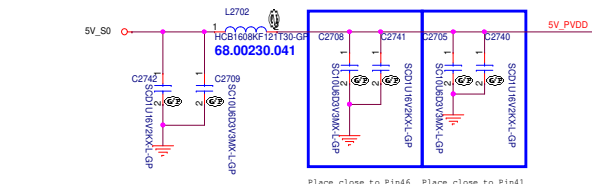
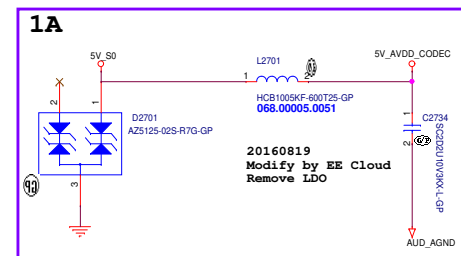
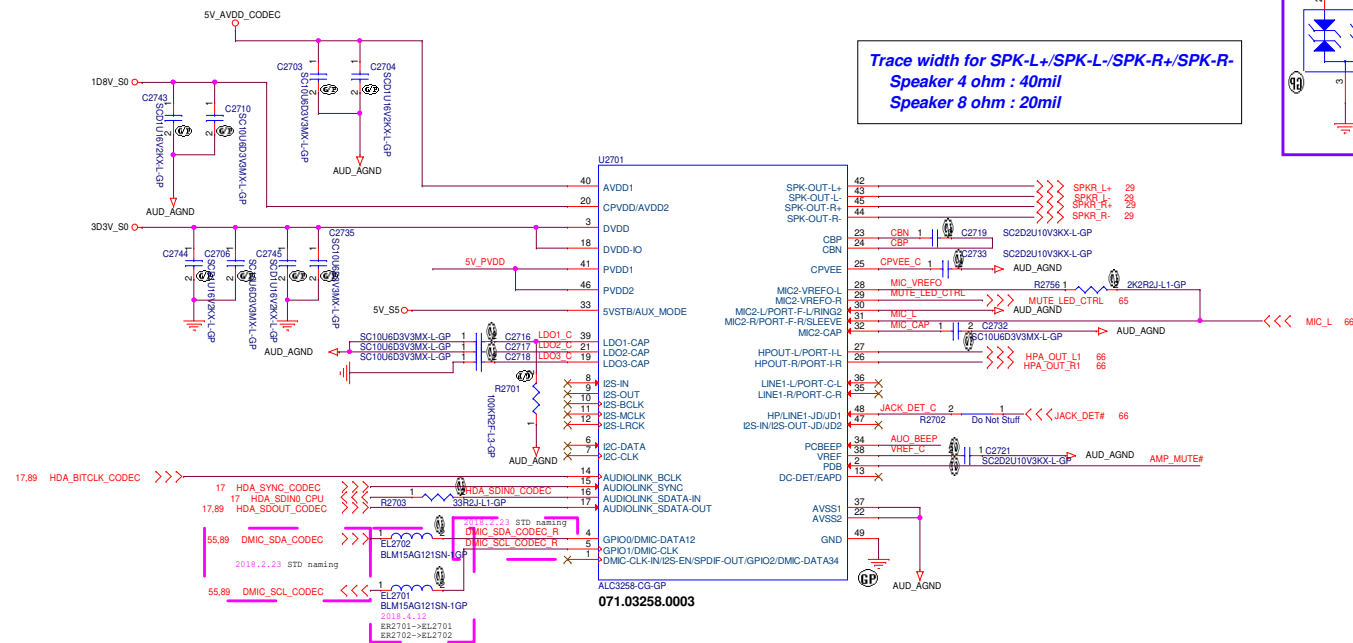


Fan Conn

Layout 15 mil



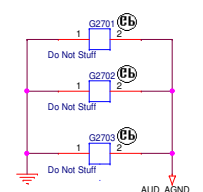
UMA	
Wistron Corporation 21F, 88, Sec. 1, Hsin Tai Wu Rd., Hstchih, Taipei Hsien 221, Taiwan, R.O.C.	
INT IO (Thermal/Fan)	
Size A3	Document Number FAROE 14" Pavilion
Date Monday, August 06, 2018	Rev SA
Sheet 26 of 106	



AMP. for Headphone

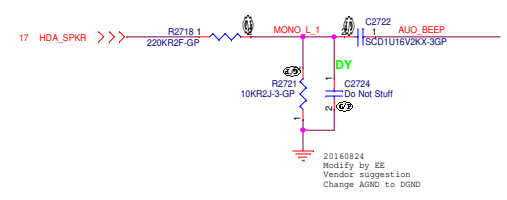
Digital GND & AUD_AGND

Tie Analog GND and Digital GND under codec by a single point



audio ground must be connect to digital ground with an 80 mil copper bridge located directly under codec to prevent ESD latch up.

PC BEEP



UMA

緯創資通 Wistron Corporation
21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

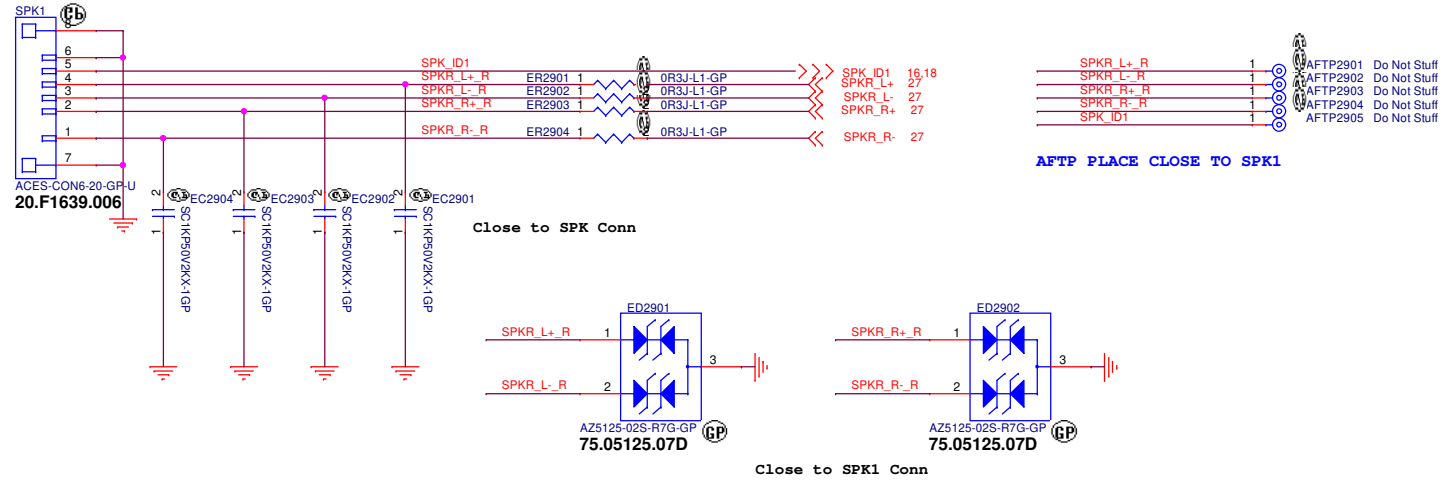
Title: **Audio (Codec ALC3258)**

Size C Document Number: **FAROE 14" Pavilion** Rev: **SA**

Date: Monday, August 06, 2018 Sheet: 27 of 106

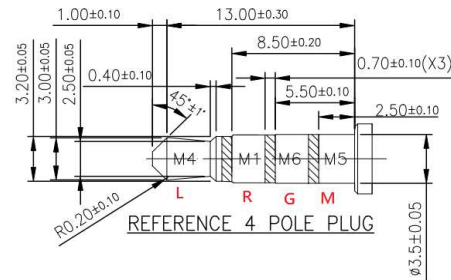
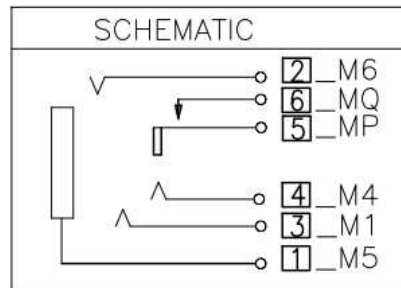
Audio_Speaker

Speaker vendor	FG	Sable
SPK_ID (0 or 1)	1	0



Audio_Jack

Combo-Jack (Headphone & MIC)



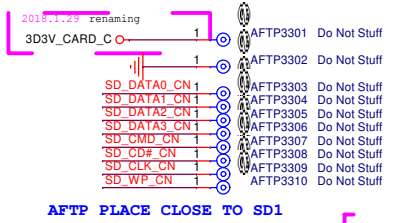
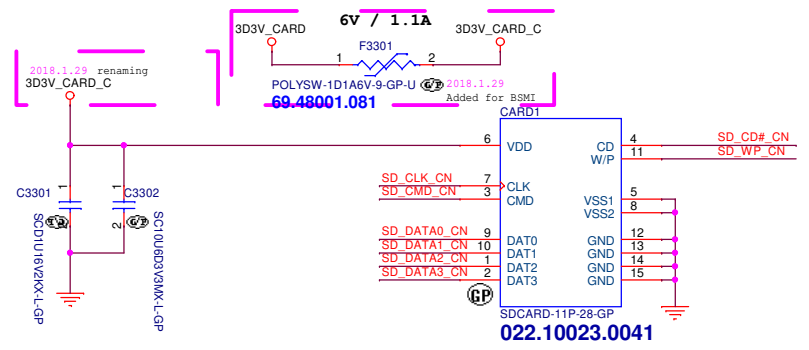
UMA

緯創資通 Wistron Corporation
21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title		
Audio (HP/SPK/MIC Jack)		
Size A3	Document Number FAROE 14" Pavilion	Rev SA
Date: Monday, August 06, 2018	Sheet 29	of 106

Cardreader IC & Cardreader Connector

SSID = CardReader

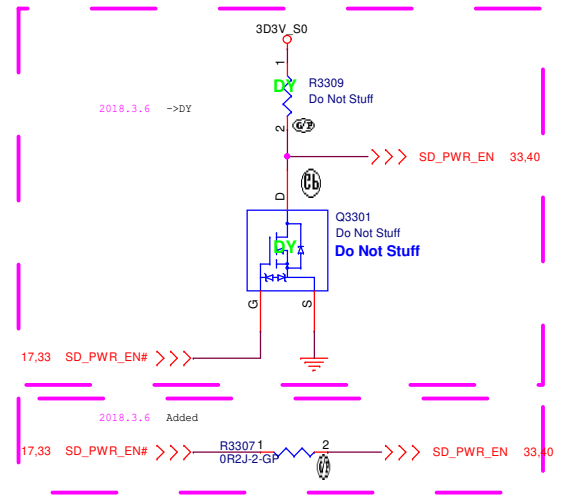
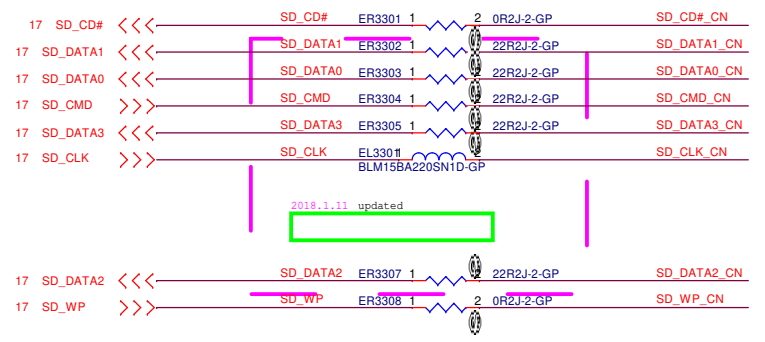
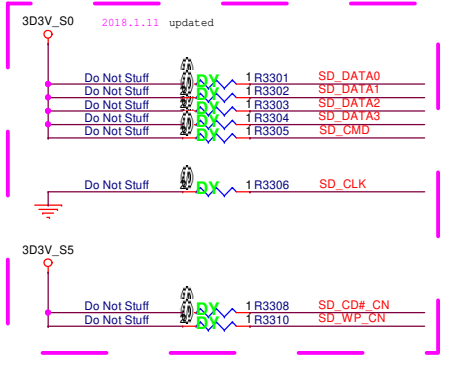


AFTP PLACE CLOSE TO SD1

with out card	CD	CD
	WP	WP
inserted card (unlock)	CD	CD
	WP	WP
inserted card(lock)	CD	CD
	WP	WP

Pin Define

Connector Pin No.	SD Card Pin No.	Pin Define
P1	P9	DAT2
P2	P1	DAT3
P3	P2	CMD
P4		CD
P5	P3	VSS1
P6	P4	VDD
P7	P5	CLK
P8	P6	VSS2
P9	P7	DAT0
P10	P8	DAT1
P11		W/P
P12		GND
P13		GND
P14		GND
P15		GND



UMA

緯創資通 Wistron Corporation
21F, 88, Sec. 1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

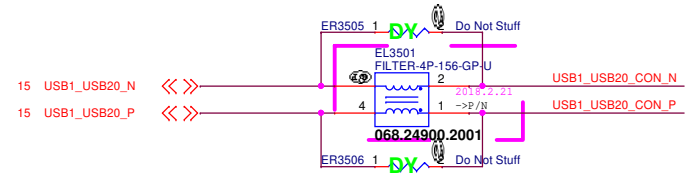
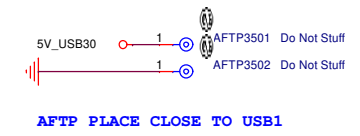
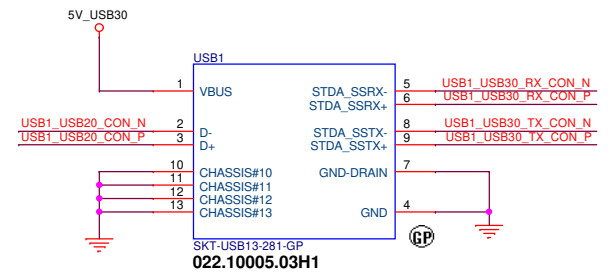
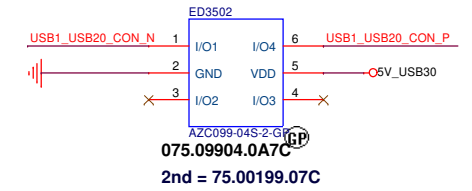
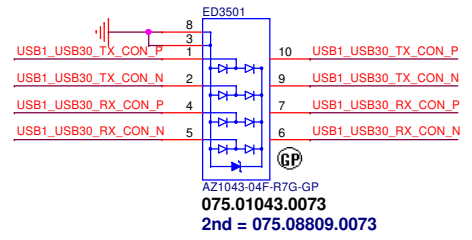
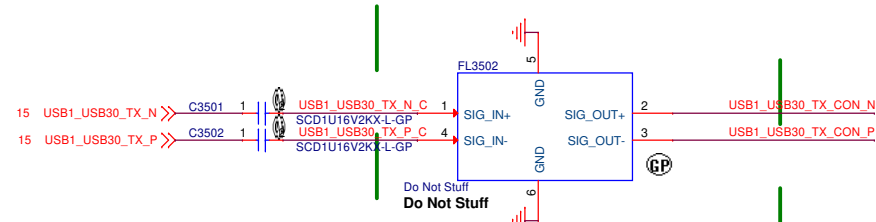
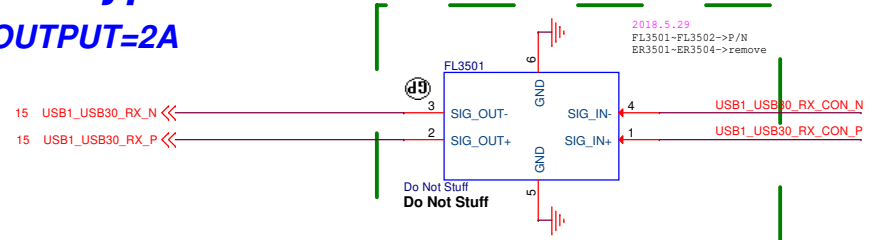
Title: **CARDREADER (SDIO/SD Conn)**

Size A3 Document Number: **FAROE 14" Pavilion** Rev SA

Date: Monday, August 06, 2018 Sheet 33 of 106

USB Type A Connector

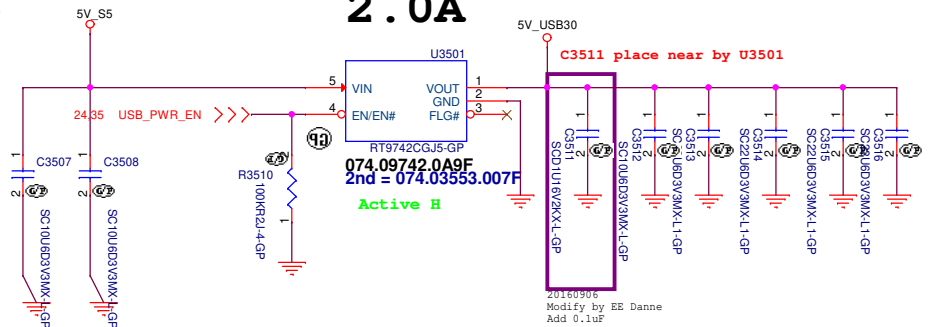
OUTPUT=2A



USB3 Power Switch

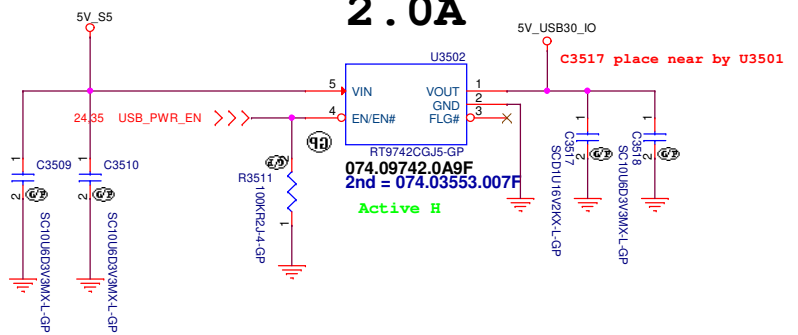
2.0A

U3501 place close to USB1

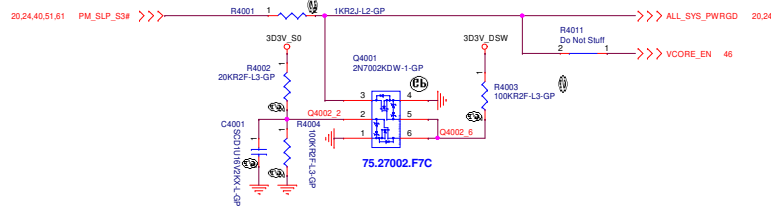


2.0A

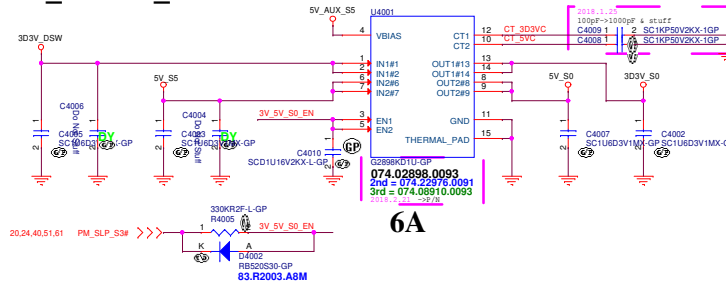
U3502 place close to IO1



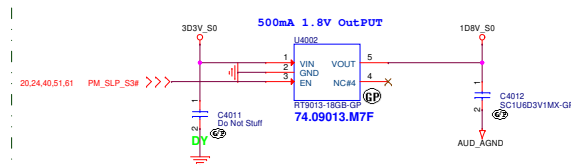
ALLSYSPWRGO/ VCORE_ENABLE



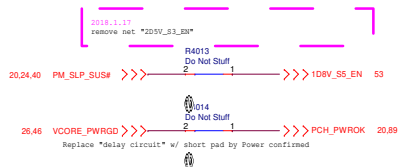
3D3V_S0/ 5V_S0



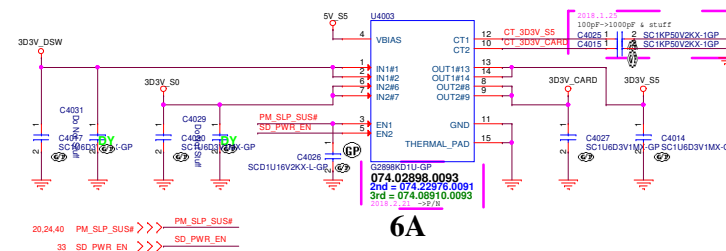
1D8V_S0



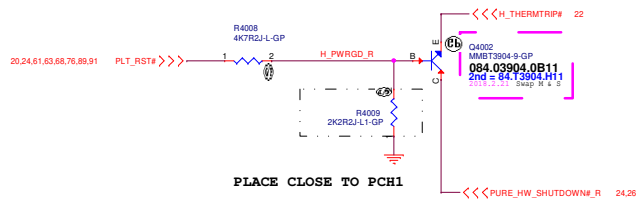
Power Sequence



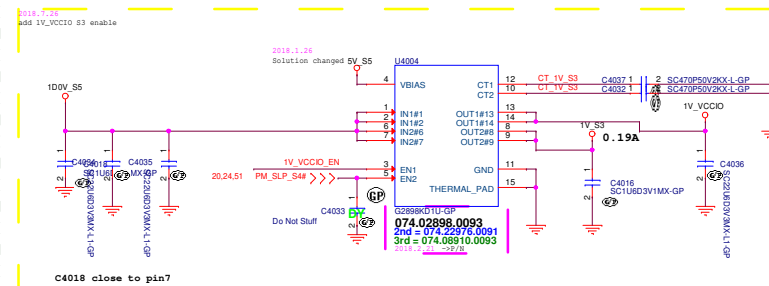
3D3V_S5/ 3D3V_CARD



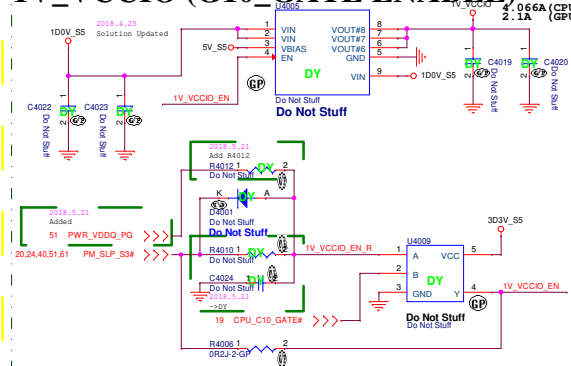
HW_SHUTDOWN



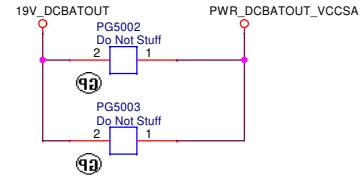
1V_S3/1V_VCCIO (S3 Enable)



1V_VCCIO (G10_GATE ENABLE)



Main Func = CPU_CORE

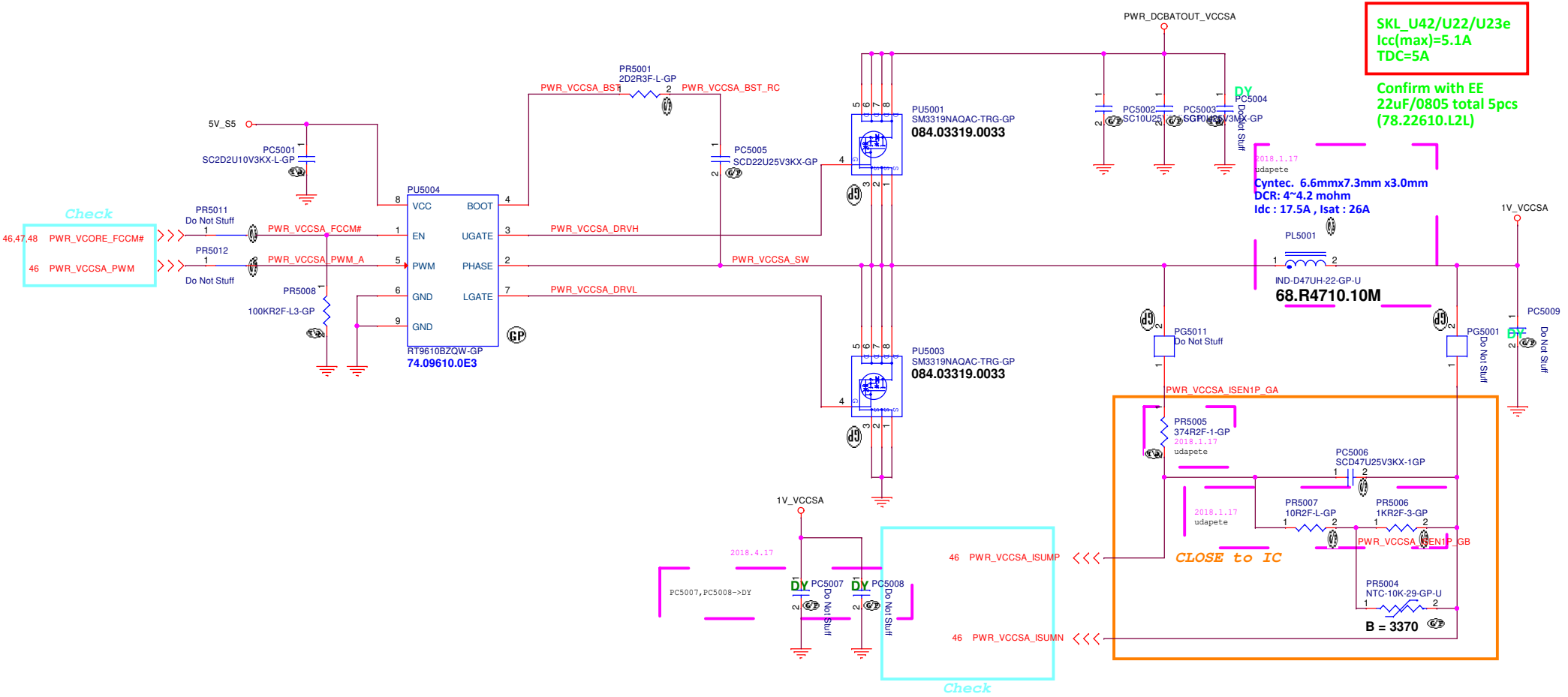


SKL_U42/U22/U23e
 Icc(max)=5.1A
 TDC=5A

Confirm with EE
 22uF/0805 total 5pcs
 (78.22610.L2L)

2018.1.17
 udapete
Cyntec. 6.6mmx7.3mm x3.0mm
 DCR: 4~4.2 mohm
 Idc : 17.5A , Isat : 26A

PL5001
 IND-D47UH-22-GP-U
68.R4710.10M



Check

46.47.48 PWR_VCORE_FCCM#
 46 PWR_VCCSA_PWM

2018.4.17

46 PWR_VCCSA_ISUMP <<<
 46 PWR_VCCSA_ISUMN <<<

Check

CLOSE to IC

PR5005 374R2F-1-GP
 2018.1.17 udapete

PC5006 SCD47U25V3KX-1GP

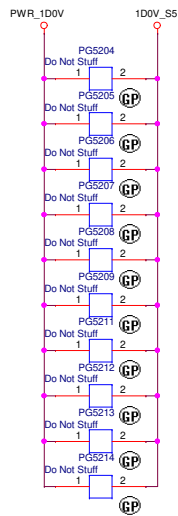
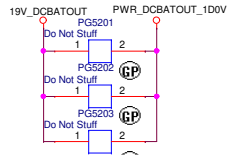
PR5007 10R2F-L-GP
 2018.1.17 udapete

PR5006 1KR2F-3-GP

PWR_VCCSA_ISEN1P_LB

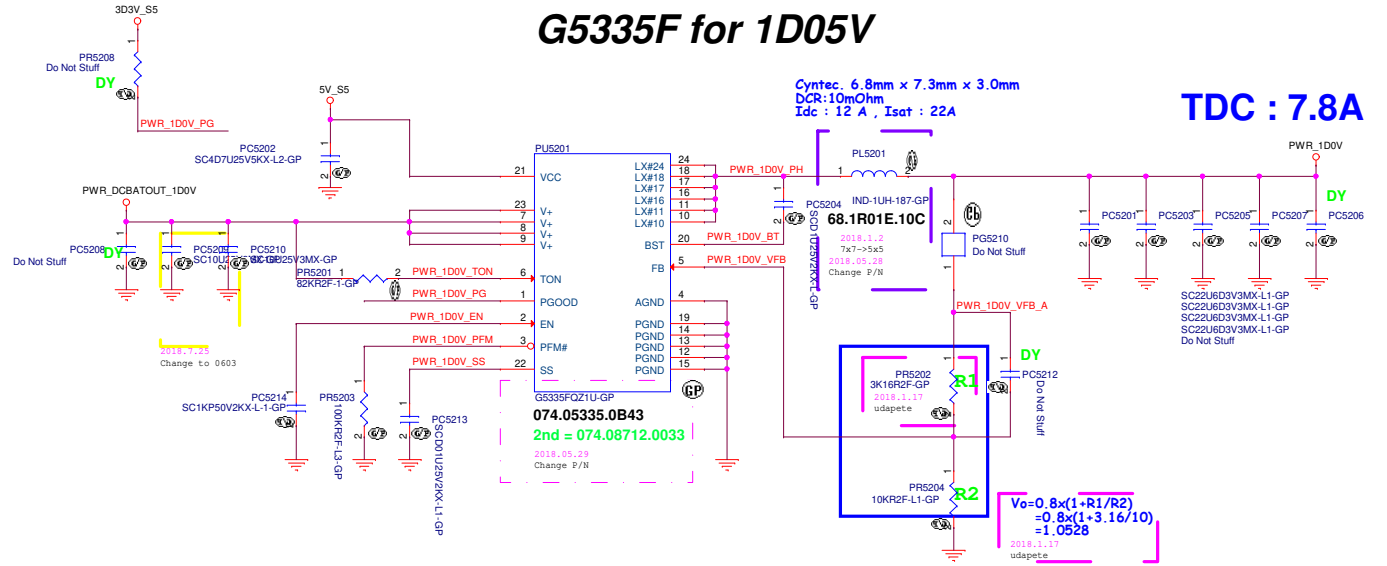
PR5004 NTC-10K-29-GP-U
 B = 3370

OFFPAGE



SSID = PWR.Plane.Regulator_1p0v

G5335F for 1D05V



IC	AOZ2262 (10A)	AOZ2261 (8A)	AOZ2260 (6A)
COM	074.02262.0043	074.02261.0A73	074.02260.0043
Chock	68.1R01A.20B IDC : 10A	68.1R01A.20B IDC : 10A	68.1R01A.20B IDC : 10A
Output CAP	22uF/6.3V * 5pcs DY*1	22uF/6.3V * 4pcs DY*1	22uF/6.3V * 4pcs DY*1

Cyntec. 6.8mm x 7.3mm x 3.0mm
DCR:10mOhm
Idc : 12 A , Isat : 22A

TDC : 7.8A

$$V_o = 0.8 \times (1 + R1/R2) = 0.8 \times (1 + 3.16/10) = 1.0528$$

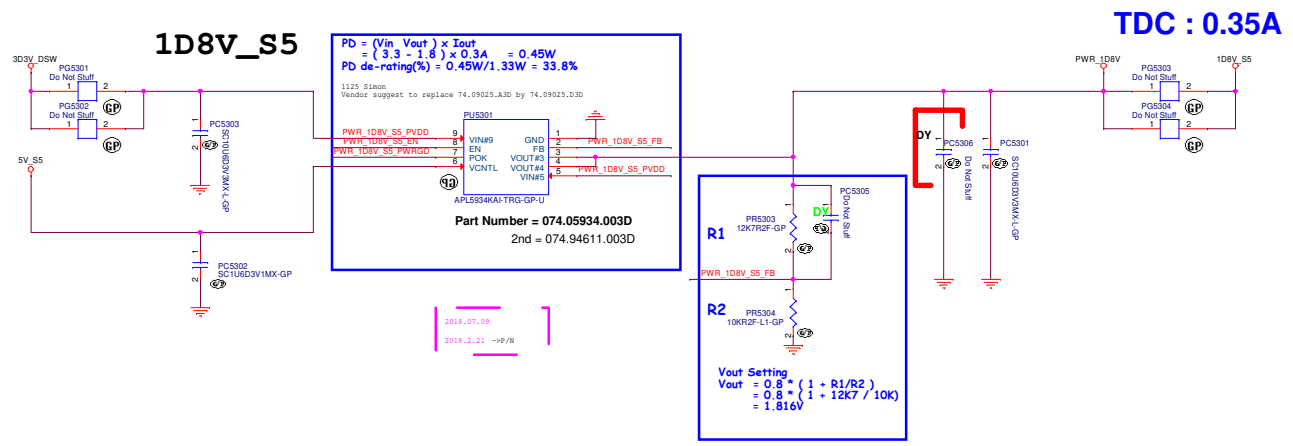
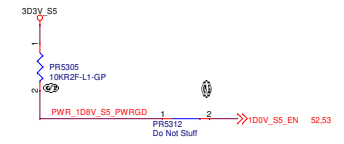
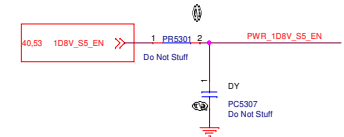
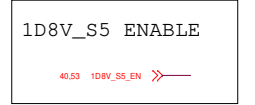
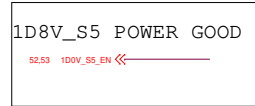
UMA

緯創資通 Wistron Corporation
21F, 9th. Sec.1, Hsien Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title **Power (AOZ2262QL_1D0V)**

Size Customer Document Number **FAROE 14" Pavilion** Rev **SA**

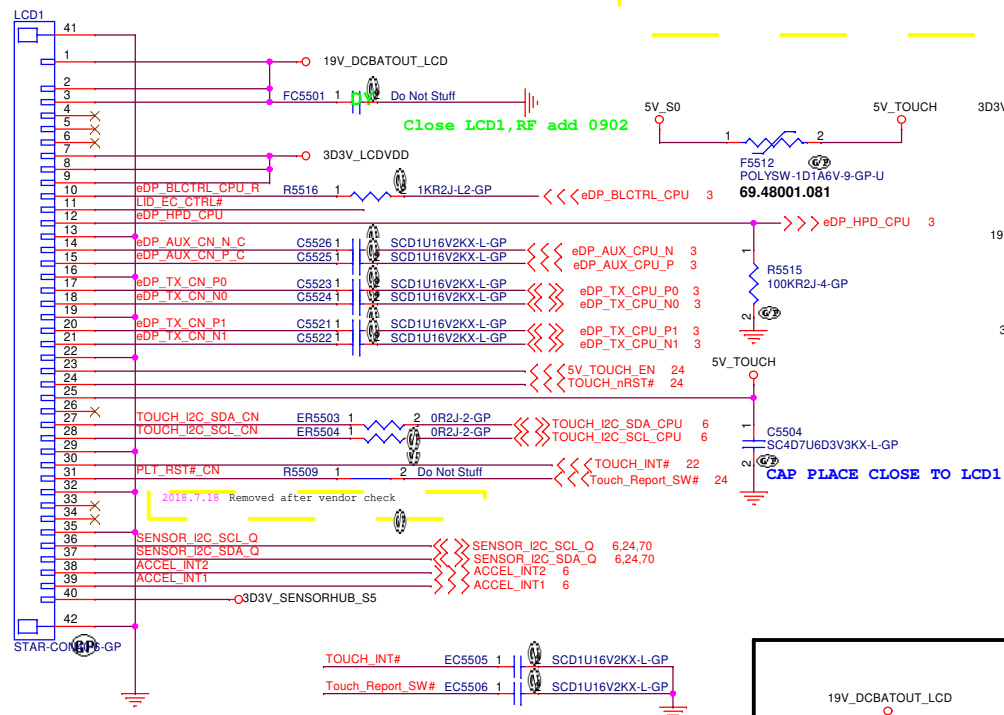
Date: Monday, August 06, 2016 Sheet 52 of 106



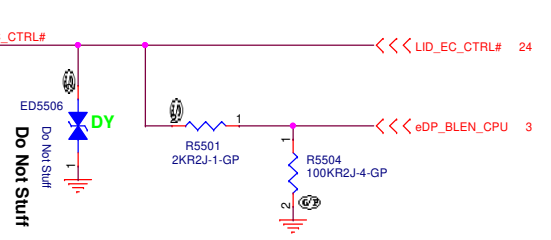
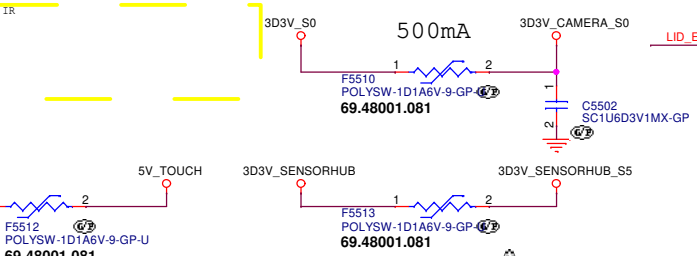
2018.07.09
 2018.2.21 ->R/R

eDP + G-sensor + Touch Connector

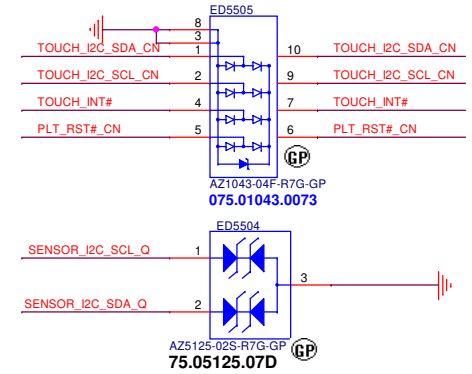
2018.7.19 Removed IR



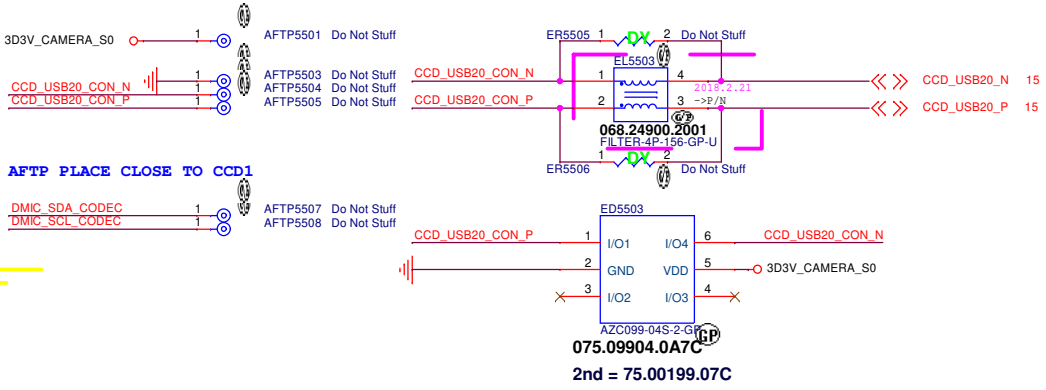
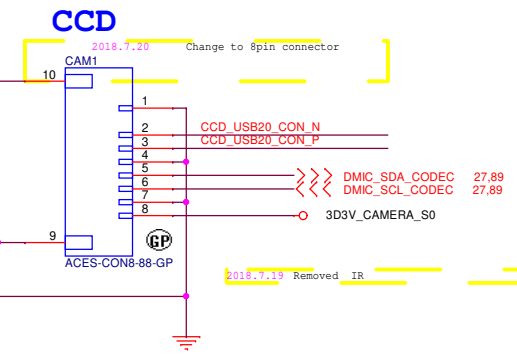
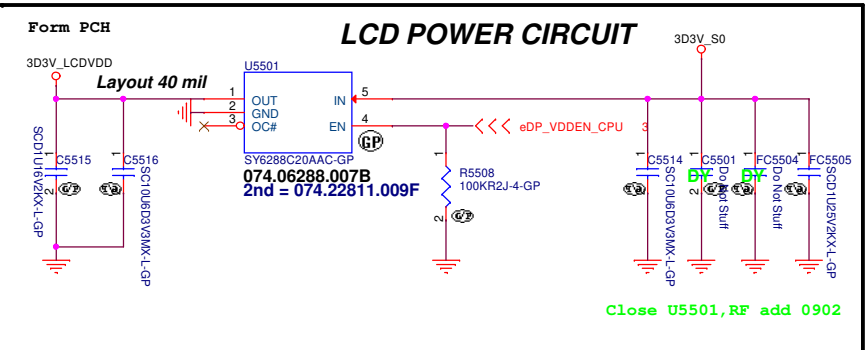
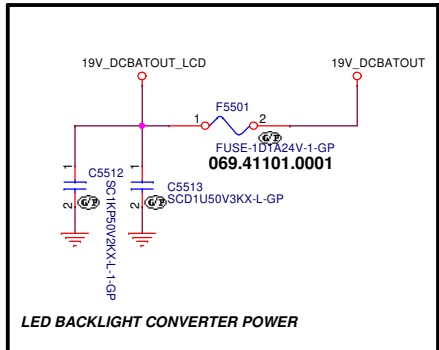
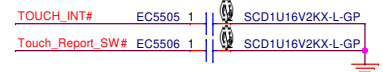
Close LCD1, RF add 0902



- 3D3V_LCDVDD Do Not Stuff
- 19V_DCBATOUT_LCD Do Not Stuff
- eDP_HPD_CPU Do Not Stuff
- LID_EC_CTRL# Do Not Stuff
- eDP_BLCtrl_CPU_R Do Not Stuff
- 5V_TOUCH Do Not Stuff
- 3D3V_SENSORHUB_S5 Do Not Stuff
- TOUCH_INT# Do Not Stuff
- Touch_Report_SW# Do Not Stuff
- TOUCH_nRST# Do Not Stuff
- TOUCH_I2C_SDA_CN Do Not Stuff
- TOUCH_I2C_SCL_CN Do Not Stuff
- SENSOR_I2C_SCL_Q Do Not Stuff
- SENSOR_I2C_SDA_Q Do Not Stuff
- ACCEL_INT2 Do Not Stuff
- ACCEL_INT1 Do Not Stuff



2018.7.20 Delet TOUCH POWER



UMA

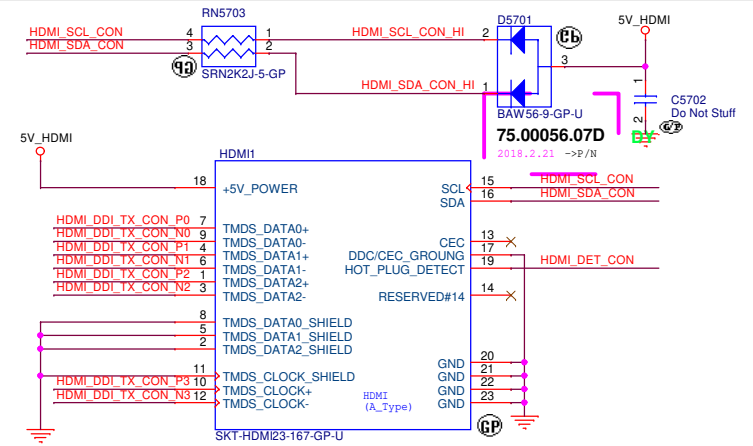
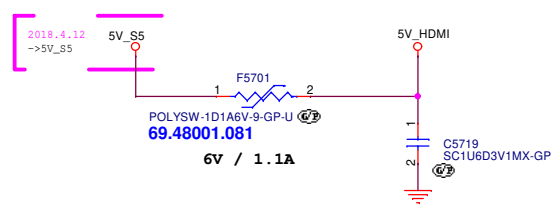
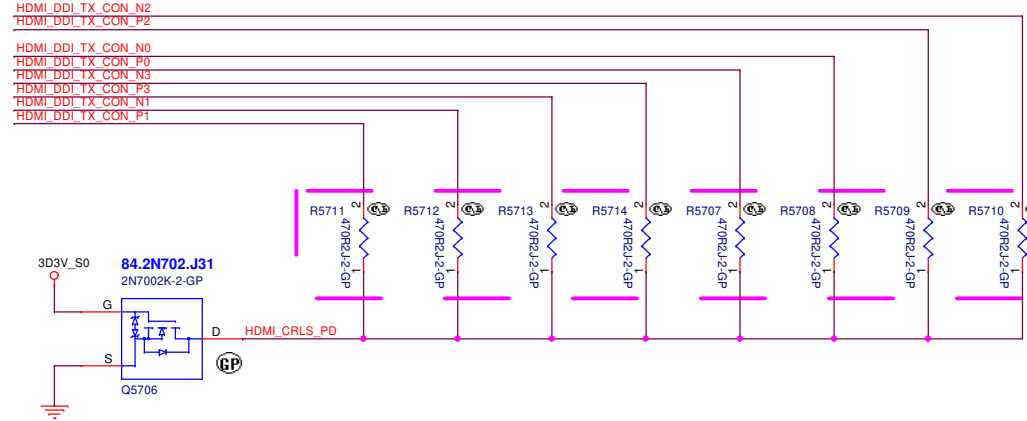
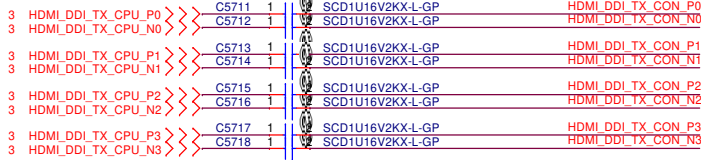
緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **Display (LCD/Inverter)**

Size A3 Document Number: **FAROE 14" Pavilion** Rev SA

Date: Monday, August 06, 2018 Sheet 55 of 106

HDMI PORT



2018.1.16 updated
#575412 PDG rev. 0.7

Figure 5-20. HDMI* Cost-Reduced-Level-Shifter (CRLS) Topology

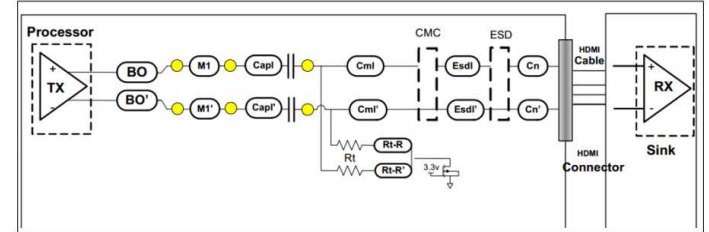


Table 5-26. HDMI* Cost-Reduced-Level-Shifter (CRLS) Topology Guidelines for Max Data rate of 1.65 GT/s

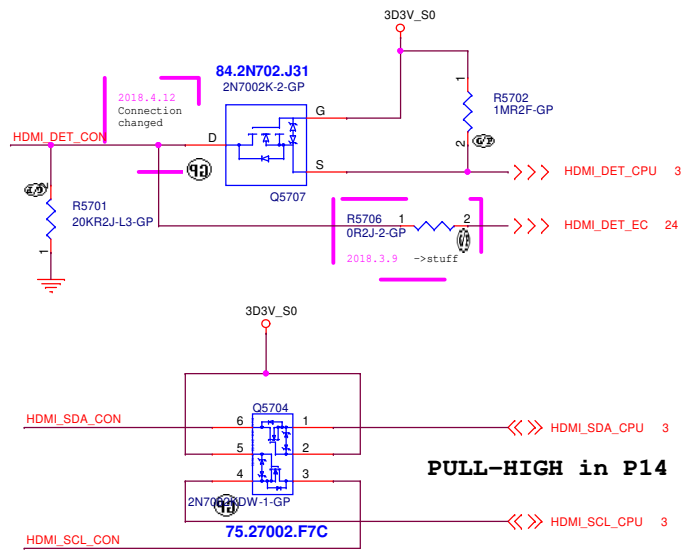
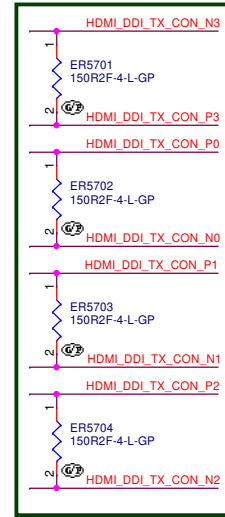
Segment	Stack-up	Via Count ¹	Max Length [mils]	Max Length [mm]
Max Data Rate			1.65 GT/s	2.97 GT/s
B0	MS/SL	Max 3 Vias are allowed.	500	500
M1	MS/SL/DSL		6000	2400
Capl	MS		100	100
Cml	MS		100	100
Esdl	MS		100	100
Cn	MS		300	300
Rt-R	MS		500	100
Total Length			6500	2500

Table 5-26. HDMI* Cost-Reduced-Level-Shifter (CRLS) Topology Guidelines for Max Data rate of 1.65 GT/s

Segment	Stack-up	Via Count ¹	Max Length [mils]	Max Length [mm]
Max Data Rate			1.65 GT/s	2.97 GT/s

Notes:

- CRLS at 2.97 GT/s supports only Stripline stack-up (no microstrip) for B0 and M1 Segments.
- 12 mils PTPS for main route sections
- ESD is recommended. CMC is optional
- Resistor (Rt) Value = 740 ohm +/-5%
- Max nFET Ron = 3 ohm
- The 3.3V supply should be core rail which will turn off in sleep states.

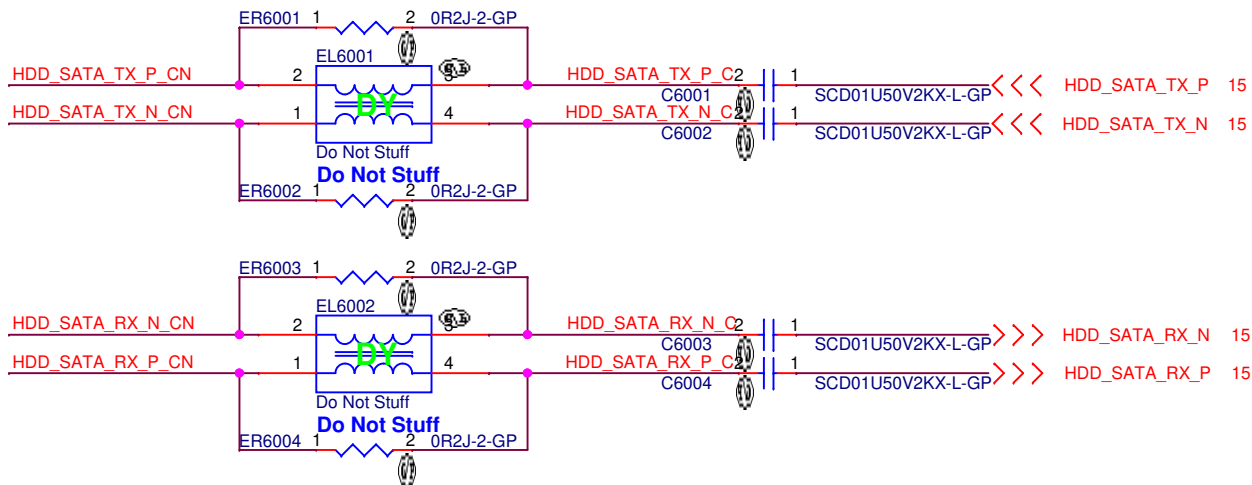
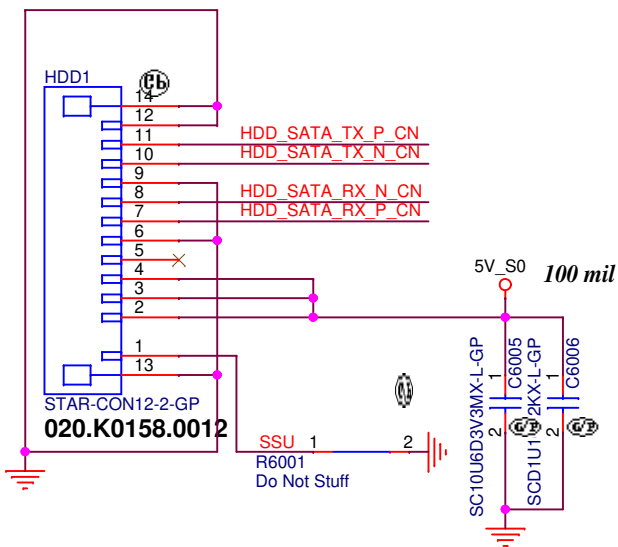


PULL-HIGH in P14

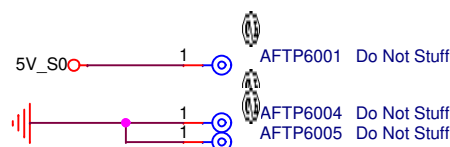
緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: Display (HDMI Level Shifter/Conn)
Size A3 Document Number FAROE 14" Pavilion Rev SA
Date: Monday, August 06, 2018 Sheet 57 of 106

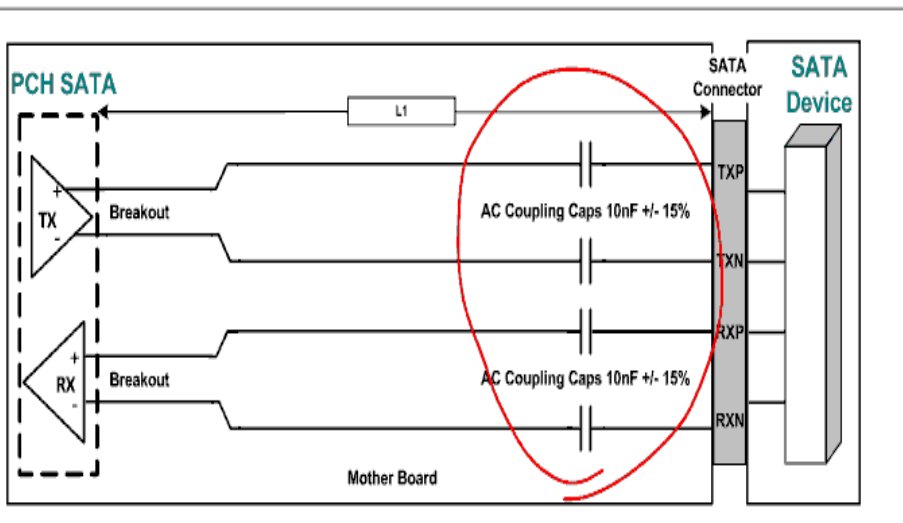
SATA HDD Connector



need check TX/RX mapping



AFTP PLACE CLOSE TO HDD1

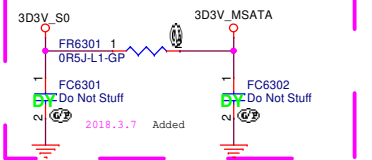


UMA

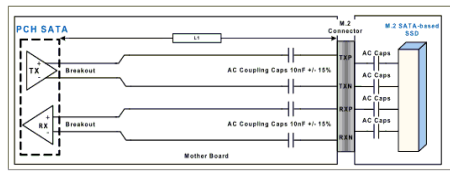
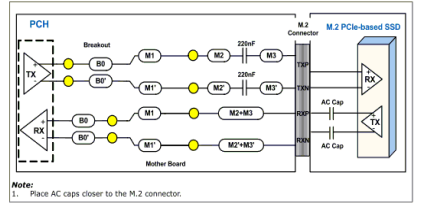
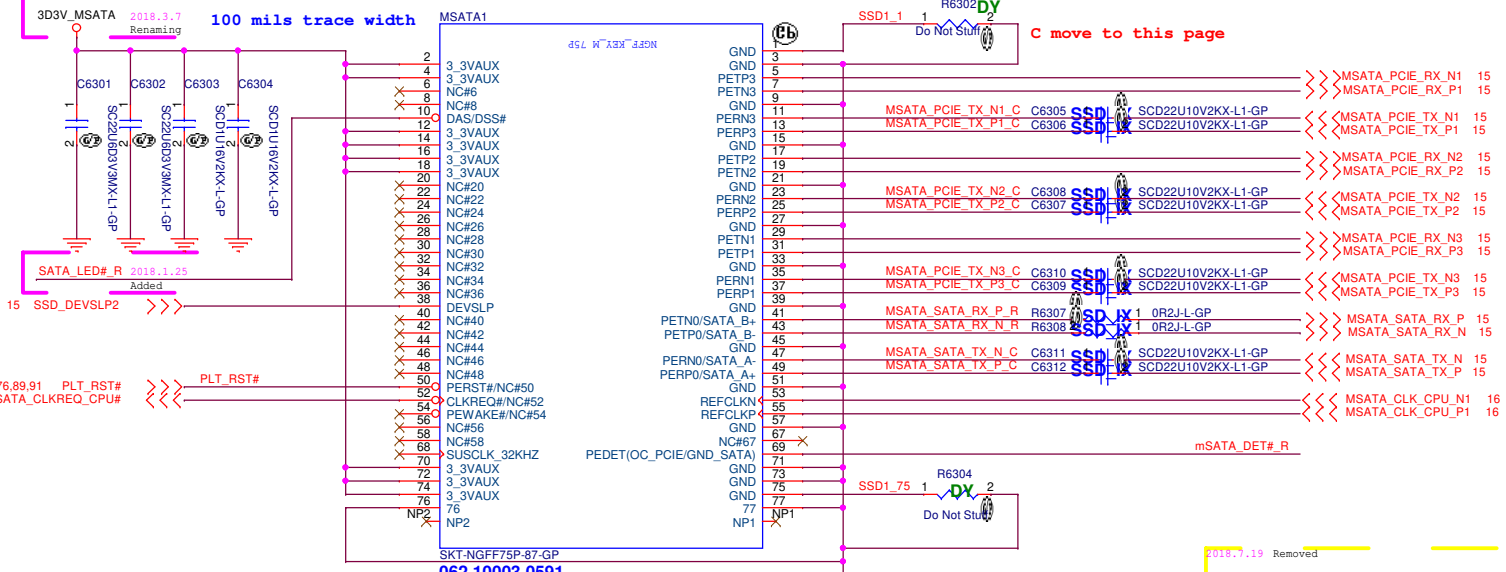
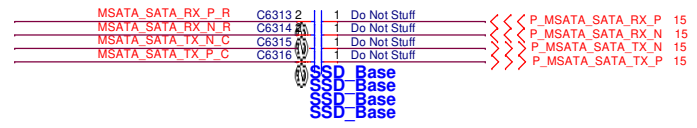
緯創資通 Wistron Corporation
 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title INT IO (HDD/ODD)		
Size A4	Document Number FAROE 14" Pavilion	Rev SA
Date: Monday, August 06, 2018	Sheet 60 of	106

NGFF Connector



SSD slot C key M 2280-S3



20.24.40.61.68.76.89.91 PLT_RST#
16.18 MSATA_CLKREQ_CPU#

PLT_RST#

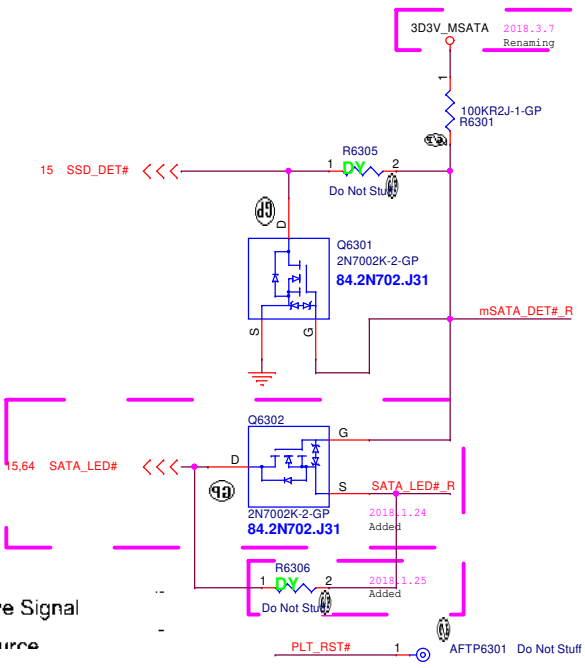
mSATA_DET#_R

2018.7.19 Removed

SSD_DET#	
1	SATA
0	PCIe

20150713 Add Truth Table and modify direction

8 N/C
10 LED1# Device Active Signal
12 3.3V 3.3V source



UMA place close to MSATA1

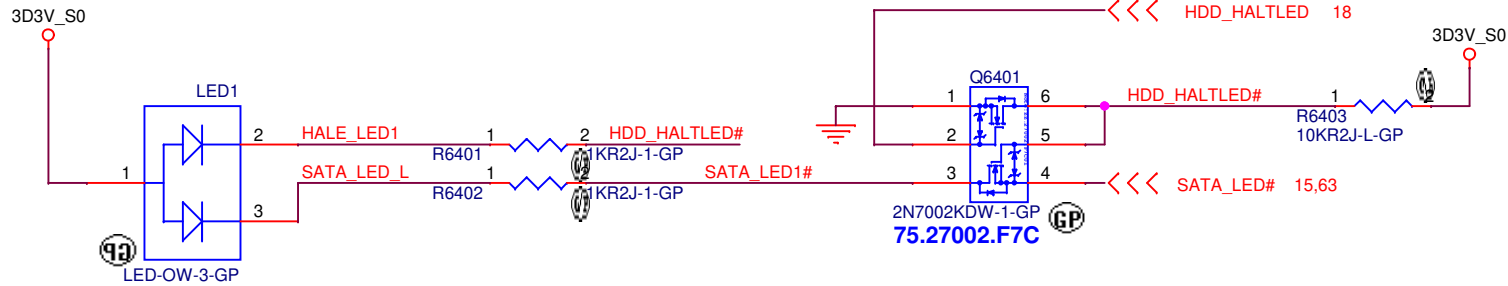
緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: **INT IO (SSD M.2/ eMMC)**

Size A3 Document Number: **FAROE 14" Pavilion** Rev SA

Date: Monday, August 06, 2018 Sheet 63 of 106

HDD LED



Vol Up,Down BTN

UMA

緯創資通 **Wistron Corporation**
 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
 Taipei Hsien 221, Taiwan, R.O.C.

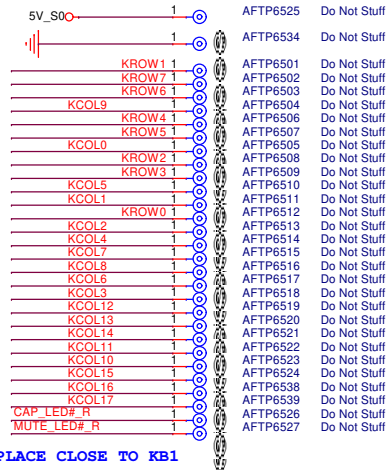
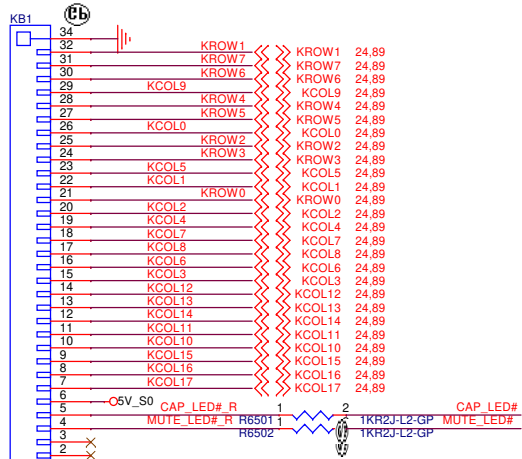
Title **LED / Button / Power Button**

Size A4	Document Number FAROE 14" Pavilion	Rev SA
------------	--	------------------

Date: Monday, August 06, 2018 Sheet 64 of 106

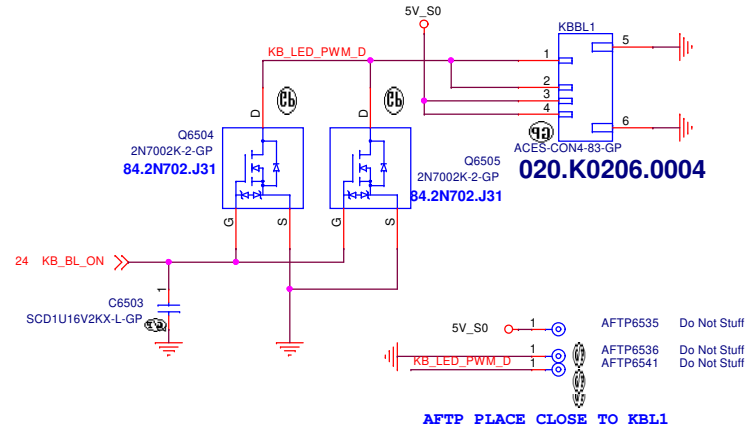
SSID = Key Board CN & TP CN

Key Board conn.



AFTP PLACE CLOSE TO KB1

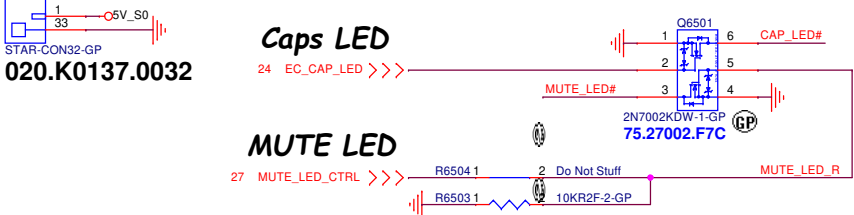
Keyboard backlight conn.



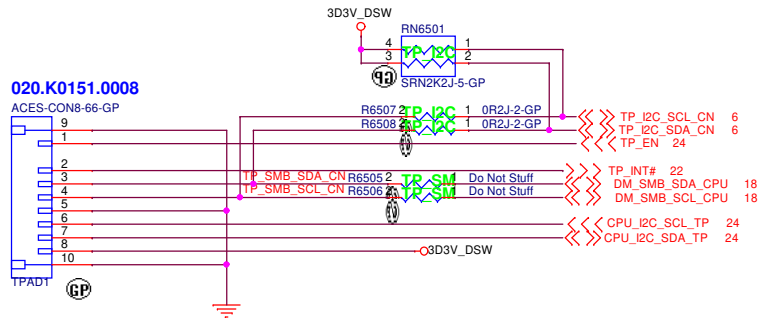
AFTP PLACE CLOSE TO KBL1

Caps LED

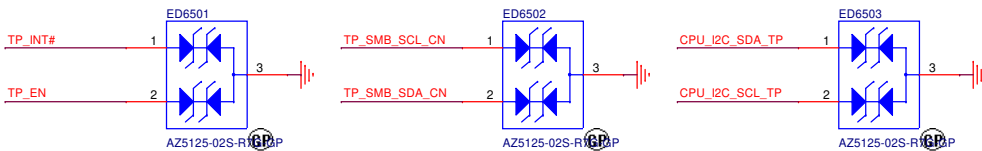
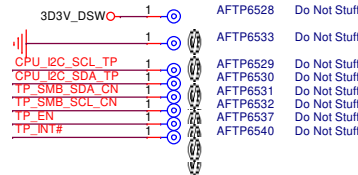
MUTE LED



Touch Pad conn.



AFTP PLACE CLOSE TO TPAD1



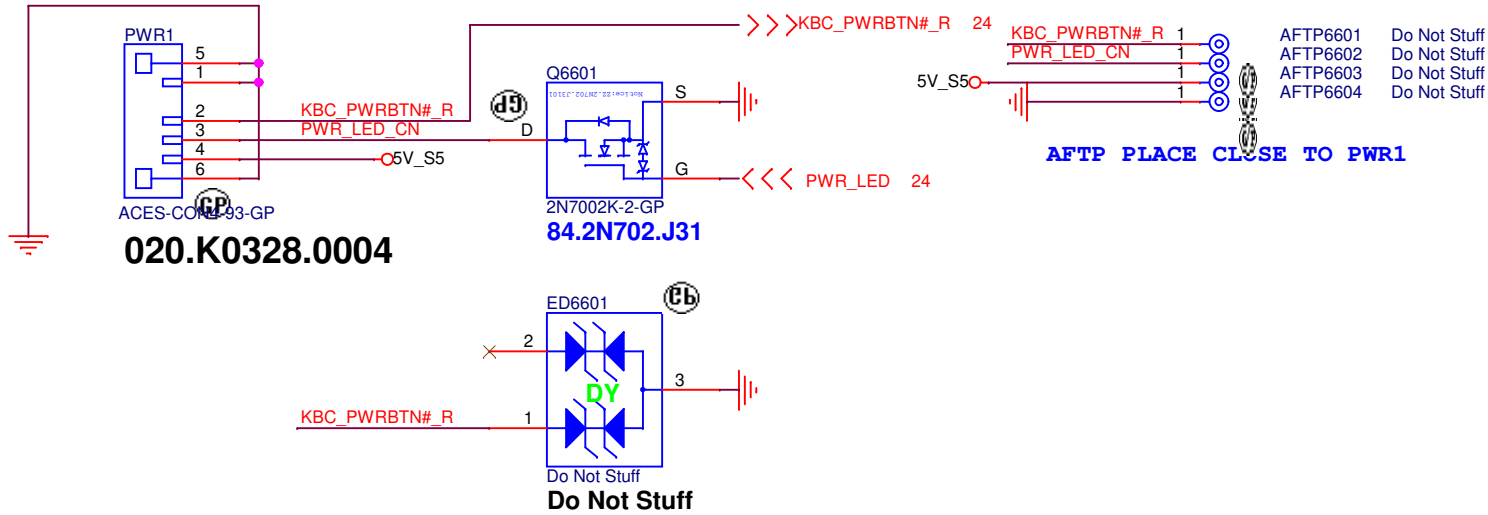
Wistron Confidential document, Anyone can not Duplicate, Modify, Forward or any other purpose application without get Wistron permission

UMA

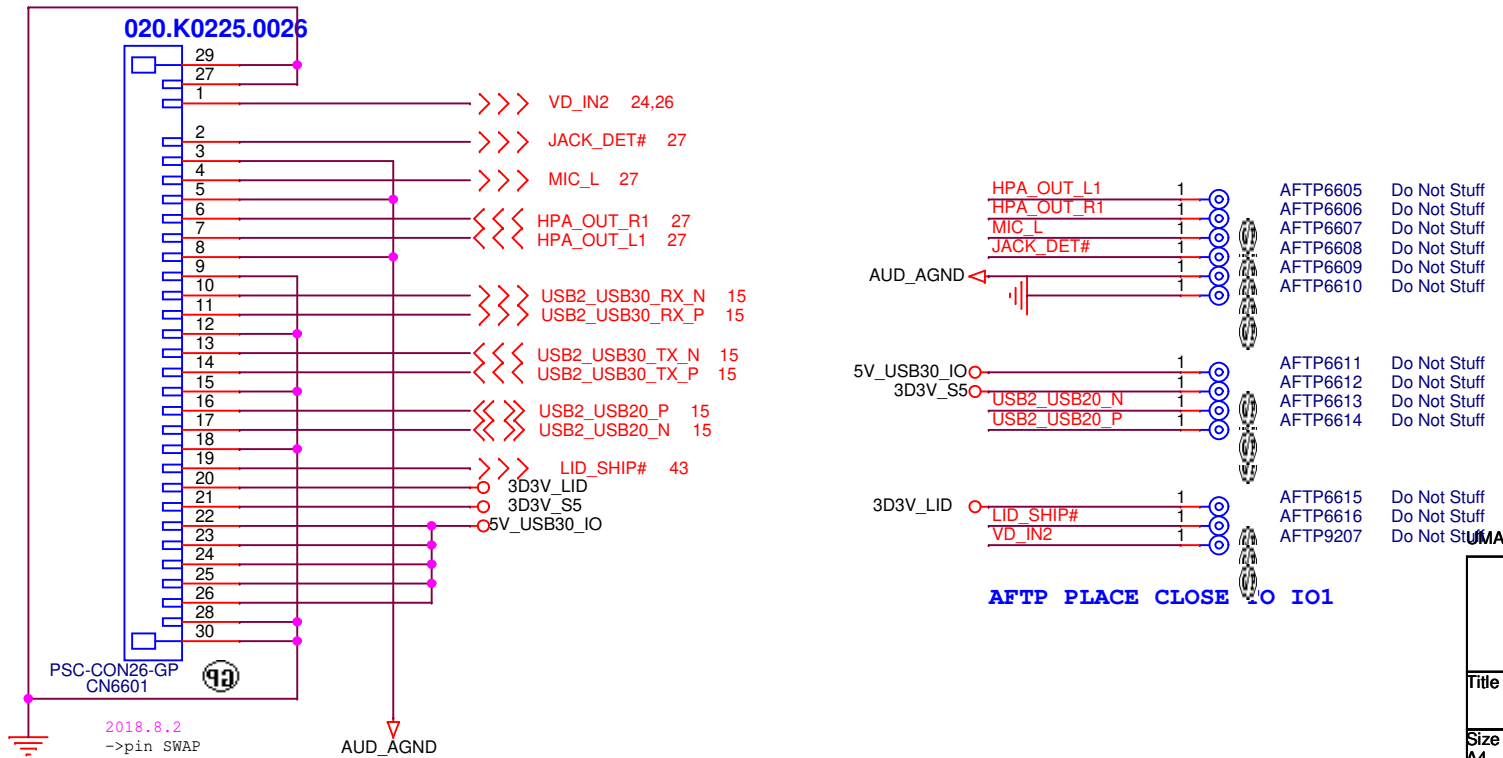
緯創資通 Wistron Corporation
21F, 88, Sec. 1, Hsin Tai Wu Rd., Hstchih, Taipei Hsien 221, Taiwan, R.O.C.

Title		
INT IO (KB/TP)		
Size	Document Number	Rev
A3	FAROE 14" Pavilion	SA
Date:	Monday, August 06, 2018	Sheet 65 of 106

PWBD Conn.



IO Board Conn.

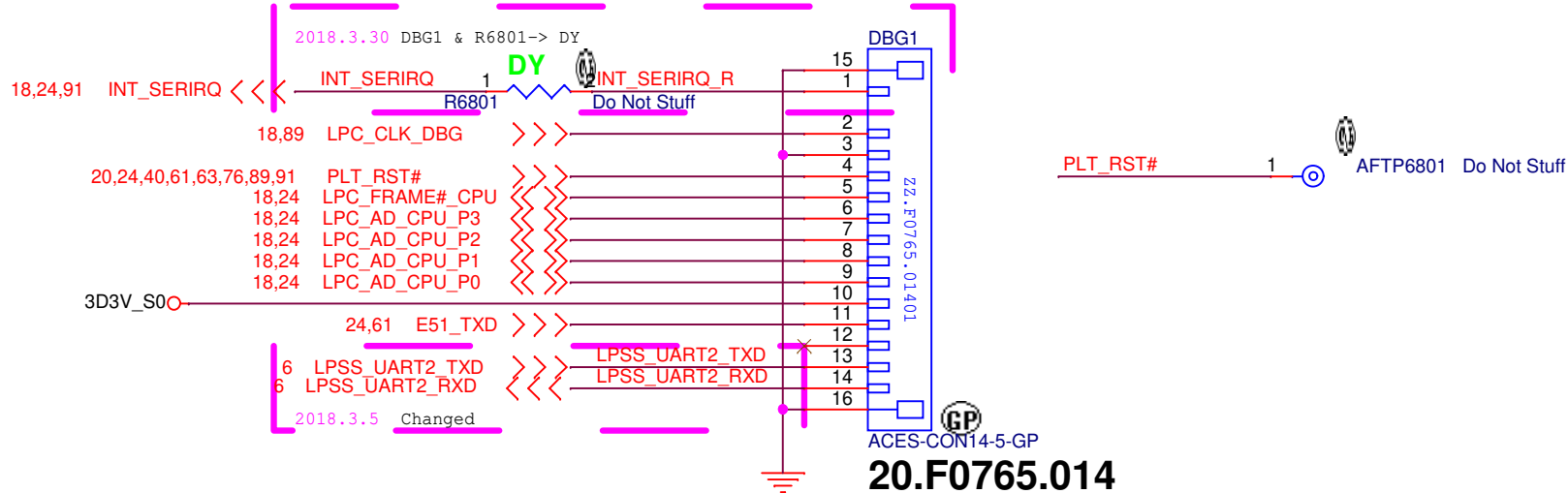
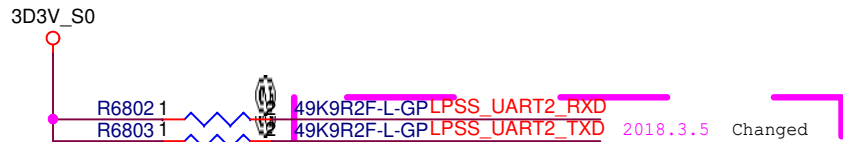


緯創資通 **Wistron Corporation**
 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
 Taipei Hsien 221, Taiwan, R.O.C.

Title **IO Board Conn (USB/AUDIO/CR..etc)**

Size A4 Document Number **FAROE 14" Pavilion** Rev SA

Date: Monday, August 06, 2018 Sheet 66 of 106



20.F0765.014

DB,SI,PV: 20.F0765.014

MV: ZZ.F0765.01401

UMA

緯創資通

Wistron Corporation

21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

Debug (LPC debug)

Size
A

Document Number

FAROE 14" Pavilion

Rev

SA

Date: Monday, August 06, 2018

Sheet 68 of 106

To KBC
for HDD Protect

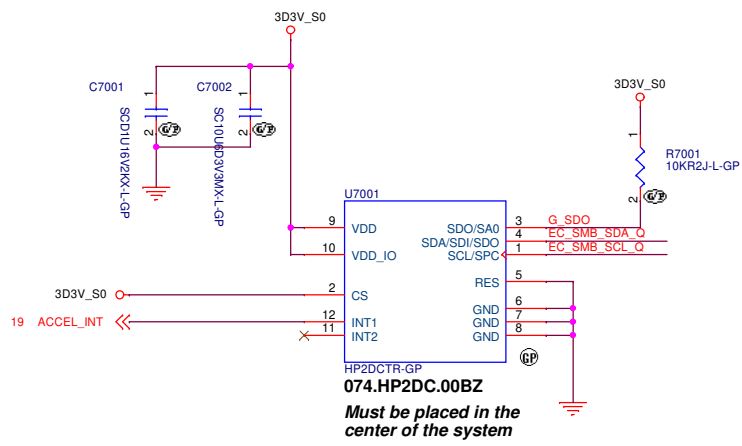
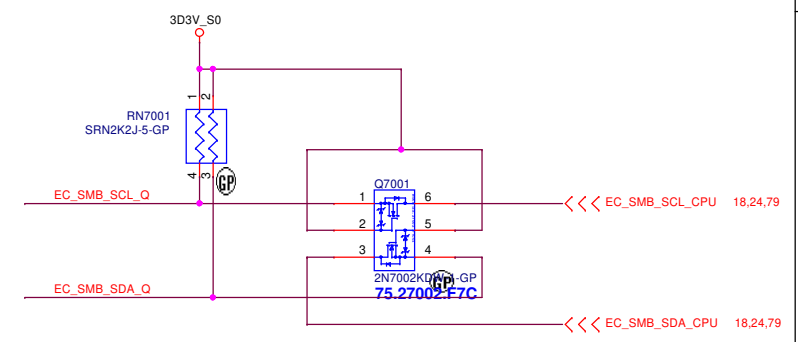


Table 13. SAD+Read/Write patterns

Command	SAD[6:1]	SAD[0] = SA0	R/W	SAD+R/W
Read	010100	0	1	01010001 (51h)
Write	010100	0	0	01010000 (50h)
Read	010100	1	1	01010011 (53h)
Write	010100	1	0	01010010 (52h)



To Sensor HUB
for LCD angle

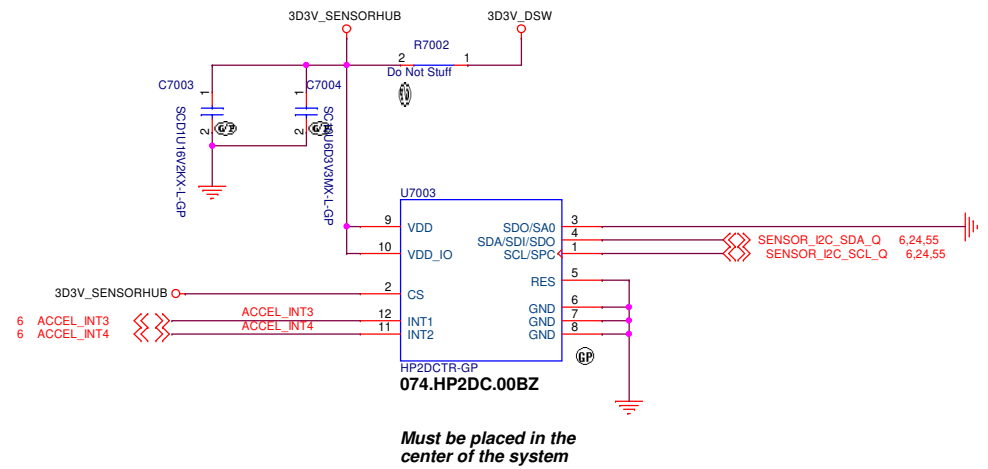
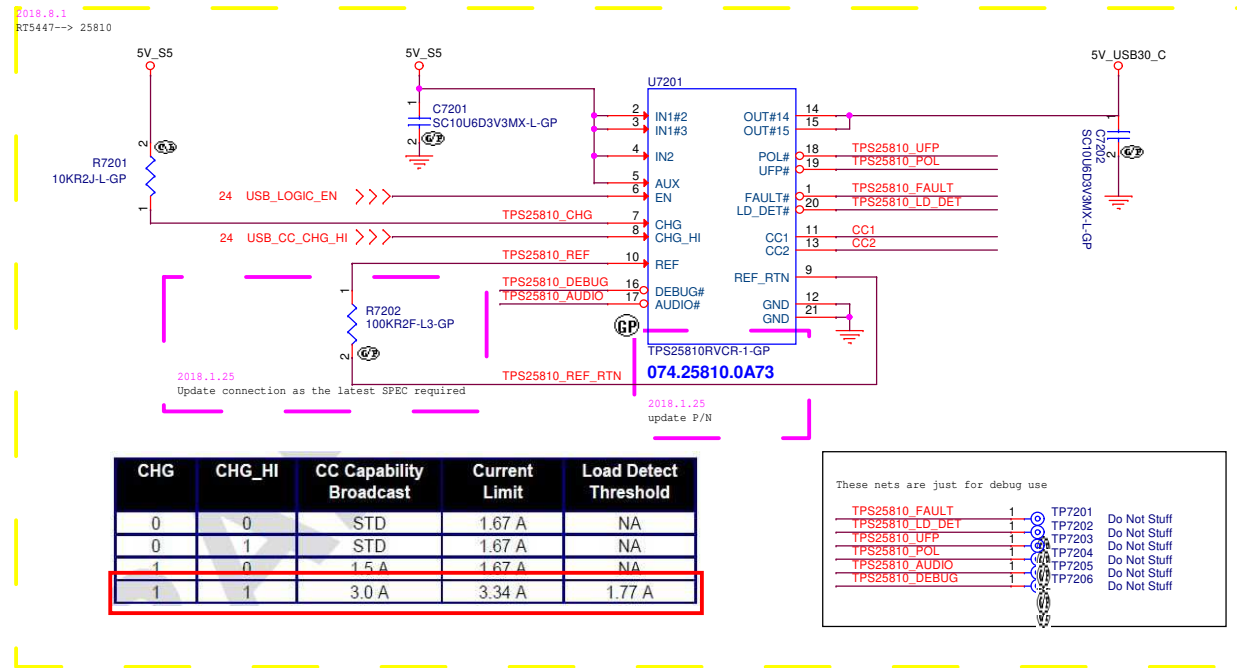


Table 13. SAD+Read/Write patterns

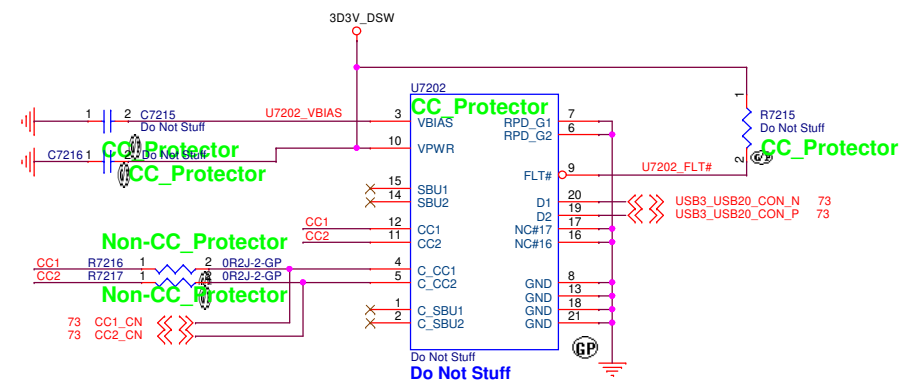
Command	SAD[6:1]	SAD[0] = SA0	R/W	SAD+R/W
Read	010100	0	1	01010001 (51h)
Write	010100	0	0	01010000 (50h)
Read	010100	1	1	01010011 (53h)
Write	010100	1	0	01010010 (52h)

USB 3.0 TYPE C Controller

OUTPUT=3A



USB 3.0 TYPE C Port Protector

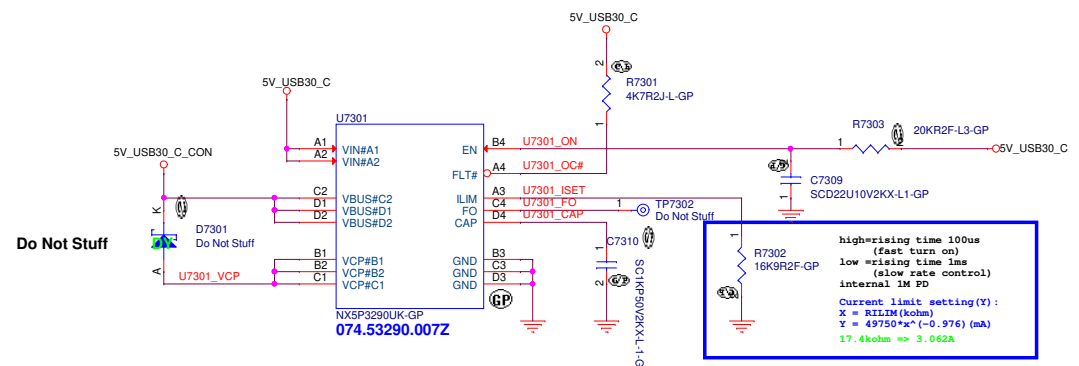
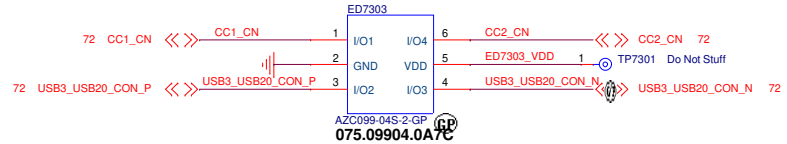
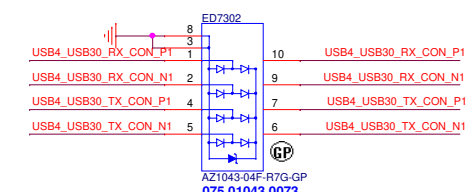
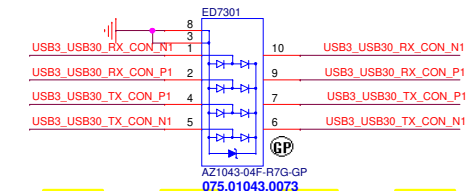
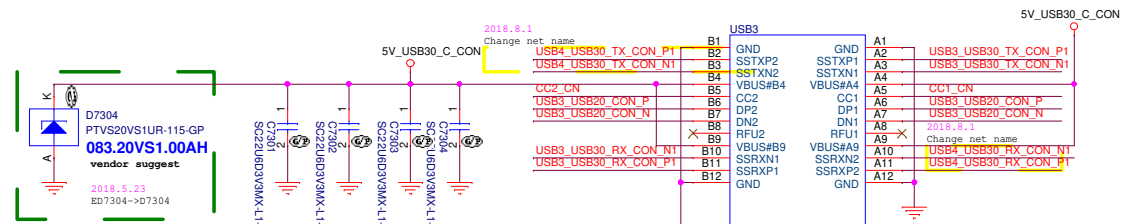
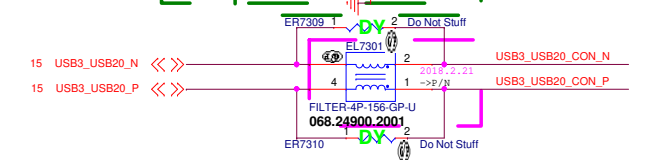
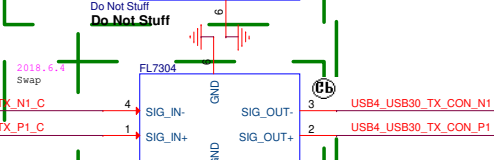
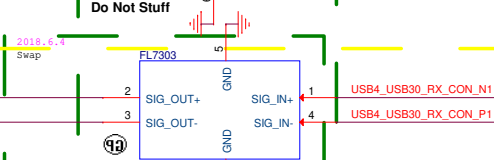
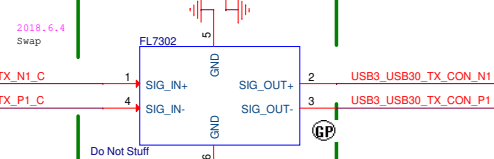
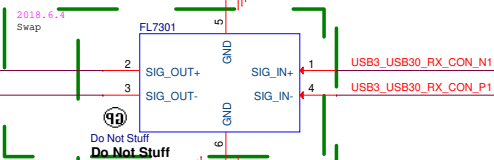


USB Type C Connector

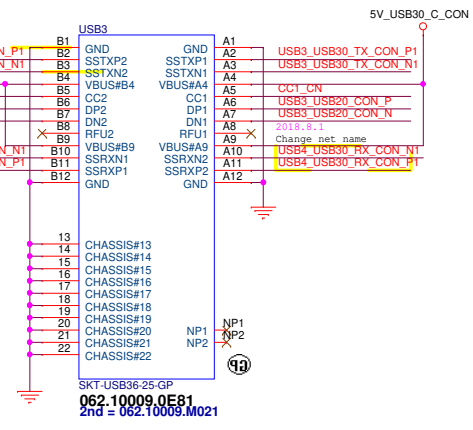
OUTPUT=3A

PV: 66.R0036.B4L

2018.5.23
FL7301~FL7304~XP/N
ER7301~ER7308->xremove



high-rising time 100us (fast turn on)
low =rising time 1ms (slow rate control)
internal 1M PD
Current limit setting(Y):
X = RILIM(kohm)
Y = 49750*x*(-0.976) (mA)
17.4kohm => 3.062A



Wistron Confidential document, Anyone can not reproduce, Modify, Forward or any other purpose application without get Wistron permission

UMA

緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title: EXT IO (Type C Conn)

Size: Document Number FAROE 14" Pavilion Rev SA

Date: Monday, August 06, 2018 Sheet 73 of 106

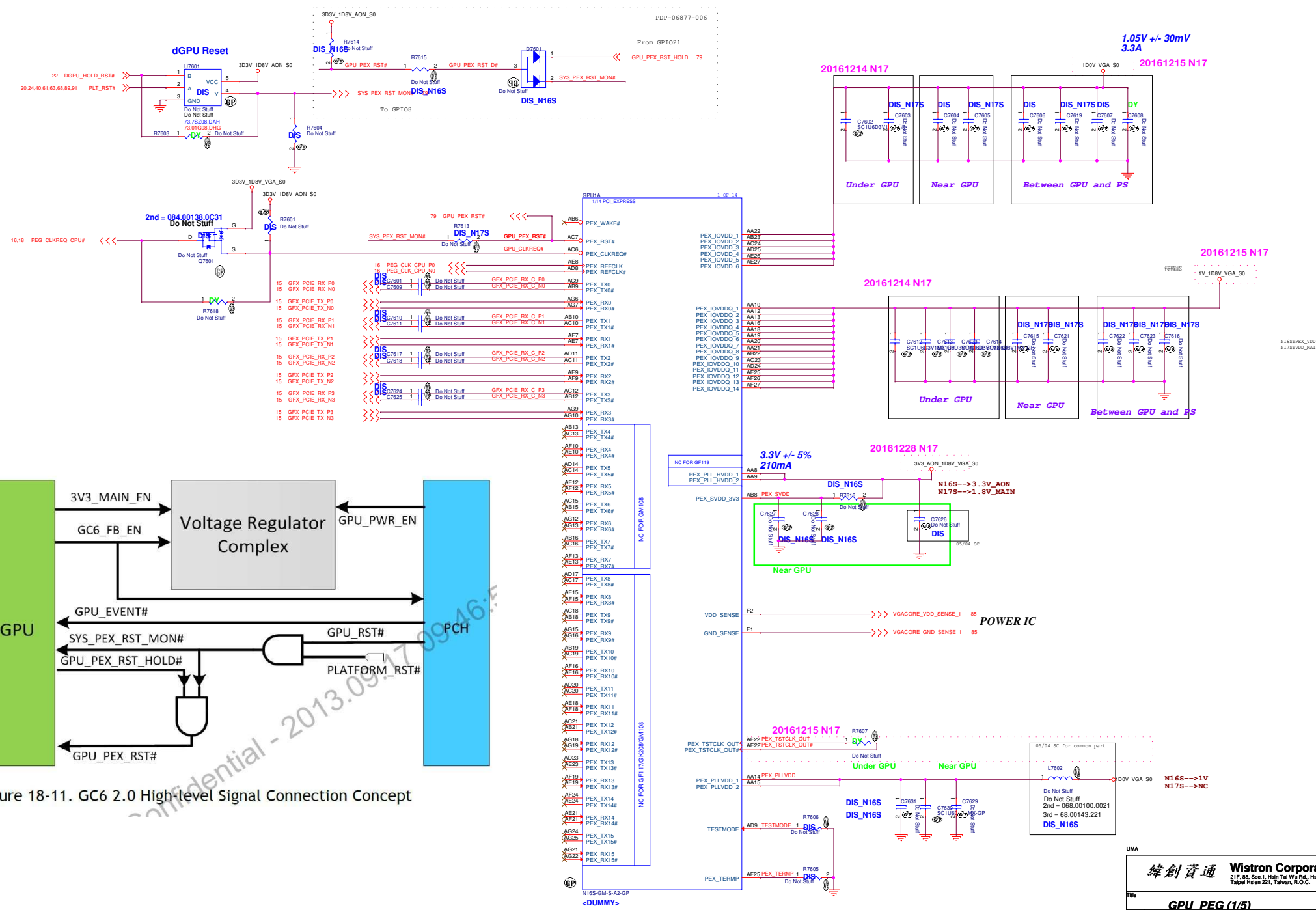
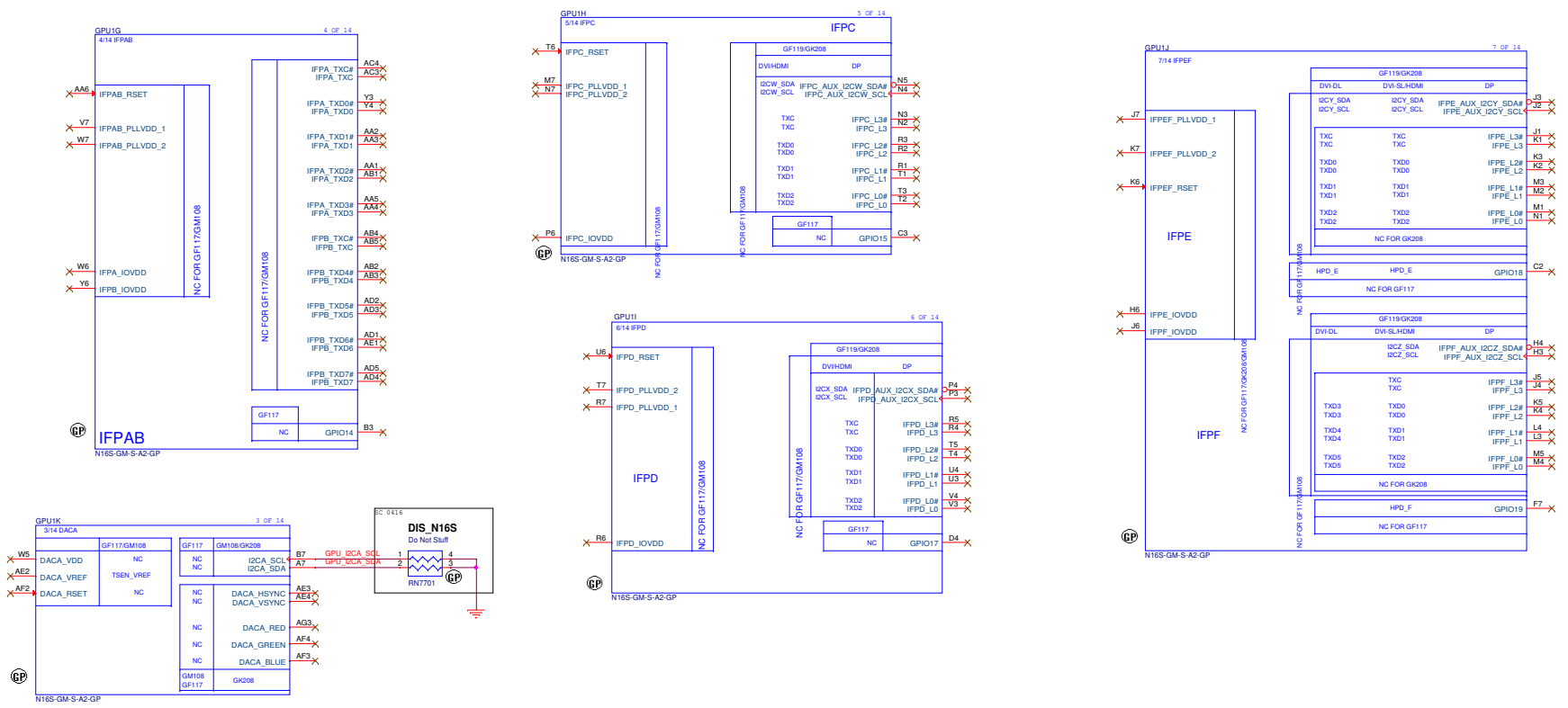


Figure 18-11. GC6 2.0 High-level Signal Connection Concept

Main Func = dGPU



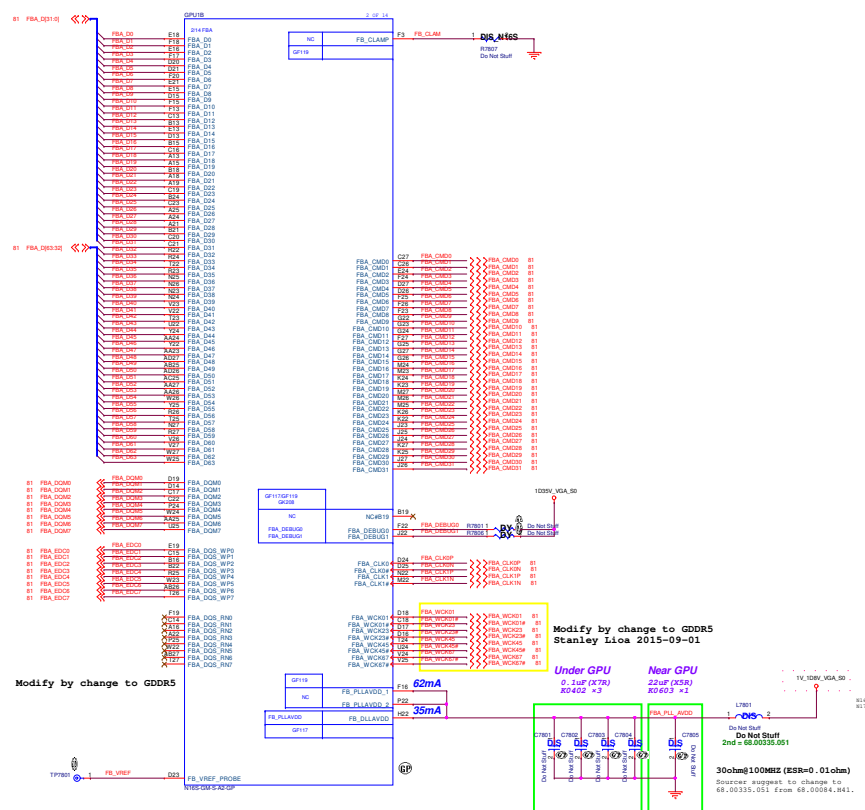
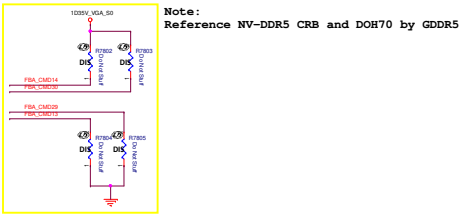
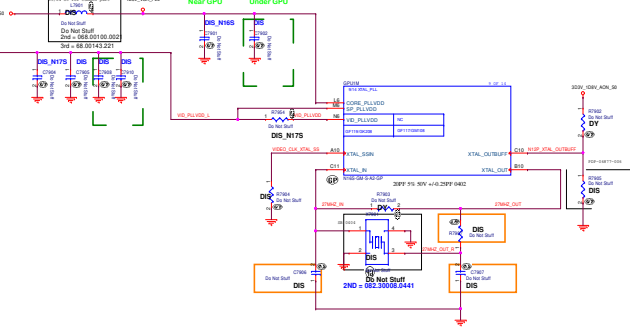
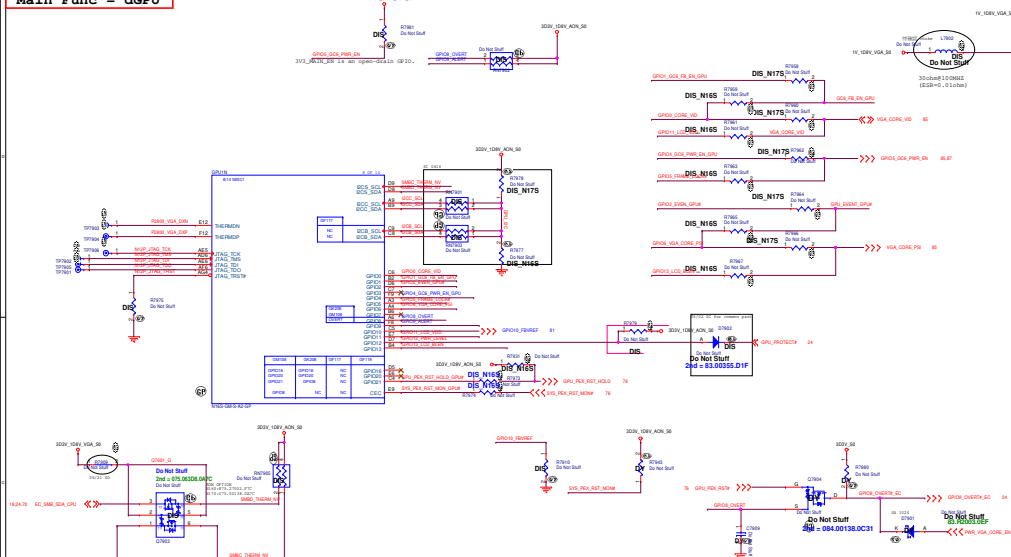


Table 5. Frame Buffer PLLs Decoupling and Filtering

GPU	Capacitor Type	Footprint	Population		Location
			N16	N17	
FB PLL Supply Rail for GDDR5					
GB2B-64,	0.1 μF X7R	0402	2	4	Under GPU
GB2C-64	22 μF X6S	0805	1	1	Near GPU
Bead Type					
	30 Ω (ESR=0.010 Ω)	0603	1		Near GPU





Memory Density	Allowed Memory Configuration	FBVDD/Q	Vendor	Manufacturer Part Number	Die Revision	Strap	Memory Speed Grade (MHz)	Date Code Alert	Qual Plan	Status
8 Gb	256Mx32 512Mx16	1.35V	Samsung	K4G80325FB-HC28	B-die	0x0	3250	N/A	Full	Substitution allowed with waiver?
			Hynix	H5GC8H24MJR-R2C	M-die	0x5	3000	N/A	Full	Post production ready
			Hynix	H5GC8H24MJR-R4C	M-die	0x5	3000	N/A	Full	Substitution allowed with waiver?
			Micron	MTS1J256M32HF-60A	A-die	0x1	2500	N/A	Full	Production ready
			Micron	MTS1J256M32HF-70A	A-die	0x1	3000	N/A	Full	Substitution allowed with waiver?
			Micron	MTS1J256M32HF-80A	A-die	0x1	3000	N/A	Full	Substitution allowed with waiver?
			Micron	MTS1J256M32HF-70B	B-die	0x8	3000	N/A	Full	Post production ready
			Micron	MTS1J256M32HF-80B	B-die	0x8	3000	N/A	Full	Substitution allowed with waiver?
			Hynix	H5GC8H24AJR-R2C	A-die	0x9	3000	N/A	Full	Post production ready
			Hynix	H5GC8H24AJR-R4C	A-die	0x9	3000	N/A	Full	Substitution allowed with waiver?

Memory Type	FBVDD/FBVDDQ	Memory Density	Vendor	Manufacturer Part Number	Die Revision	Strap	Memory Speed Grade (MHz)	Memory Date Code Minimum	Status
256Mx32			Samsung	K4G80325FB-HC25	B-die	0x0	3250	N/A	Substitution allowed with waiver?
			Hynix	H5GC8H24MJR-12L	M-die	0x5	2500	N/A	Post production ready
			Hynix	H5GC8H24MJR-R4C	M-die	0x5	3000	N/A	Substitution allowed with waiver?
			Hynix	H5GC8H24MJR-R4C	M-die	0x5	3000	N/A	Substitution allowed with waiver?
			Micron	MTS1J256M32HF-60A	A-die	0x1	2500	N/A	Production ready
			Micron	MTS1J256M32HF-70A	A-die	0x1	3000	N/A	Substitution allowed with waiver?
			Micron	MTS1J256M32HF-80A	A-die	0x1	3000	N/A	Substitution allowed with waiver?
			Micron	MTS1J256M32HF-70B	B-die	0x8	3000	N/A	Post production ready
			Micron	MTS1J256M32HF-80B	B-die	0x8	3000	N/A	Substitution allowed with waiver?
			Hynix	H5GC8H24AJR-R2C	A-die	0x9	3000	N/A	Post production ready
512Mx16			Samsung	K4G80325FB-HC03	B-die	0x0	2500	N/A	Production ready
			Samsung	K4G80325FB-HC28	B-die	0x0	3000	N/A	Substitution allowed with waiver?
			Samsung	K4G80325FB-HC25	B-die	0x0	3250	N/A	Substitution allowed with waiver?
5									

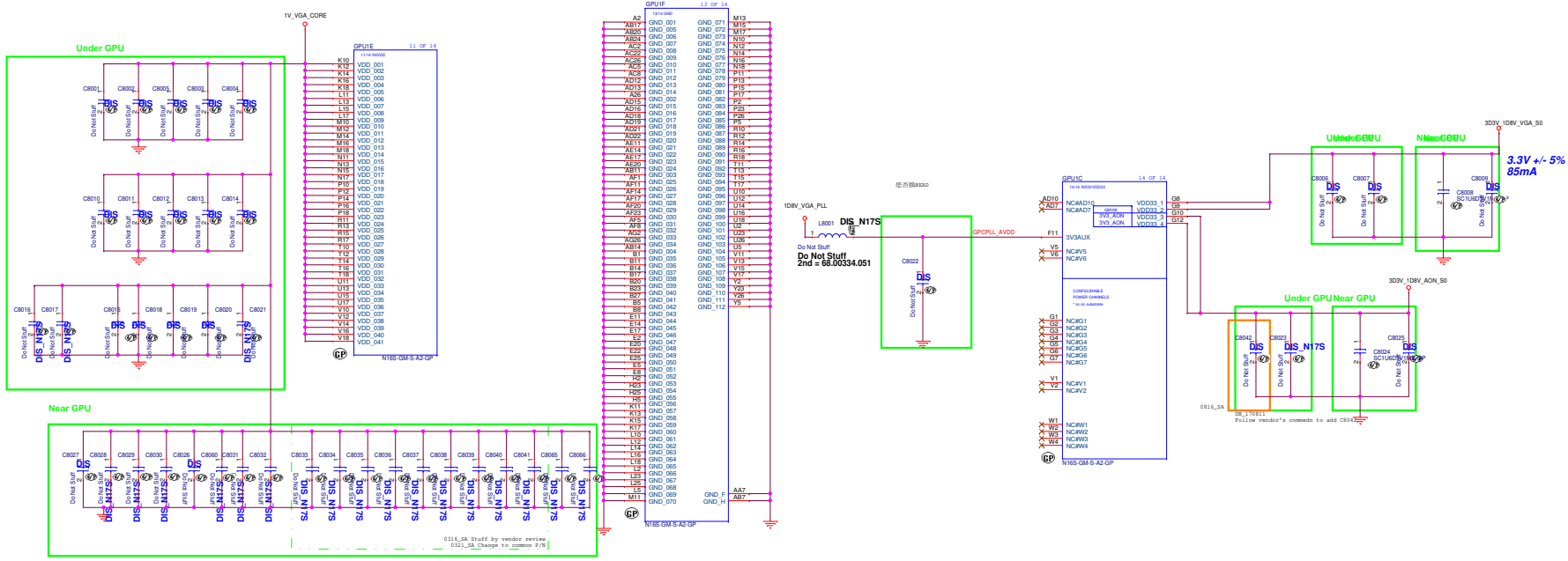


Table 3. NVDD Decoupling and Filtering

GPU	Capacitor Type	Footprint	Population		Location
			N16	N17	
NVDD Supply Net					
GB2B-64, GB2C-64	4.7 μ F	X6S 0603	10	12	Under GPU
	1 μ F	X6S 0402	4	5	Under GPU
	47 μ F	X5R 0805	1	-	Near GPU
	10 μ F	X7R 0805	-	11	Near GPU
	22 μ F	X5R 0805	1	4	Near GPU
	4.7 μ F	X5R 0805	1	4	Near GPU
	330 μ F	POS 7343	1	2	Near GPU

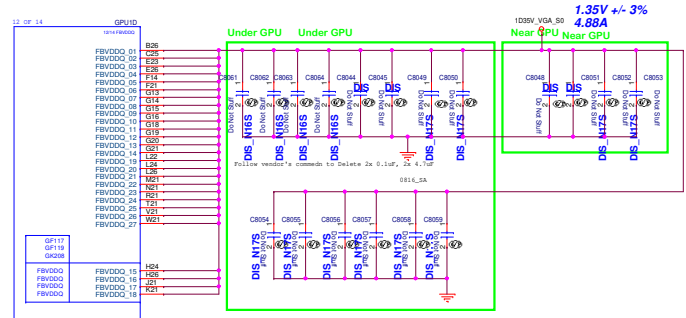
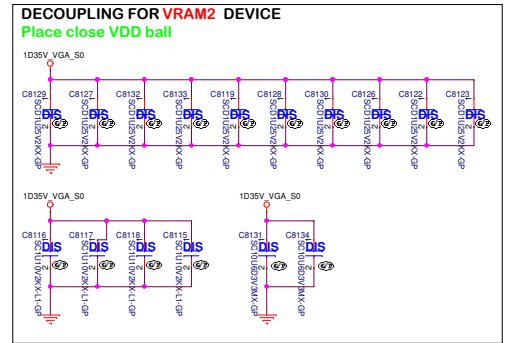
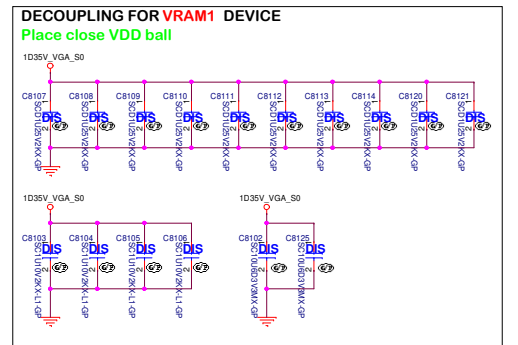
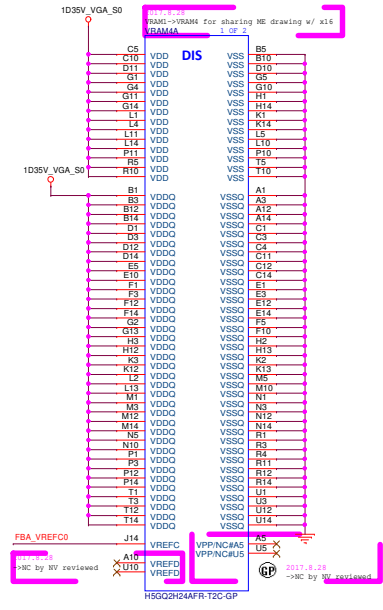
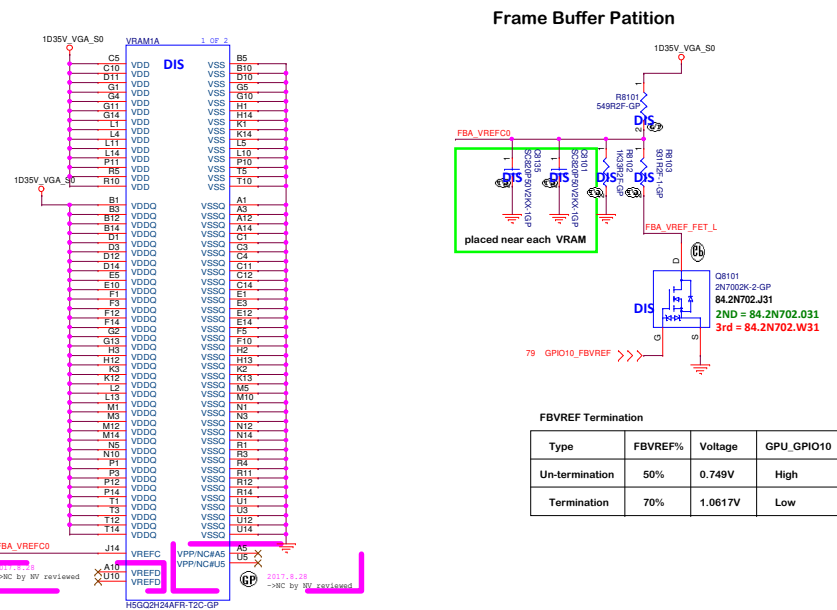


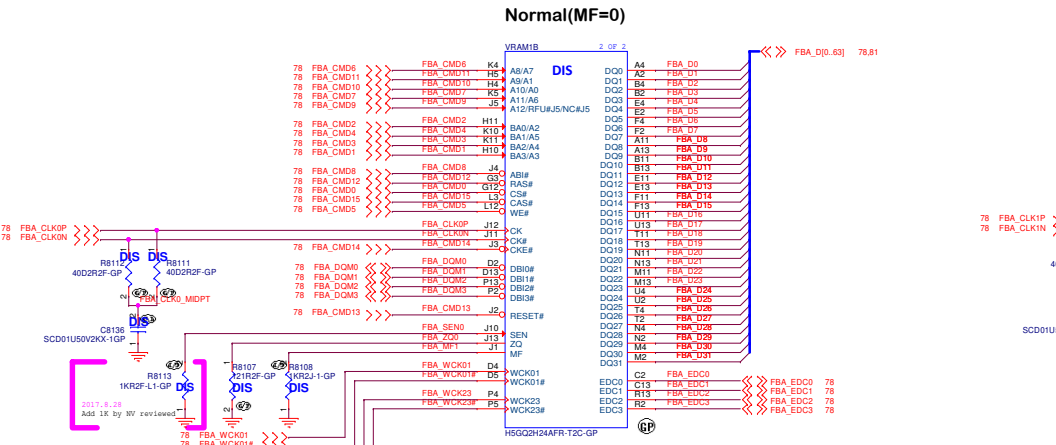
Table 4. Frame Buffer Core and IO Decoupling and Filtering

GPU	Capacitor Type	Footprint	Population		Location
			N16	N17	
FBVDD/Q Supply Rail for GDDR5					
GB2B-64, GB2C-64	0.1 μ F	X7R 0402	2	2	Under GPU
	1 μ F	X7R 0603	2	8	Under GPU
	4.7 μ F	X6S 0603	2	0	Under GPU
	10 μ F	X6S 0603	0	2	Under GPU
	10 μ F	X6S 0603	1	1	Near GPU
	22 μ F	X6S 0603W	1	3	Near GPU

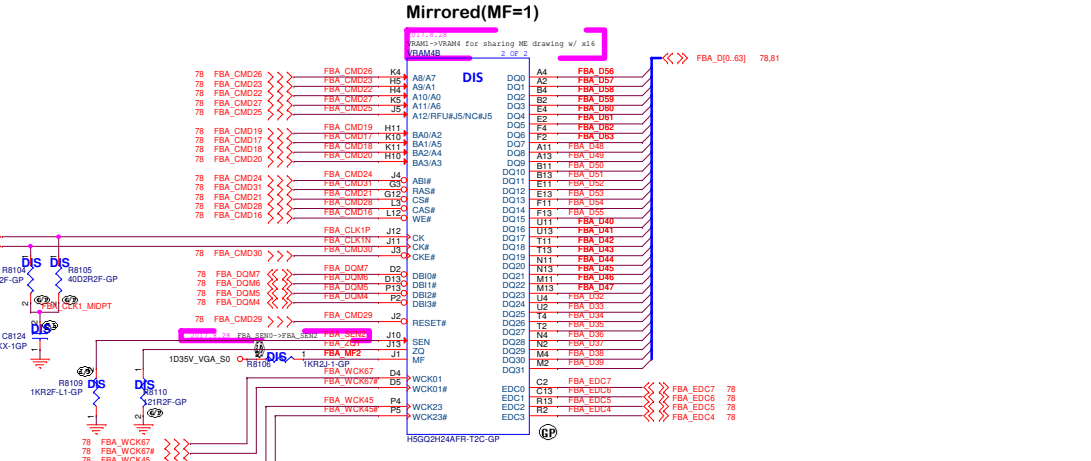




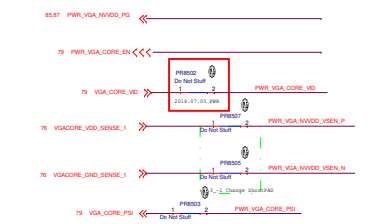
Frame Buffer Partition 0..31



Frame Buffer Partition 32..63



Main Func = dGFX_CORE



need EE Check

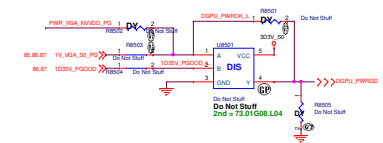
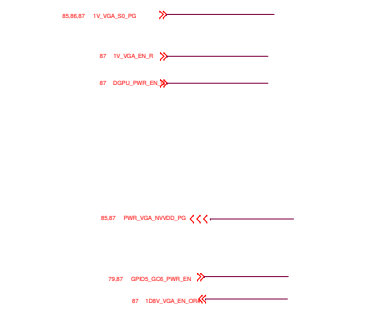


Table 1
Operation Phase Number PSI Voltage Setting

1phase with DEM	0V to 0.4V
1phase with CCM	0.7V to 0.88V
2phase with CCM	1.08V to 1.35V
2phase with CCM	1.6V to 5.5V

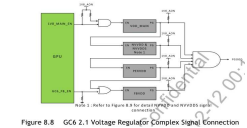
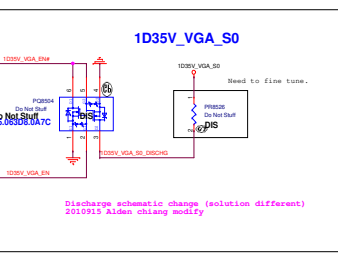
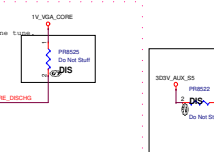
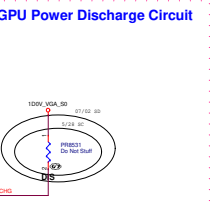
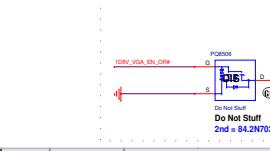
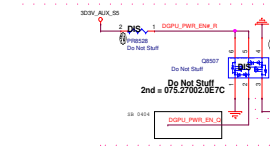
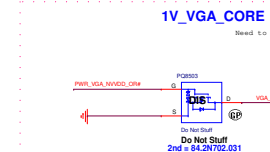
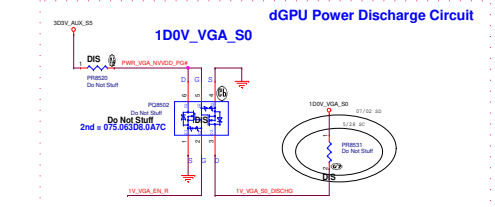
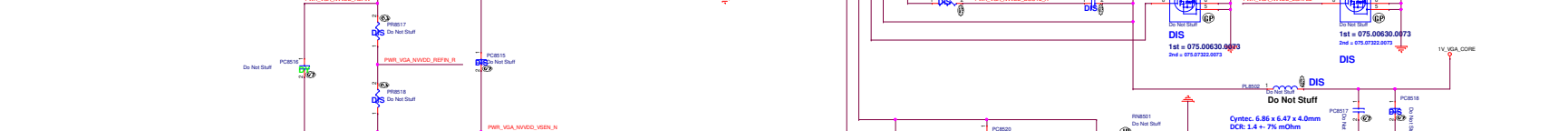
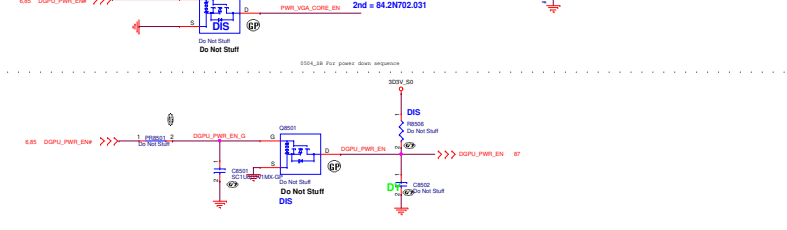
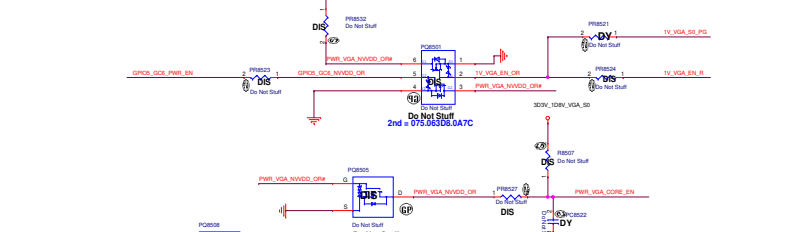


Figure 8.8 GC6.2.1 Voltage Regulator Complex Signal Connection



For tuning VGA_CORE sequence.



Item	Location	QW16	N16	N17
1	PU8514	RT8812AGQW	74.08812.073	RT8816AGQW 074.08816.0A73
2	PR8511	20K	64.20025.6DL	6.19K 64.61915.6DL
3	PR8510	20K	64.20025.6DL	20.5K 64.20525.6DL
4	PR8512	2K	64.20015.6DL	4.32K 64.43215.6DL
5	PR8514	18K	64.18025.6DL	16.5K 64.16525.6DL
6	PR8561	0R	63.R0034.1DL	309R 64.30905.6DL
7	PC8519	2700p	78.27224.2FLDL	4700p 078.47222.02FD
8	PR8525	0R	63.R0034.1DL	DY
9	PR8526	0R	63.R0034.1DL	DY
10	PR8527	DY	63.R0034.1DL	OR 63.R0034.1DL
11	PR8576	DY	OR	OR 63.R0034.1DL
12	PR8577	DY	160K	64.16035.6DL
13	PR8508	15.4K	64.15425.6DL	DY
14	PR8504	348K	64.34835.6DL	499K 64.49935.6DL

SSID = PWR.Plane.Regulator_lp35v

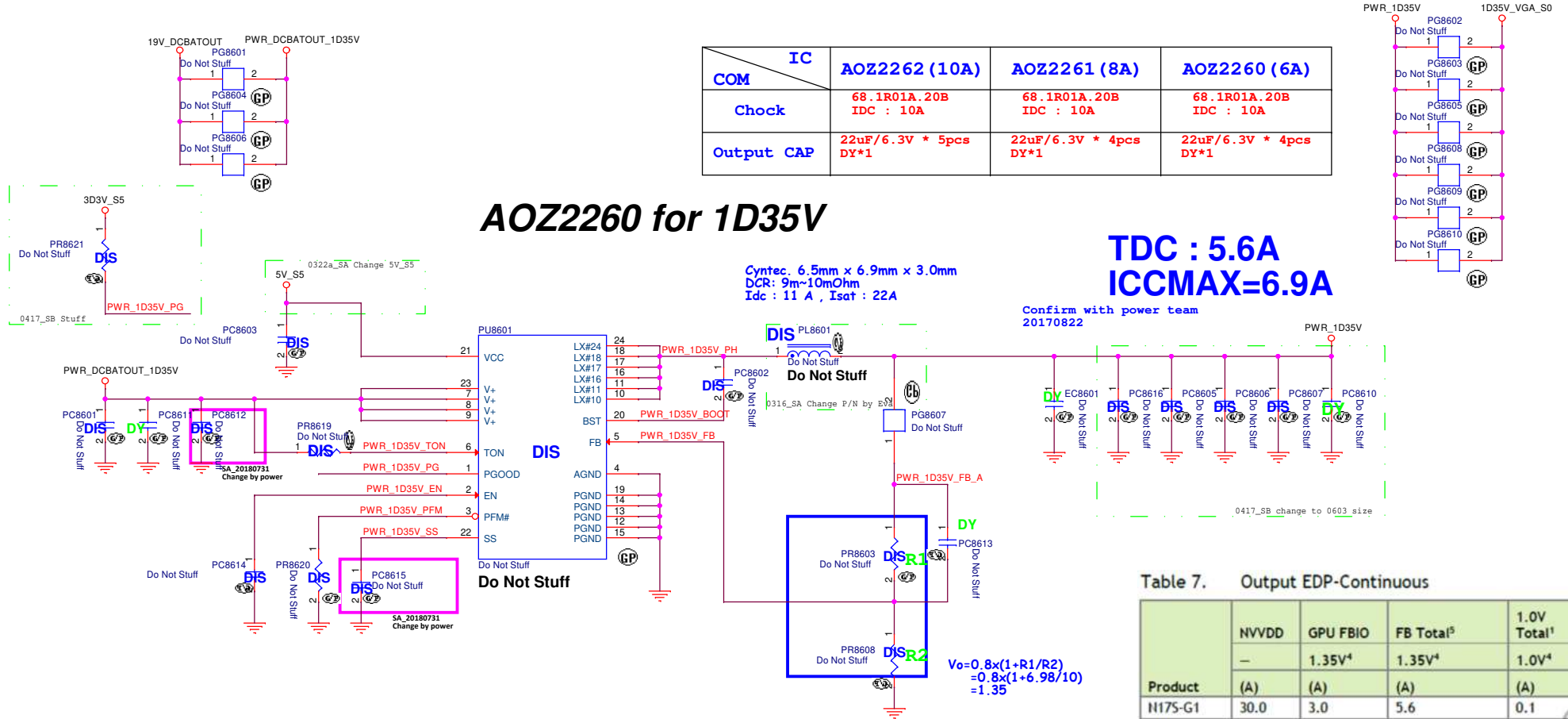
COM	IC	AOZ2262 (10A)	AOZ2261 (8A)	AOZ2260 (6A)
Check		68.1R01A.20B IDC : 10A	68.1R01A.20B IDC : 10A	68.1R01A.20B IDC : 10A
Output CAP		22uF/6.3V * 5pcs DY*1	22uF/6.3V * 4pcs DY*1	22uF/6.3V * 4pcs DY*1

AOZ2260 for 1D35V

Cyntec. 6.5mm x 6.9mm x 3.0mm
DCR: 9m~10mOhm
Idc : 11 A , Isat : 22A

TDC : 5.6A
ICCMAX=6.9A

Confirm with power team
20170822



OFFPAGE

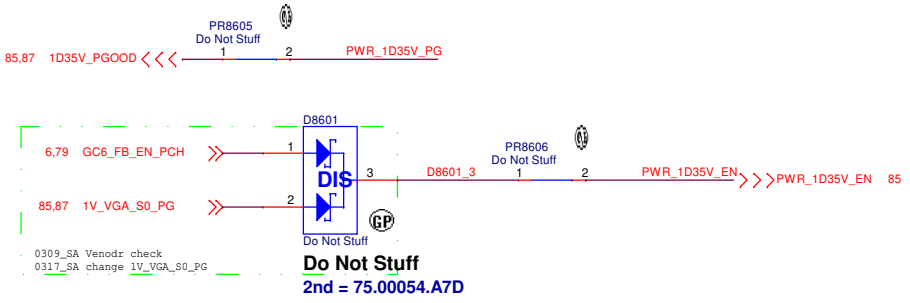


Table 7. Output EDP-Continuous

	NVDD	GPU FBIO	FB Total ²	1.0V Total ¹	1.8V Total ²
	—	1.35V ⁴	1.35V ⁴	1.0V ⁴	1.8V ⁴
Product	(A)	(A)	(A)	(A)	(A)
II175-G1	30.0	3.0	5.6	0.1	0.3
II175-LG	15.4	2.5	5.0	0.1	0.2

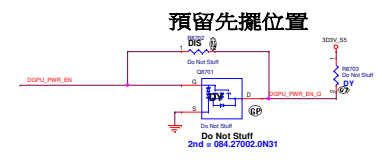
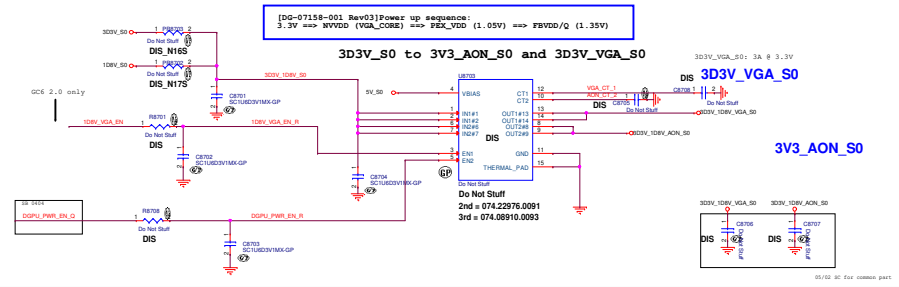
Table 8. Output EDP-Peak

	NVDD	GPU FBIO	FB TOTAL ⁴	1.0V Total ¹
	—	1.35V ³	1.35V ³	1.0V ³
Product	(A)	(A)	(A)	(A)
II175-G1	60.1	3.4	6.9	0.2
II175-LG	48.3	2.8	5.8	0.2

$$V_o = 0.8 \times \frac{1+R1/R2}{1+6.98/10} = 1.35$$

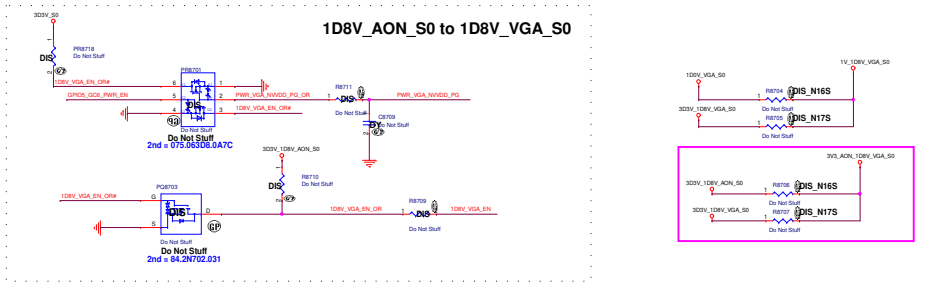
G5516 for 1.8V_AON_S0

- 79.85 GPDS_GDS_PWR_EN >>>
- 85 PWR_VGA_NVDD_PD >>>
- 85 DGPU_PWR_EN >>>
- 85 TV_VGA_EN_B <<<
- 85.86 TV_VGA_S0_PD <<<
- 85 1D8V_VGA_EN_OH <<<
- 85 DGPU_PWR_EN_L0 <<<

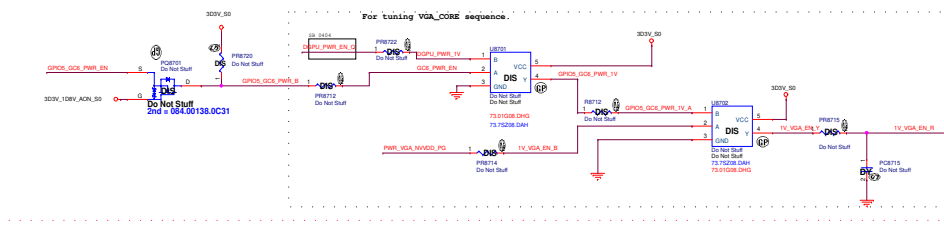


PARAMETER	MIN	MAX	UNITS
VIN1.2 Input voltage range	0.8	V _{BUS}	V
VBIAS Bias voltage range	2.5	5.5	V
EN1.2 ON voltage range	0	5.5	V
VOUT1.2 Output voltage range	---	VIN1.2	V
VIH High-level input voltage, EN1, EN2	1.2	5.5	V
VIL Low-level input voltage, EN1, EN2	---	0.5	V
CT1.2 Input Capacitor	1	---	µF

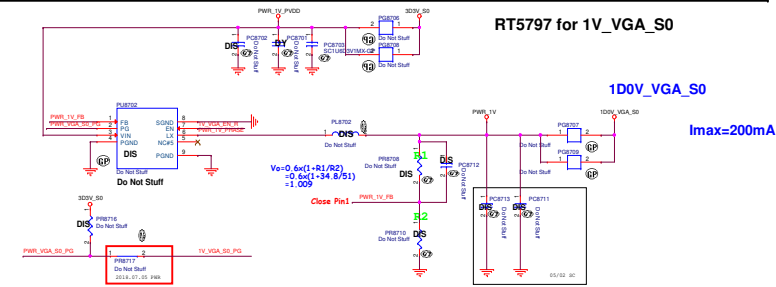
1D8V_AON_S0 to 1D8V_VGA_S0



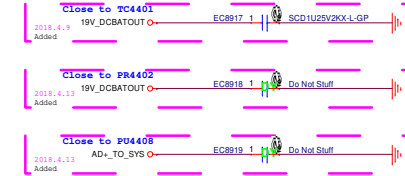
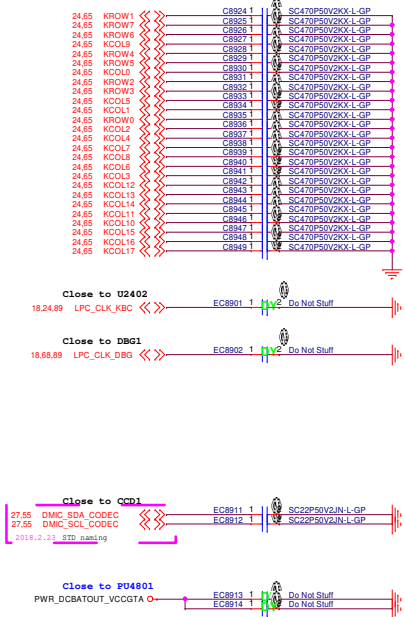
For tuning VGA_CORE sequence.



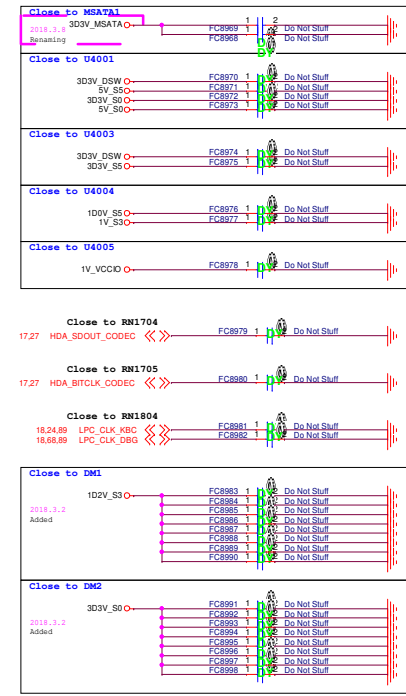
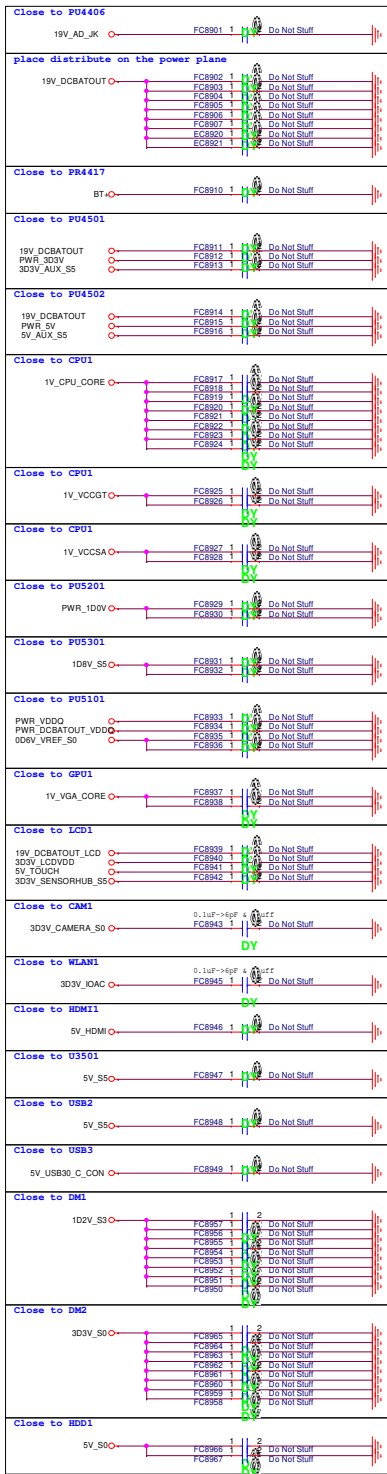
RT5797 for 1V_VGA_S0

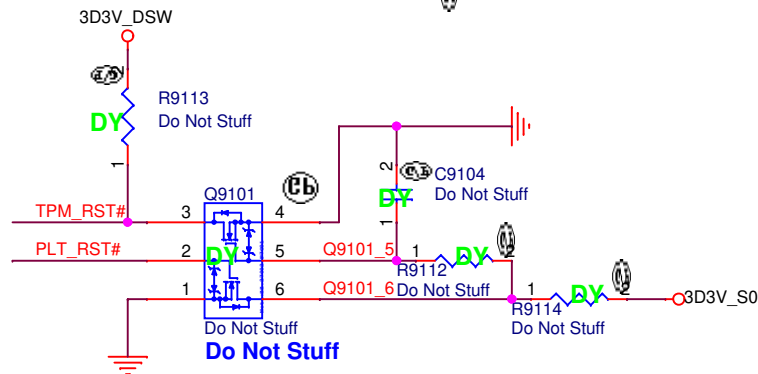
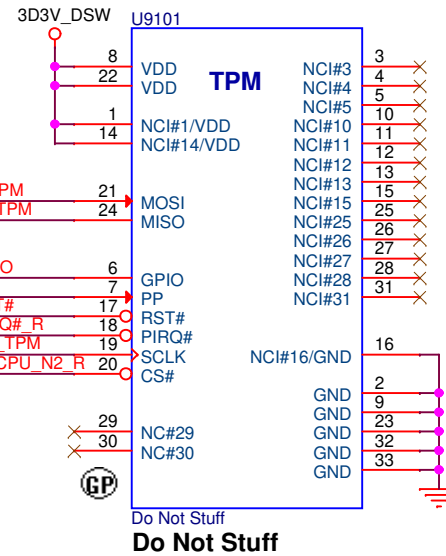
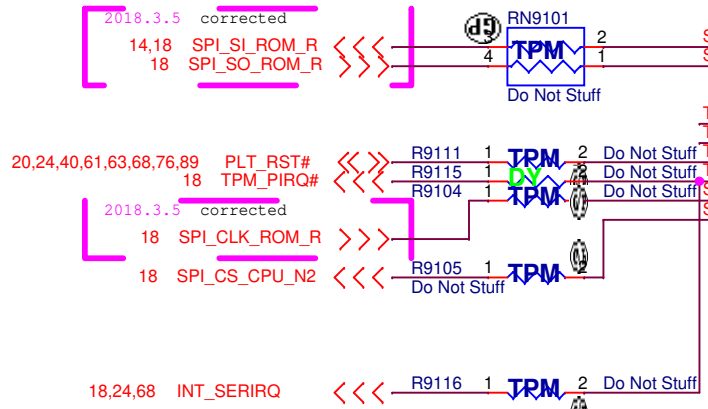
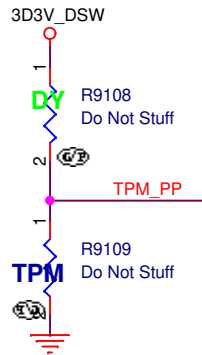
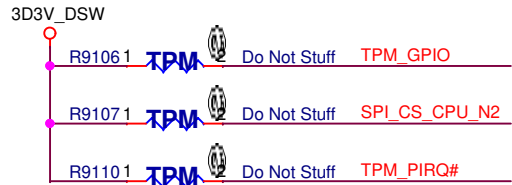
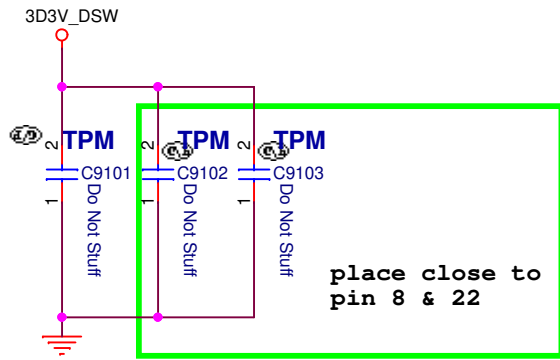


EMI



RF





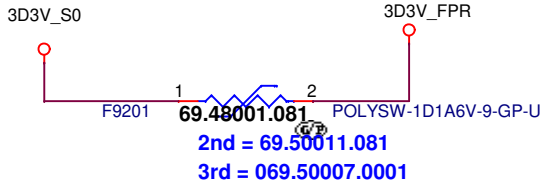
Wistron Confidential document, Anyone can not Duplicate, Modify, Forward or any other purpose application without get Wistron permission

UMA

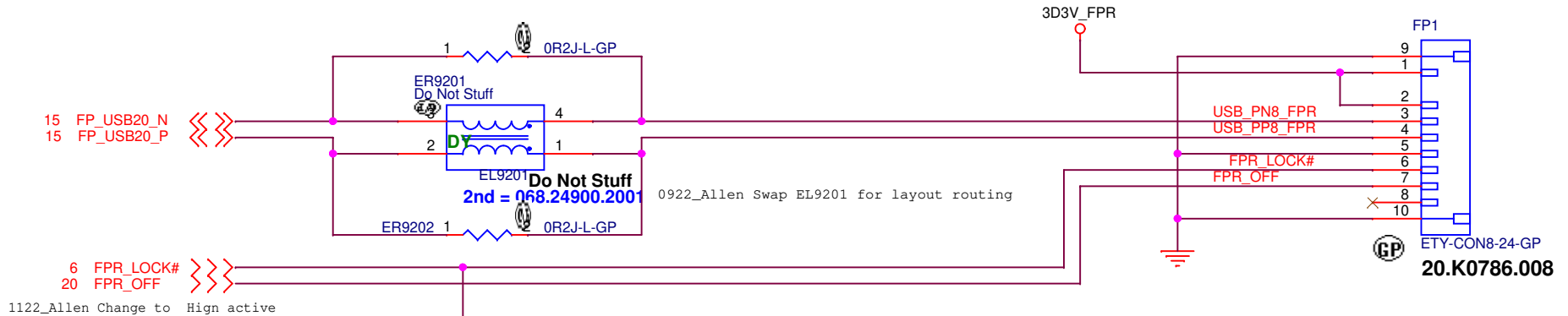
緯創資通 Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.

Title INT IO (TPM)

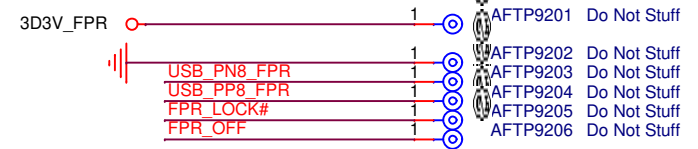
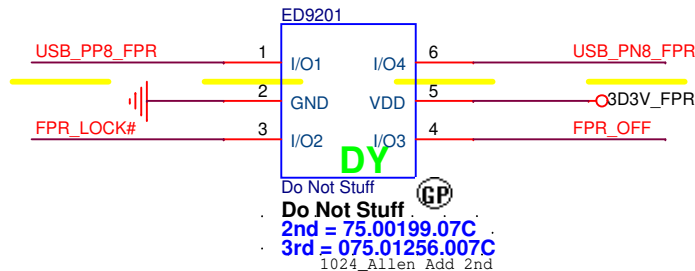
Size A4	Document Number	Rev SA
Date: Monday, August 06, 2018		Sheet 91 of 106
FAROE 14" Pavilion		



1109_Allen Add 2nd & 3rd



2018.7.19 Change net name



AFTP place close to FPR1

UMA

緯創資通 Wistron Corporation
 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
 Taipei Hsien 221, Taiwan, R.O.C.

Title INT IO (Finger Print)

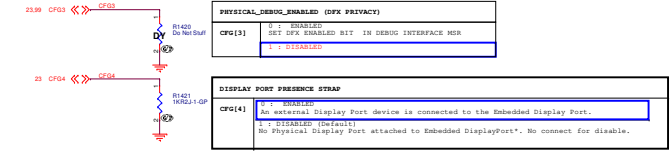
Size A4 Document Number FAROE 14" Pavilion Rev SA

Date: Monday, August 06, 2018 Sheet 92 of 106

PCH Strap Pin

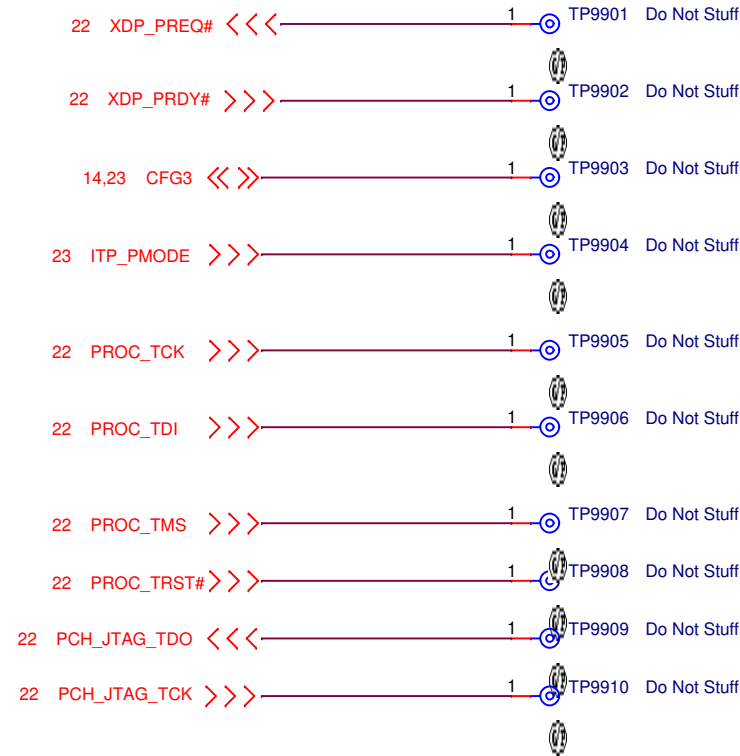
GPIO	GPP_C5/SML0ALERT#	SPIO_MOSI	GPP_E6	GPP_B23	SPIO_IO2	CNV_BRI_DT	GPP_F6 / CNV_RGI_DT	GPP_D12 / ISH_SPI_M0 SI / GSP12 MOSI
Schematic								
Description	This strap should sample HIGM. External pull-up is required. Recommended 100K if pulled up to 3.3V or 75K if pulled up to 1.8V.	This strap should sample HIGM. External pull-up is required. Recommended 100K if pulled up to 3.3V or 75K if pulled up to 1.8V.	This strap should sample HIGM. External pull-up is required. Recommended 100K if pulled up to 3.3V or 75K if pulled up to 1.8V.	Internal DCI-00B	This strap should sample HIGM. External pull-up is required. Recommended 100K if pulled up to 3.3V or 75K if pulled up to 1.8V.	XTAL Frequency Selection	An external pull-up or pull-down is required.	This strap should sample HIGM. External pull-up is required. Recommended 100K if pulled up to 3.3V or 75K if pulled up to 1.8V.
High	eSPI	Disable =default=	Reserved	Enable IntelR DCI-00B	DISABLED =default=	24M	INTEGRATED CNVI DISABLE	3.3V
Low	LPC =default=	Enable	Reserved	Disable IntelR DCI-00B =default=	ENABLED	38.4 MHz =default=	INTEGRATED CNVI ENABLE	1.8V
GPIO	GPP_B18/GSP10_MOSI	HDA_SDO / I2S0_TXD	TBT_LSX #0	TBT_LSX #1	TBT_LSX #2	GPD7	SPIO_IO3	GPP_C2
Schematic								
Description	0 = Disable "No Reboot" mode. 1 = Enable "No Reboot" mode.	Flash Descriptor Security Override	DDP1 I2C/TBT LSX #0 / BSSB-LS #0 pins VCC configuration	DDP2 I2C/TBT LSX #1 / BSSB-LS #1 pins VCC configuration	DDP3 I2C/TBT LSX #2/BSSB-LS #2 pins VCC configuration	This strap should sample HIGM. External pull-up is required. Recommended 100K.	This strap should sample HIGM. External pull-up is required. Recommended 100K if pulled up to 3.3V or 75K if pulled up to 1.8V.	Intel ME Crypto Transport Layer Security (TLS) cipher suite (no confidentiality). (Default)
High	No Reboot	Disable	3.3V	3.3V	3.3V	XTAL IS ATTACHED	DISABLED =default=	Enable
Low	Reboot =default=	Enable =default=	1.8V	1.8V	1.8V	XTAL INPUT IS SINGLE ENDED	Enable	Disable =default=
GPIO	GPP_H2	ITP_PMODE	GPP_H21	GPP_H23				
Schematic								
Description	eSPI Flash Sharing Mode	Reserved	An external pull-up is required on this strap since 38.4 MHz XTAL is not supported on the PCB.	This strap must be configured to '0' (SAFS is disabled) if the eSPI or I2C strap is configured to '0' (eSPI is disabled).				
High	1 = Slave Attached Flash Sharing (SAFS) is enabled.	DFXTESTMODE DISABLED =default=	24MHZ	SAF ENABLE				
Low	0 = Master Attached Flash Sharing (MAFS) is enabled. (Default)	DFXTESTMODE ENABLED	38.4/19.2MHZ =default=	MAF ENABLE =default=				

CPU Strap Pin

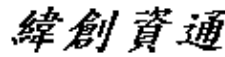


Enable Intel ME Crypto Transport Layer Security (TLS) cipher suite (with confidentiality). Must be pulled up to support Intel AMT with TLS.

Disable Intel ME Crypto Transport Layer Security (TLS) cipher suite (no confidentiality). (Default)

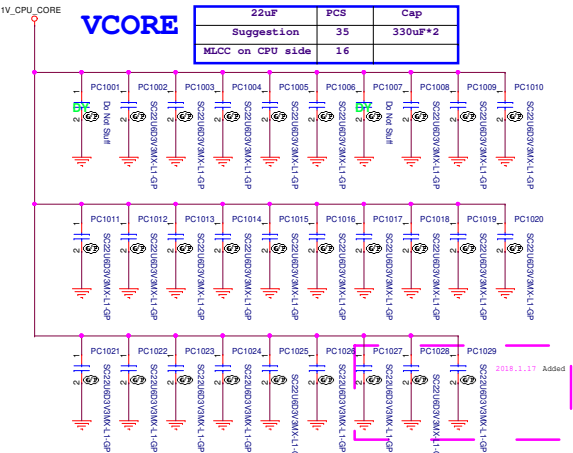


UMA

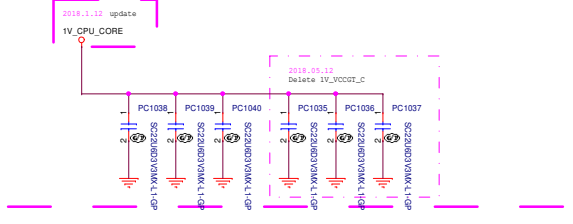
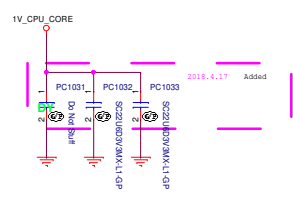
 Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Debug (HDT debug)	
Size A4	Document Number FAROE 14" Pavilion
Date: Monday, August 06, 2018	Rev SA
Sheet 99 of 106	

Main Func = CPU

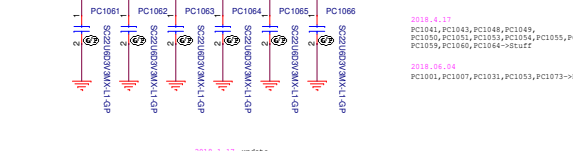
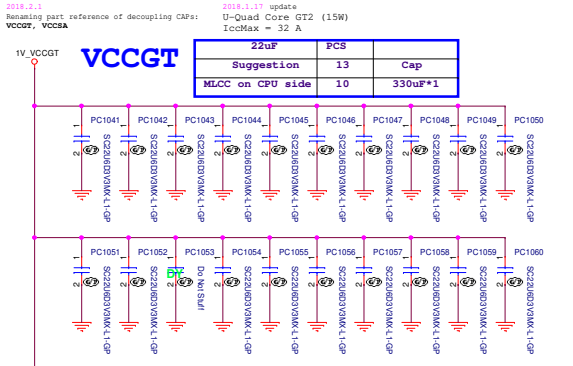
2018.1.17 update
U-Quad Core GT2 (15W)
Imax = 70A



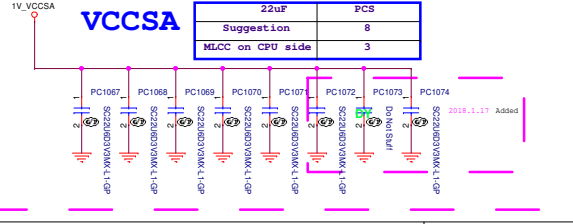
22uF	PCS	Cap
Suggestion	35	330uF*2
MLCC on CPU side	16	



22uF	PCS	Cap
Suggestion	13	330uF*1
MLCC on CPU side	10	



2018.1.17 update
U-Quad Core GT2 (15W)
IccMax = 6A



22uF	PCS	Cap
Suggestion	8	
MLCC on CPU side	3	

2018.1.12 updated
#575412 PDG rev.0.7

Table 11-2. Decoupling Requirements for Whiskey Lake U 4+2 Processor (Sheet 1 of 2)

Domain	Primary Side cap	Secondary Side cap	Placement guideline
VCCORE		42x 1uF 0402/0201	To be placed as close as possible to the vias that connect to the BGA pins.
		14x 10uF 0402	
		9x 22uF 0603	Place as close to the package as possible
		8x 10uF 0402	
		18x 47uF 0805 (6.3V)	Place as close to the package as possible. Can be placed on as either Primary or back side cap.

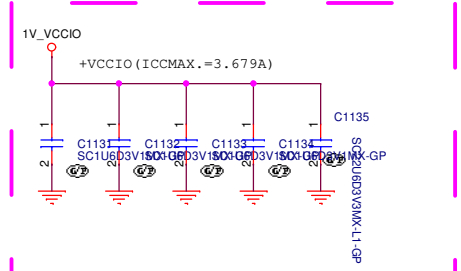
Table 11-2. Decoupling Requirements for Whiskey Lake U 4+2 Processor (Sheet 2 of 2)

Domain	Primary Side cap	Secondary Side cap	Placement guideline
VCCGT	15x 22uF 0603		Place underneath the package
	4x 47uF 0805 (6.3V)		
		11x 1uF 0402/0201	Place as close to the package as possible
VCCSA		15x 10uF 0402	Placeholder only.
		4x 0402	
		7x 10uF 0402	
VDDQ		4x 1uF 0402/0201	Place as close to the package as possible.
		3x 10uF 0402	
		1x 22uF 0603	
		6x 10uF 0402	
VCCIO	4x 1uF 0201		Place underneath the package
		6x 10uF 0402	Place as close to the package as possible
		4x 0402	Placeholder Only
VCCPLL_OC	1x 1uF 0402		Do not merge VccPLL, VccPLL_OC and VccST to any noisy and high current power rail and do not route them close/ adjacent to and reference to, any noisy and high current rail on top and bottom layers - as this may impact to PLL failing to phase lock.
VCCPLL	1x 0.1uF 0201		Place as close as possible to BGA.
		1x 1uF 0402	Place as close as possible to BGA and can be placed on as either Primary or backside cap.
		1x 0805	Placeholder Only. Can be placed on as either Primary or back side cap.
VCCST	1x 1uF 0402		
VCCSTG	1x 1uF 0402		

- Notes:**
- The 6.3V voltage is for the higher capacitance retention; more 0805 components will be required for a lower voltage capacitor rating. Assumption: VR loop bandwidth ' 250kHz e.g., 1MHz switching VR
 - Component placement order: Package edge > 0402 caps > 0603 caps > 0805 caps > Bulk caps > Power source.

Main Func = CPU

VCCIO

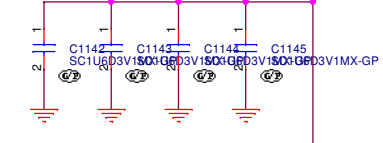
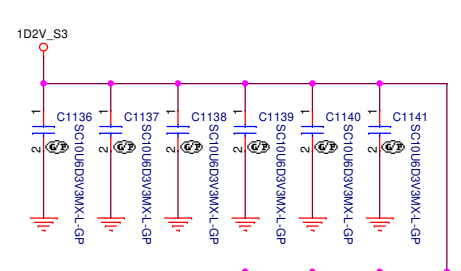


2018.2.1
Renaming part reference of decoupling CAPs:
VCCIO, VDDQ, VecST, VecSG, VecPLL_OC, VCCPLL

Place as close to the CPU as possible

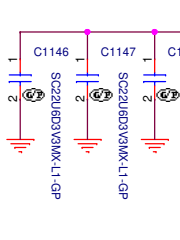
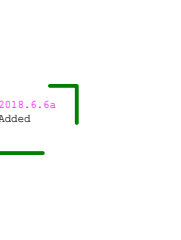
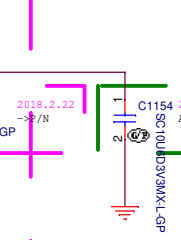
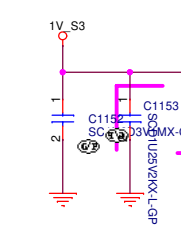
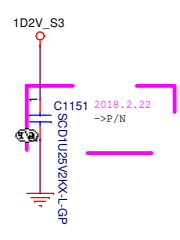
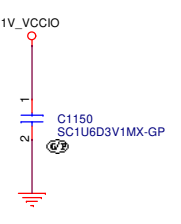
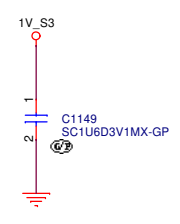
VDDQ

U-Quad Core GT2 (15W)
Imax = 3.3A



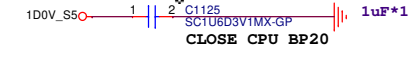
2018.1.12 update

VccST IccMax = 0.06A
VccSTG IccMax = 0.02 A
VccPLL_OC IccMax = 0.12 A
VCCPLL IccMax = 0.13 A



CLOSE CPU BP11, BP2 CLOSE CPU BG1, BG2 CLOSE CPU BL27, BM26 CLOSE CPU BR11, BT11

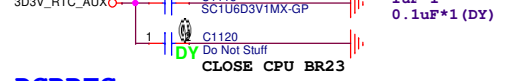
VCCPRIM_1P05



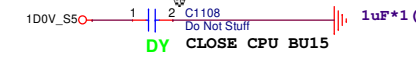
VCCDPHY_1P24



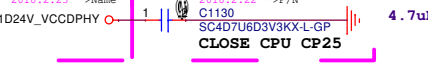
VCCRTC



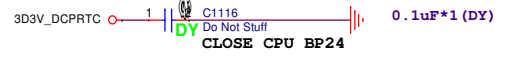
VCCPRIM_CORE



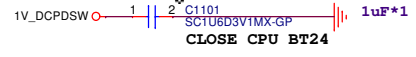
VCCDPHY_EC_1P24



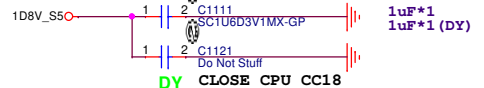
DCPRTC



VCCDSW_1P05



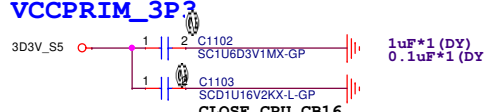
VCCPRIM_1P8



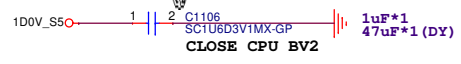
VCCPRIM_MPHY_1P05



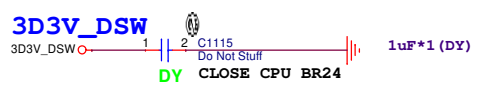
VCCPRIM_3P3



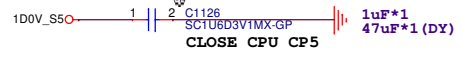
VCCAMPHYPLL_1P05



3D3V_DSW



VCCA_XTAL_1P05



VCCHDA



UMA

Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
CPU (Power CAP2)	
Title Size A3 Date: Monday, August 06, 2018	Document Number FAROE 14" Pavilion Sheet 11 of 106
Rev SA	Rev SA

